



MachXO5-NX High-Speed I/O Interface

Technical Note

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Contents

Contents	3
Abbreviations in This Document.....	10
1. Introduction	11
2. External Interface Description	12
3. High-Speed I/O Interface Building Blocks	13
3.1. SGMII Clock Data Recovery (CDR)	15
3.2. I/O Banks	16
3.3. Clock Scheme	18
3.3.1. Primary Clocks	18
3.3.2. Edge Clocks	18
3.4. DQS Lane	18
3.5. PLL	18
3.6. DDRDLL.....	19
3.7. DLLDEL.....	19
3.8. DQSBUF	20
3.9. Input DDR (IDDR).....	20
3.10. Output DDR (ODDR)	20
3.11. Edge Clock Dividers (CLKDIV)	20
3.12. Input/Output DELAY.....	21
4. Building Generic High-Speed Interfaces	22
4.1. Types of High-Speed I/O Interfaces.....	22
5. High-Speed DDR Interface Details	24
5.1. GDDR1_RX.SCLK.Centered	24
5.2. GDDR1_RX.SCLK.Aligned	25
5.3. GDDR2_RX.ECLK.Centered	27
5.4. GDDR2_RX.ECLK.Aligned	28
5.5. GDDR4_RX.ECLK.Centered	30
5.6. GDDR4_RX.ECLK.Aligned	31
5.7. GDDR5_RX.ECLK.Centered	33
5.8. GDDR5_RX.ECLK.Aligned	34
5.9. GDDR71_RX.ECLK	36
5.10. Soft MIPI D-PHY Receive Interfaces	37
5.10.1. Implementation Details	38
5.11. GDDR1_TX.SCLK.Aligned	40
5.12. GDDR1_TX.SCLK.Centered	41
5.13. GDDR2_TX.ECLK.Aligned	42
5.14. GDDR2_TX.ECLK.Centered	43
5.15. GDDR4_TX.ECLK.Aligned	44
5.16. GDDR4_TX.ECLK.Centered	45
5.17. GDDR5_TX.ECLK.Aligned	46
5.18. GDDR5_TX.ECLK.Centered	47
5.19. GDDR71_TX.ECLK	48
5.20. Soft MIPI D-PHY Transmit Interfaces.....	49
5.20.1. Implementation Details	49
5.21. MachXO5-NX Generic DDR Design Guidelines	51
5.21.1. Receive Interface Guidelines	51
5.21.2. Transmit Interface Guidelines.....	51
5.21.3. Clocking Guidelines for Generic DDR Interface	52
6. MachXO5-NX Memory Interfaces.....	53
6.1. DDR Memory Interface Requirements.....	56
6.2. Features for Memory Interface Implementation.....	56
6.2.1. DQS Grouping	56

6.2.2.	DLL-Compensated DQS Delay Elements	57
6.2.3.	Data Valid Module	58
6.2.4.	READ Pulse Positioning Optimization	58
6.2.5.	Dynamic Margin Control on DQSBUF	60
6.2.6.	Read Data Clock Domain Transfer Using Input FIFO.....	60
6.2.7.	DDR Input and Output Registers (IDDR/ODDR)	61
6.3.	Memory Interface Implementation	61
6.3.1.	Read Implementation	61
6.3.2.	Write Implementation (DQ, DQS, and DM)	63
6.3.3.	Write Implementation (DDR3/DDR3L Address, Command, and Clock).....	65
6.3.4.	Write Implementation (LPDDR4 Address, Command, and Clock)	66
6.4.	DDR Memory Interface Design Rules and Guidelines	67
6.5.	DDR3 Memory Interface Termination Guidelines.....	68
6.5.1.	Termination for DQ, DQS, and DM	68
6.5.2.	Termination for CK.....	68
6.5.3.	Termination for Address, Commands, and Controls.....	68
6.5.4.	Termination for DDR3/DDR3L DIMM.....	69
6.6.	DDR Memory Interface Pinout Guidelines	69
6.7.	Pin Placement Considerations for Improved Noise Immunity	70
7.	Using IP Catalog to Build and Plan High-Speed DDR Interfaces.....	71
7.1.	Configuring DDR Modules in IP Catalog	71
7.2.	Configuring SDR Modules.....	72
7.3.	Configuring DDR Generic Modules.....	75
7.4.	Configuring 7:1 LVDS Interface Modules.....	79
7.5.	Configuring DDR Memory Interfaces	81
7.6.	Configuring MIPI D-PHY Modules.....	86
8.	I/O Logic (DDR) User Primitives and Attributes	88
8.1.	Input/Output DELAY	88
8.2.	DELAYA	89
8.3.	DELAYB	90
8.4.	DELAY Attribute Description	90
8.5.	DDRDLL (Master DLL)	91
8.5.1.	DDRDLLA	91
8.6.	DLL Delay (DLLDEL).....	92
8.7.	Input DDR Primitives	93
8.7.1.	IDDRX1	93
8.7.2.	IDDRX2	93
8.7.3.	IDDRX4	94
8.7.4.	IDDRX5	95
8.7.5.	IDDR71	96
8.8.	Output DDR Primitives	97
8.8.1.	ODDRX1.....	97
8.8.2.	ODDRX2.....	97
8.8.3.	ODDRX4.....	98
8.8.4.	ODDRX5.....	99
8.8.5.	ODDR71.....	100
8.8.6.	DQSBUF (DQS Strobe Control Block).....	100
8.9.	IDDR/ODDR Modules for Memory DDR Implementation	101
8.9.1.	Primitive Symbols.....	101
8.9.2.	IDDRX2DQ.....	101
8.9.3.	IDDRX4DQ.....	102
8.9.4.	ODDRX2DQ	103
8.9.5.	ODDRX4DQ	104
8.10.	Memory Output DDR Primitives for DQS Output.....	105

8.10.1. ODDR2DQS	105
8.10.2. ODDR4DQS	106
8.11. Memory Output DDR Primitives for Tristate Output Control	107
8.11.1. TSHX2DQ.....	107
8.11.2. TSHX4DQ.....	108
8.11.3. TSHX2DQS.....	109
8.11.4. TSHX4DQS.....	110
8.12. Memory Output DDR Primitives for Address and Command.....	111
8.12.1. OSHX2	111
8.12.2. OSHX4	112
8.13. LPDDR4 Output Delay Primitives	113
8.13.1. OUTDELAYA	113
9. Soft IP Modules.....	114
9.1. Detailed Description of Each Soft IP.....	114
9.1.1. GDDR_SYNC	114
9.1.2. RX_SYNC	115
9.1.3. MEM_SYNC.....	116
9.1.4. BW_ALIGN	117
9.1.5. MIPI_FILTER	118
References.....	119
Technical Support Assistance	120
Revision History	121

Figures

Figure 2.1. External Interface Definitions	12
Figure 3.1. LFMXO5-15D/20TD/20TDQ/25/30TD/30TDQ/35T/65T Clocking Diagram.....	13
Figure 3.2. LFMXO5-55T/55TD/55TDQ/100T Clocking Diagram.....	14
Figure 3.3. MachXO5-NX SGMII CDR IP	15
Figure 3.4. DLLDEL and Code Control	19
Figure 3.5. DDR Delay Block Diagram	19
Figure 3.6. PIC Delay Cell Diagram	21
Figure 5.1. GDDR1_RX.SCLK.Centered Interface (Static Delay)	24
Figure 5.2. GDDR1_RX.SCLK.Centered Interface (Dynamic Data delay)	24
Figure 5.3. GDDR1_RX.SCLK.Aligned Interface (Static Delay)	25
Figure 5.4. GDDR1_RX.SCLK.Aligned Interface (Dynamic Data/Clock Delay)	26
Figure 5.5. GDDR2_RX.ECLK.Centered Interface (Static Delay)	27
Figure 5.6. GDDR2_RX.ECLK.Centered Interface (Dynamic Data Delay).....	27
Figure 5.7. GDDR2_RX.ECLK.Aligned Interface (Static Delay)	28
Figure 5.8. GDDR2_RX.ECLK.Aligned Interface (Dynamic Data/Clock Delay)	29
Figure 5.9. GDDR4_RX.ECLK.Centered Interface (Static Delay)	30
Figure 5.10. GDDR4_RX.ECLK.Centered Interface (Dynamic Data Delay).....	30
Figure 5.11. GDDR4_RX.ECLK.Aligned Interface (Static Delay)	31
Figure 5.12. GDDR4_RX.ECLK.Aligned Interface (Dynamic Data/Clock Delay)	32
Figure 5.13. GDDR5_RX.ECLK.Centered Interface (Static Delay)	33
Figure 5.14. GDDR5_RX.ECLK.Centered Interface (Dynamic Data Delay).....	33
Figure 5.15. GDDR5_RX.ECLK.Aligned Interface (Static Delay)	34
Figure 5.16. GDDR5_RX.ECLK.Aligned Interface (Dynamic Data/Clock Delay)	35
Figure 5.17. GDDR71_RX.ECLK Interface	36
Figure 5.18. MIPI D-PHY RX Block Diagram.....	38
Figure 5.19. MIPI D-PHY RX Interface Diagram.....	39
Figure 5.20. GDDR1_TX.SCLK.Aligned Interface	40
Figure 5.21. GDDR1_TX.SCLK.Centered Interface.....	41
Figure 5.22. GDDR2_TX.ECLK.Aligned Interface	42
Figure 5.23. GDDR2_TX.ECLK.Centered Interface	43
Figure 5.24. GDDR4_TX.ECLK.Aligned Interface	44
Figure 5.25. GDDR4_TX.ECLK.Aligned Interface	45
Figure 5.26. GDDR5_TX.ECLK.Aligned Interface	46
Figure 5.27. GDDR5_TX.ECLK.Aligned Interface	47
Figure 5.28. GDDR71_TX.ECLK Interface	48
Figure 5.29. MIPI D-PHY TX Block Diagram.....	49
Figure 5.30. MIPI D-PHY TX Interface Diagram	50
Figure 6.1. Typical DDR3/DDR3L Memory Interface.....	53
Figure 6.2. Typical LPDDR4 Memory Interface	54
Figure 6.3. DQ-DQS During Read	54
Figure 6.4. DQ-DQS During Write	55
Figure 6.5. DQ-DQS Grouping	57
Figure 6.6. DQSBUF Block Functions.....	58
Figure 6.7. READ Signal Training Process.....	60
Figure 6.8. DDR3/DDR3L and LPDDR4 Read Side Implementation.....	61
Figure 6.9. DDR3/DDR3L Write Side (DQ, DQS, and DM)	63
Figure 6.10. LPDDR4 Write Side (DQ,DQS, and DM).....	64
Figure 6.11. DDR3/DDR3L Address, Command, and Clock Generation	65
Figure 6.12. LPDDR4 Output for CA Generation	66
Figure 6.13. LPDDR4 Output for CSN, CKE, and CLOCK Generation	67
Figure 7.1. IP Catalog Main Window.....	71
Figure 7.2. SDR Option Selected in the IP Catalog Tab	72

Figure 7.3. SDR Configuration Tab	73
Figure 7.4. DDR_Generic Option Selected in the IP Catalog Tab	75
Figure 7.5. DDR_Generic Configuration Tab	76
Figure 7.6. GDDR_7:1 Option Selected in the IP Catalog Tab	79
Figure 7.7. GDDR_7:1 LVDS Configuration Tab	80
Figure 7.8. DDR_MEM Option Selected in the IP Catalog Tab	81
Figure 7.9. DDR_MEM Configuration	82
Figure 7.10. DDR_MEM Clock/Address/Command Tab	84
Figure 7.11. DDR_MEM Advanced Settings Tab	85
Figure 7.12. MIPI_DPHY Option Selected in the IP Catalog Tab	86
Figure 7.13. MIPI_DPHY Configuration Settings Tab	87
Figure 8.1. DELAYA Primitive	89
Figure 8.2. DELAYB Primitive	90
Figure 8.3. DDRDLLA Primitive	91
Figure 8.4. DLLDELD Primitive	92
Figure 8.5. IDDRX1 Primitive	93
Figure 8.6. IDDRX2 Primitive	93
Figure 8.7. IDDRX4 Primitive	94
Figure 8.8. IDDRX5 Primitive	95
Figure 8.9. IDDR71	96
Figure 8.10. ODDRX1	97
Figure 8.11. ODDRX2	97
Figure 8.12. ODDRX4 Primitive	98
Figure 8.13. ODDRX5 Primitive	99
Figure 8.14. ODDR71 Primitive	100
Figure 8.15. IDDRX2DQ Primitive	101
Figure 8.16. IDDRX4DQ Primitive	102
Figure 8.17. ODDRX2DQ	103
Figure 8.18. ODDRX4DQ Primitive	104
Figure 8.19. ODDRX2DQS Primitive	105
Figure 8.20. ODDRX4DQS Primitive	106
Figure 8.21. TSHX2DQ Primitive	107
Figure 8.22. TSHX4DQ Primitive	108
Figure 8.23. TSHX2DQS Primitive	109
Figure 8.24. TSHX4DQS Primitive	110
Figure 8.25. OSHX2 Primitive	111
Figure 8.26. OSHX4 Primitive	112
Figure 8.27. OUTDELAYA Primitive	113
Figure 9.1. GDDR_SYNC Ports	114
Figure 9.2. RX_SYNC Ports	115
Figure 9.3. MEM_SYNC Ports	116
Figure 9.4. BW_ALIGN Ports	117
Figure 9.5. MIPI_FILTER Ports	118

Tables

Table 3.1. LFMXO5-15D/25 I/O Banks	16
Table 3.2. LFMXO5-55T/55TD/55TDQ/100T I/O Banks	16
Table 3.3. LFMXO5-20TD/20TDQ/30TD/30TDQ/35T/65T I/O Banks.....	17
Table 4.1. Generic High-Speed I/O Interfaces.....	22
Table 5.1. MIPI D-PHY Module Signal Descriptions	37
Table 6.1. DDR Memory Configurations Support	55
Table 6.2. DDRDLL Connectivity.....	57
Table 6.3. DDRDLL Connectivity.....	59
Table 6.4. I/O Standards for DDR Memory	68
Table 7.1. EBR-Based Single-Port Memory Port Definitions	74
Table 7.2. DDR_Generic Configuration Tab Parameters.....	77
Table 7.3. IP Catalog DDR_Generic Interface Selection	78
Table 7.4. GDDR_7:1 LVDS Configuration Parameters	80
Table 7.5. DDR_MEM General Tab Parameters.....	83
Table 7.6. DDR_MEM Clock/Address/Command Parameters	84
Table 7.7. DDR_MEM Advanced Settings Tab Parameters	85
Table 7.8. Configuration Options for MIPI D-PHY Interface	87
Table 8.1. Software Primitives	88
Table 8.2. DELAYA Port List	89
Table 8.3. DELAYB Port List	90
Table 8.4. DELAYA and DELAYB Attributes	90
Table 8.5. DDRDLLA Port List	91
Table 8.6. DDRDLL Attributes	91
Table 8.7. DLLDELD Port List	92
Table 8.8. DLLDELD Attributes	92
Table 8.9. IDDRX1 Port List	93
Table 8.10. IDDRX2 Port List	93
Table 8.11. IDDRX4 Port List	94
Table 8.12. IDDRX5 Port List	95
Table 8.13. IDDR71 Port List	96
Table 8.14. ODDRX1F Port List.....	97
Table 8.15. ODDRX2 Port List.....	98
Table 8.16. ODDRX4 Port List.....	98
Table 8.17. ODDRX5 Port List.....	99
Table 8.18. ODDR71 Port List.....	100
Table 8.19. Summary of all DDR Memory Primitives.....	101
Table 8.20. IDDRX2DQ Port List	101
Table 8.21. IDDRX4DQ Port List	102
Table 8.22. ODDRX2DQ Port List	103
Table 8.23. ODDRX4DQ Port List	104
Table 8.24. ODDRX2DQS Port List.....	105
Table 8.25. ODDRX4DQS Port List.....	106
Table 8.26. TSHX2DQ Port List	107
Table 8.27. TSHX4DQ Port List	108
Table 8.28. TSHX2DQS Port List	109
Table 8.29. TSHX4DQS Port List	110
Table 8.30. OSHX2 Port List	111
Table 8.31. OSHX4 Port List	112
Table 8.32. OUTDELAYA Parameter	113
Table 8.33. OUTDELAYA Port List.....	113
Table 9.1. List of Soft IPs Supported	114
Table 9.2. Soft IP Used in Each Interface	114

Table 9.3. GDDR_SYNC Ports Description.....	115
Table 9.4. GDDR_SYNC Ports Description.....	115
Table 9.5. MEM_SYNC Port Description	116
Table 9.6. BW_ALIGN Port Description.....	117
Table 9.7. MIPI_FILTER Port Description	118

Abbreviations in This Document

A list of abbreviations used in this document.

Abbreviation	Definition
CA	Command and Address
CLKDIV	Edge Clock Dividers
DDR	Double Data Rate
DLL	Delay-Locked Loops
DM	Data Mask
DSP	Digital Signal Processing
IDDR	Input DDR
ECLK	Edge Clock
HP	High Performance
LLC	Lower Left Corner
LRC	Lower Right Corner
ODDR	Output DDR
ODT	On-Die Termination
PCB	Printed Circuit Board
PCLK	Primary Clock
PLC	Programmable Logic Cell
PIC	Programmable I/O Cell
PIO	Programmable I/O
RX	Receiver
SCLK	System Clock
SDR	Single Data Rate
SSN	Simultaneous Switching Noise
TX	Transmitter
WR	Wide Range

1. Introduction

Lattice Semiconductor MachXO5™-NX devices support high-speed I/O interfaces, including Double Data Rate (DDR) and Single Data Rate (SDR) interfaces, using the logic built into the Programmable I/O (PIO). SDR applications capture data on one edge of a clock while DDR interfaces capture data on both the rising and falling edges of the clock, thus doubling the performance. MachXO5-NX device I/O also has dedicated circuitry that is used along with the DDR I/O to support DDR3, DDR3L, and LPDDR4 SDRAM memory interfaces.

This document discusses how to utilize the capabilities of the MachXO5-NX devices to implement high-speed Generic DDR interface and the DDR memory interfaces. Refer to the [MachXO5-NX Memory Interfaces](#) section of this document for more information.

2. External Interface Description

This technical note uses two types of external interface definitions, centered, and aligned.

- A centered external interface means that, at the device pins, the clock is centered in the data opening.
- An aligned external interface means that, at the device pins, the clock and data transition are aligned. This is sometimes called edge-on-edge.

Figure 2.1 shows the external interface waveform for SDR and DDR.

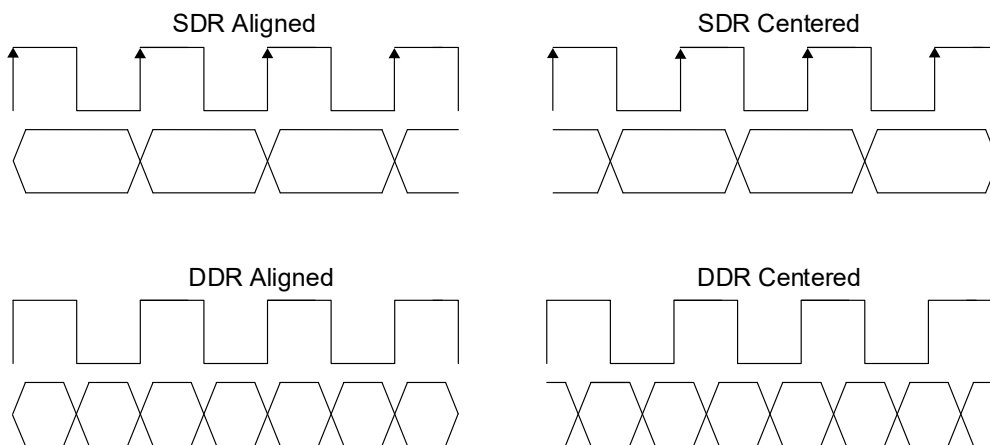


Figure 2.1. External Interface Definitions

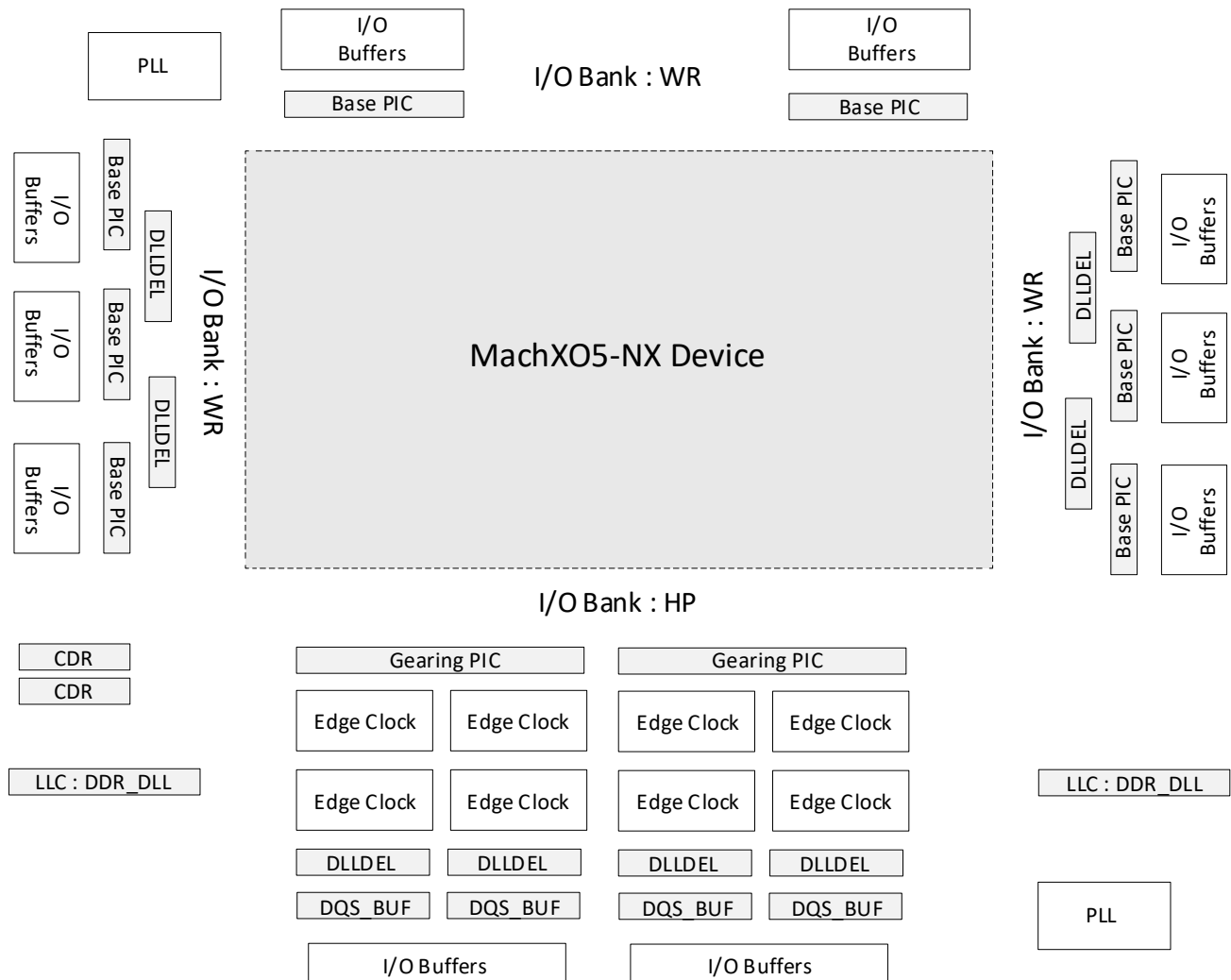
The interfaces described are referenced as centered or aligned interfaces.

- An aligned interface needs to adjust the clock location to satisfy the capture flip-flop setup and hold times.
- A centered interface needs to balance the clock and data delay to the first flip-flop to maintain the setup and hold already provided.

3. High-Speed I/O Interface Building Blocks

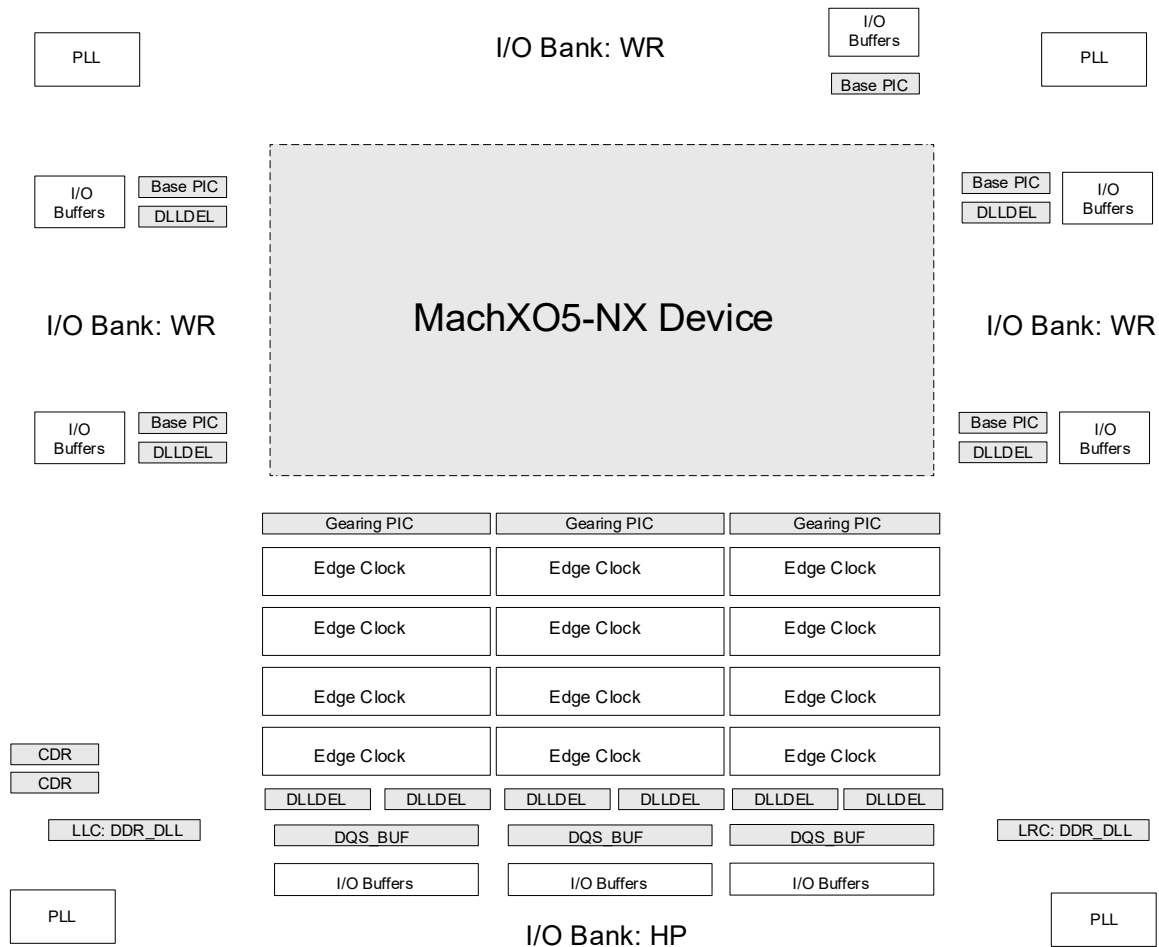
The MachXO5-NX devices contain dedicated functions for building high-speed interfaces. This section describes when and how to use these functions. A complete description of the library elements, including descriptions and attributes, is provided at the end of this document.

Figure 3.1 and Figure 3.2 show a high-level diagram of the clocking resources available in the MachXO5-NX devices for building high-speed I/O interfaces.



Note: This clocking diagram applies to LFMXO5-15D/25. LFMXO5-20TD/20TDQ/30TD/30TDQ/35T/65T devices have similar clocking structures but with 3 I/O banks on the bottom. For detailed specifications, refer to the *MachXO5-NX Family Data Sheet* (FPGA-DS-02102).

Figure 3.1. LFMXO5-15D/20TD/20TDQ/25/30TD/30TDQ/35T/65T Clocking Diagram



Note: This clocking diagram applies to LFMXO5-55T/100T. Other MachXO5-NX devices share a similar clocking diagram. However, the number of I/O banks and PLLs may vary. For detailed specifications, refer to the *MachXO5-NX Family Data Sheet (FPGA-DS-02102)*.

Figure 3.2. LFMXO5-55T/55TD/55TDQ/100T Clocking Diagram

In [Figure 3.1](#), the locations of the Base PIC, Gearing PIC, DDR_DLL, DLL_DEL, and DQS_BUF are provided. One DQS_BUF is provided per 12 I/O. One DLL_DEL is provided for each of the four Edge Clocks. Two DDR_DLLs are provided, one at the lower left corner and the other at the lower right corner. I/O bank WR uses Base PICs and bank HP uses Gearing PICs.

3.1. SGMII Clock Data Recovery (CDR)

The MachXO5-NX devices include two hardened Clock Data Recovery (CDR) components. The CDRs enable Serial Gigabit Media Independent Interface (SGMII) solutions. There are three main blocks in each CDR: the CDR, deserializer, and FIFO. Each CDR features two loops. The first loop is locked to the reference clock. Once locked, the loop switches to the data path loop where the CDR tracks the data signals to generate the correcting signals needed to achieve and maintain phase lock with the data. The data is then passed through a deserializer, which deserializes the data to 10-bit parallel data. The 10-bit parallel data is then sent to the FIFO bridge, which allows the CDR to interface with the rest of the FPGA. [Figure 3.3](#) shows a block diagram of the SGMII CDR IP.

As shown in [Figure 3.1](#), the two hardened blocks are located at the bottom left of the chip and use the high-speed I/O for the differential pair input. It is recommended that the reference clock be entered through a GPIO that is also connected to the PLL.

Note: The SGMII interface using LVDS I/O has limitations when operating across the full specified temperature range. Lattice recommends using alternative interfaces, such as SERDES or RGMII, for designs requiring a Gigabit Ethernet. Refer to the [Knowledge Database article](#) for details. Contact your local Lattice sales representative for more information.

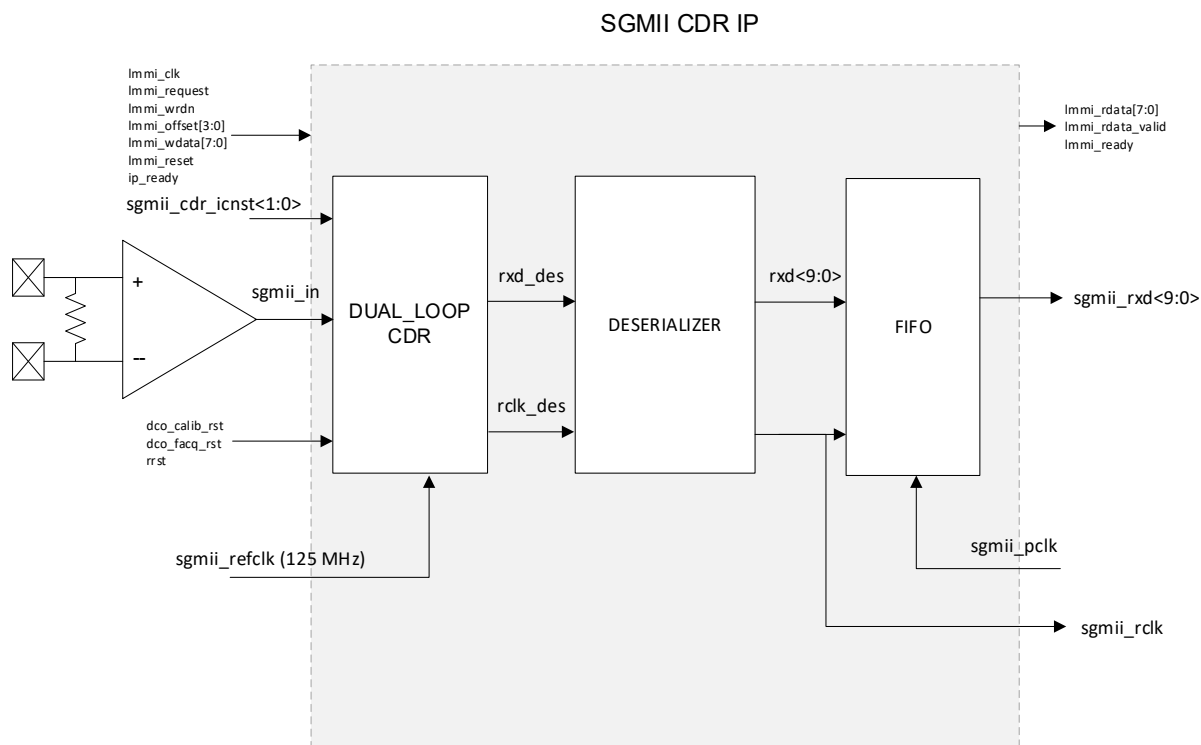


Figure 3.3. MachXO5-NX SGMII CDR IP

3.2. I/O Banks

There are 10 banks in the LFMXO5-15D and LFMXO5-25 devices, 8 banks in the LFMXO5-55T, LFMXO5-55TD, LFMXO5-55TDQ, and LFMXO5-100T devices, and 11 banks in the LFMXO5-20TD, LFMXO5-20TDQ, LFMXO5-30TD, LFMXO5-30TDQ, LFMXO5-35T, and LFMXO5-65T devices.

The banks are named in a clockwise direction starting from the top right. For visual reference, refer to [sysI/O User Guide for Nexus Platform \(FPGA TN-02067\)](#).

Table 3.1. LFMXO5-15D/25 I/O Banks

Bank ID	I/O Reference	Comments
BANK 0	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 1	3.3 V ²	WR ¹
BANK 2	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 3	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 4	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 5	1.8 V/1.5 V/1.2 V/1.0 V	HP
BANK 6	1.8 V/1.5 V/1.2 V/1.0 V	HP
BANK 7	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 8	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 9	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹

Notes:

1. WR can be used as an emulated differential output port.
2. Supports only 3.3 V.

Table 3.2. LFMXO5-55T/55TD/55TDQ/100T I/O Banks

Bank ID	I/O Reference	Comments
BANK 0	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 1	3.3 V ²	WR ¹
BANK 2	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 3	1.8 V/1.5 V/1.2 V/1.0 V	HP
BANK 4	1.8 V/1.5 V/1.2 V/1.0 V	HP
BANK 5	1.8 V/1.5 V/1.2 V/1.0 V	HP
BANK 6	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 7	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹

Notes:

1. WR can be used as an emulated differential output port.
2. Supports only 3.3 V.

Table 3.3. LFMXO5-20TD/20TDQ/30TD/30TDQ/35T/65T I/O Banks

Bank ID	I/O Reference	Comments
BANK 0	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 1	3.3 V ²	WR ¹
BANK 2	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 3	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 4	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 5	1.8 V/1.5 V/1.2 V/1.0 V	HP
BANK 6	1.8 V/1.5 V/1.2 V/1.0 V	HP
BANK 7	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 8	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK 9	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹
BANK10	Does not exist	—
BANK11 ³	3.3 V/2.5 V/1.8 V/1.5V/1.2 V	WR ¹

Notes:

1. WR can be used as an emulated differential output port.
2. Supports only 3.3 V.

3.3. Clock Scheme

A complete description of the MachXO5-NX device family clocking resources and clock routing restrictions are available in [sysCLOCK PLL Design and User Guide for Nexus Platform \(FPGA-TN-02095\)](#).

Below is a brief description of each of the major elements used for building various high-speed interfaces. The [I/O Logic \(DDR\) User Primitives and Attributes](#) section of this document describes the library elements for these components.

3.3.1. Primary Clocks

Primary Clocks (PCLK) refer to the system clocks of the design. The System Clock (SCLK) ports of the DDR primitives are connected to the system clocks of the design.

3.3.2. Edge Clocks

Edge Clocks (ECLK) are high-speed, low-skew I/O dedicated clocks. They are arranged in groups of four per I/O bank on the bottom side of the device. Each of these edge clocks can be used to implement a high-speed interface.

3.4. DQS Lane

A DQS Lane uses the embedded circuit for memory interfaces. Each DQS Lane provides a clock pair (DQSP and DQSN) for the DQS strobe and up to 12 pins (8 DQ + DM+dedicated DQSP/DQSN) for DQ data and DM data mask signals. The number of DQS Lanes on the device is different for each device size. The MachXO5-NX device supports DQS lanes on the bottom side of the device.

3.5. PLL

The PLL provides frequency synthesis, with additional static and dynamic phase adjustment, as well. Six output ports are provided, CLKOP, CLKOS, CLKOS2, CLKOS3, CLKOS4, and CLKOS5. All six outputs have the same set of dividers.

3.6. DDRDLL

The DDRDLL is a dedicated DLL for creating the 90-degree clock delay. The DDRDLL outputs delay codes that are used in the DQSBUF elements to delay the DQS input or in the DLLDEL module to delay the input clock. There are two DDRDLLs at the bottom corners of the MachXO5-NX device. The DDRDLL on the bottom corners of the device can drive delay codes to two adjacent edges of the device, providing possible two DDRDLL codes for an edge.

3.7. DLLDEL

DLLDEL provides phase shift on the receive side clocks to each SCLK or ECLK (Figure 3.4), shifting the clock input by delay set by the DDRDLL delay code before the clock drives the clock tree. The DLLDEL element can further adjust the delay from the delay set by the DDRDLL code for margin test purposes. Control signal *LOADN* (Figure 3.5) asynchronously resets the delay setting to the original (DLL delay control code + fuse adjustment). Control pulse *MOVE* changes the delay setting by +1/-1 tap each time according to the *DIRECTION* value. 0 means increasing the setting by 1 tap, 1 means decreasing the setting by 1 tap. When the delay setting reaches the minimum value 0 or maximum value 255 (8 bits control), the cell generates *COUT* flag to indicate the under/overflow situation, and the delay setting does not roll-over even if the *MOVE* pulse is still coming in.

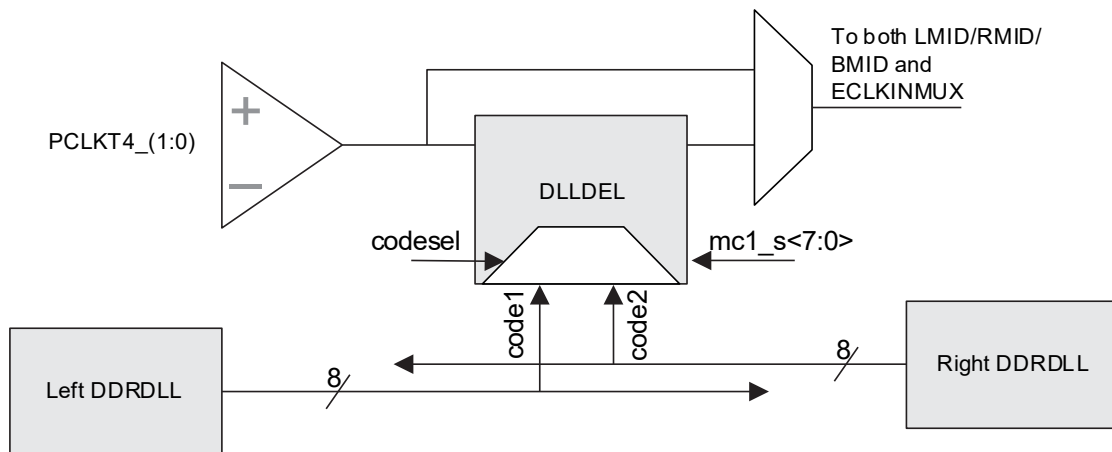


Figure 3.4. DLLDEL and Code Control

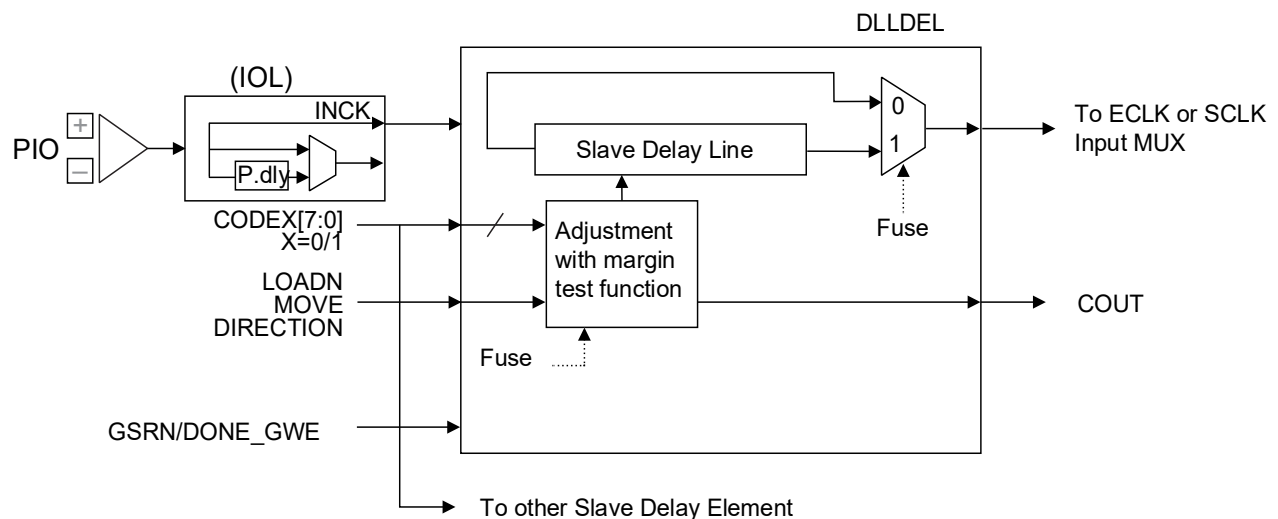


Figure 3.5. DDR Delay Block Diagram

3.8. DQSBUF

There is one DQSBUF for each DQS lane that includes 12 I/O. The DQS input is used when interfacing with DDR memories. It generates the delay on the DQS pin of the DQS lane, to provide a 90-degree phase shift on DQS to clock the DDR data at the center. The delay is set by a delay code generated in the DDRDLL component. Each DQSBUF can receive delay codes from two different DDRDLLs, hence two different DDR memory interfaces can be built on the bottom side of the device.

Each of the DQSBUF modes has an additional feature that allows you to adjust the delay from the delay set by the DDRDLL code, similar to the one used in DLLDEL for margin test, by using the MOVE and DIRECTION inputs controlled by user logic. The LOADN resets the delay back to the DDRDLL code.

3.9. Input DDR (IDDR)

The input DDR function can be used in the 1× (2:1), 2× (4:1), 4× (8:1), 7:1, and 10:1 gearing modes. In the 1× gearing mode, 1× receives 1-bit DDR data and outputs 2-bit wide parallel data synchronized to the SCLK. There is no clock domain transfer involved in the 1× gearing. The 2× receives 1-bit DDR data synchronized to the ECLK and outputs four bits of parallel data synchronized to the SCLK. The same function applies to the 4×, which receives a single bit of DDR data synchronized to the ECLK and outputs eight bits of parallel data synchronized to the SCLK. The 7:1 gearing shares the same structure as the 4× gearing. The 7:1 gearing outputs seven bits of parallel data instead of eight. The 10:1 gearing mode is for SGMII/CDR application.

3.10. Output DDR (ODDR)

The output DDR function can also be supported in 1× (2:1), 2× (4:1), 4× (8:1), 7:1, or 10:1 gearing modes. In the 1× gearing mode, the ODDR element receives 2-bit wide data from the FPGA fabric and generates a single DDR data output or clock output.

Similar to input interfaces, the 2×/4× gearing mode is used for data rates higher than 500/1000 Mbps, which requires higher than 250/500 MHz system clock. Here, the ODDR element receives 4-bit/8-bit wide data from the FPGA fabric and generates a single DDR data output or clock output. The 2×/4× element uses a high-speed edge clock (ECLK) to clock the data out for Generic high-speed interfaces and DQS clock for DDR memory interfaces.

In 7:1 gearing mode, the ODDR element receives 7-bit wide data from the FPGA fabric and generates a single DDR data output or clock output. The 7:1 element sends out data using high-speed edge clock.

3.11. Edge Clock Dividers (CLKDIV)

Clock dividers are provided to create the divided down clocks used with the I/O Mux/Demux gearing logic (SCLK inputs to the DDR) and drives to the Primary Clock routing to the fabric. There are twelve CLKDIV per device, located near the bottom high-speed I/O banks.

3.12. Input/Output DELAY

Similar to using the DLLDEL to tune the clock delay path, there are delay cells (DELAYB and DELAYA) in the PIC that can be utilized to tune the data path (Figure 3.6). DELAYB is static and DELAYA is dynamic, providing a data delay to compensate for clock injection delay. The margin test capability is similar to the one used in DLLDEL. See the DLLDEL section for more details. The DELAYA element also allows you to set the delay value using 128 steps of delay. Each delay step generates ~12.5 ps of delay. You can overwrite the delay setting dynamically using the MOVE and DIRECTION control inputs. The LOADN resets the delay back to the default value.

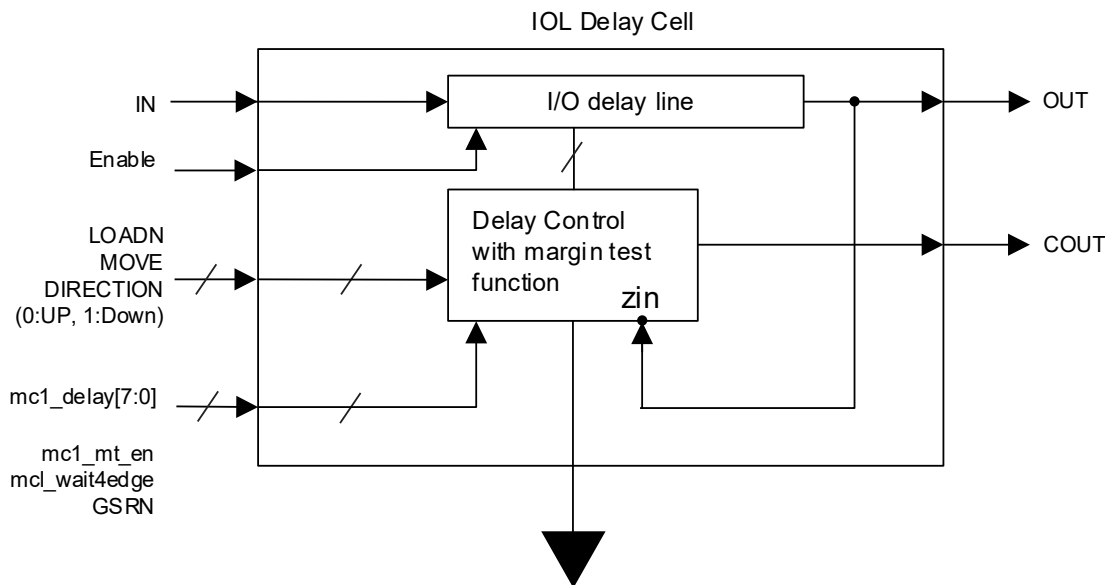


Figure 3.6. PIC Delay Cell Diagram

4. Building Generic High-Speed Interfaces

This section describes in detail the high-speed interfaces that can be built using the building blocks described in the section above. The IP Catalog tool in Lattice Radiant® design software builds these interfaces based on external interface requirements.

4.1. Types of High-Speed I/O Interfaces

This section describes the different types of high-speed I/O interfaces available in the MachXO5-NX device.

Table 4.1 lists these interfaces. The naming conventions used for each interface are provided below the table.

Table 4.1. Generic High-Speed I/O Interfaces

Mode	Interface Name	Description
Receive SDR	GIREG_RX.SCLK	SDR Input register using SCLK.
RX DDRX1 Aligned	GDDR1_RX.SCLK.Aligned	DDR 1× Input using SCLK. Data is edge-to-edge with incoming clock. DLLDEL is used to shift the incoming clock.
RX DDRX1 Centered	GDDR1_RX.SCLK.Centered	DDR ×1 Input using SCLK. Clock is already centered in data window.
RX DDRX2 Aligned	GDDR2_RX.ECLK.Aligned	DDR ×2 Input using ECLK. Data is edge-to-edge with incoming clock. Generic DDR X2 using Edge Clock. DLLDEL is used to shift the incoming clock.
RX DDRX2 Centered	GDDR2_RX.ECLK.Centered	DDR ×2 Input using ECLK. Clock is already centered in data window.
RX DDRX4 Aligned	GDDR4_RX.ECLK.Aligned	DDR ×4 Input using ECLK. Data is edge-to-edge with incoming clock. Generic DDR X4 using Edge Clock. DLLDEL is used to shift the incoming clock.
RX DDRX4 Centered	GDDR4_RX.ECLK.Centered	DDR ×4 Input using ECLK. Clock is already centered in data window.
RX DDRX5 Aligned	GDDR5_RX.ECLK.Aligned	DDR ×5 Input using ECLK. Data is edge-to-edge with incoming clock. Generic DDR X5 using Edge Clock. DLLDEL is used to shift the incoming clock.
RX DDRX5 Centered	GDDR5_RX.ECLK.Centered	DDR ×5 Input using ECLK. Clock is already centered in data window.
RX DDRX71	GDDR71_RX.ECLK	DDR 7:1 input using ECLK.
RX DDRX4 MIPI	GDDR4_RX.MIPI	DDR ×4 Input using ECLK to MIPI interface.
Transmit SDR	GOREG_TX.SCLK	SDR Output using SCLK. Clock is forwarded through ODDR.
TX DDRX1 Aligned	GDDR1_TX.SCLK.Aligned	DDR ×1 Output using SCLK. Data is edge-on-edge using same clock through ODDR.
TX DDRX1 Centered	GDDR1_TX.SCLK.Centered	DDR ×1 Output using SCLK. Clock is centered using PLL with different SCLK.
TX DDRX2 Aligned	GDDR2_TX.ECLK.Aligned	DDR ×2 Output that is edge-on-edge using ECLK.
TX DDRX2 Centered	GDDR2_TX.ECLK.Centered	DDR ×2 Output that is pre-centered PLL generated 90-degree phase, and output on ECLKs.
TX DDRX4 Aligned	GDDR4_TX.ECLK.Aligned	DDR ×4 Output that is edge-on-edge using ECLK.
TX DDRX4 Centered	GDDR4_TX.ECLK.Centered	DDR ×4 Output that is pre-centered PLL generated 90-degree phase, and output on ECLKs.
TX DDRX5 Aligned	GDDR5_TX.ECLK.Aligned	DDR ×5 Output that is edge-on-edge using ECLK.
TX DDRX5 Centered	GDDR5_TX.ECLK.Centered	DDR ×5 Output that is pre-centered PLL generated 90-degree phase, and output on ECLKs.
TX DDRX71	GDDR71_TX.ECLK	DDR 7:1 output using ECLK.
TX DDRX4 MIPI	GDDR4_TX.MIPI	DDR ×4 Output using ECLK to MIPI interface.

The following describes the naming conventions used for each of the interfaces listed in [Table 4.1](#):

- G – Generic
- IREG – SDR Input I/O Register
- OREG – SDR Output I/O Register
- DDRX1 – DDR 1× gearing I/O Register
- DDRX2 – DDR 2× gearing I/O Registers
- _RX – Receive Interface
- _TX – Transmit Interface
- .ECLK – Uses ECLK (Edge Clock) clocking resource
- .SCLK – Uses SCLK (Primary Clock) clocking resource
- .Centered – Clock is centered to the data when coming into the device

5. High-Speed DDR Interface Details

This section describes each of the generic high-speed interfaces in detail, including the clocking to be used for each interface. For detailed information about the MachXO5-NX device clocking structure, refer to [sysCLOCK PLL Design and User Guide for Nexus Platform \(FPGA-TN-02095\)](#). The various interface rules listed under each interface should be followed to build these interfaces successfully.

Some of these interfaces may require a soft IP to utilize all the features available in the hardware. These soft IP cores are available in IP Catalog and are described in this section. Some of these are mandatory for the module to function as expected and are automatically generated when building the interface through IP Catalog.

5.1. GDDR1_RX.SCLK.Centered

This section describes the Generic Receive interface with the X1 gearing using SCLK. The clock is coming in center to the data. This interface must be used for speeds up to 150 MHz.

This DDR interface uses the following modules:

- IDDRX1 element is used to capture data.
- The incoming clock is routed through the Primary (SCLK) clock tree.
- Static data delay element DELAYB is used to delay the incoming data enough to remove the clock injection time.
- Optionally, you can choose to use Dynamic Data delay adjustment using DELAYA element to control the delay on the DATA dynamically. DELAYA also allows you to override the input delay set. The type of delay required can be selected through IP Catalog.
- DEL_MODE attribute is used with DELAYB and DELAYA elements to indicate the interface type so that the correct delay value can be set in the delay element.

The following figures show the static delay and dynamic delay options for this interface.

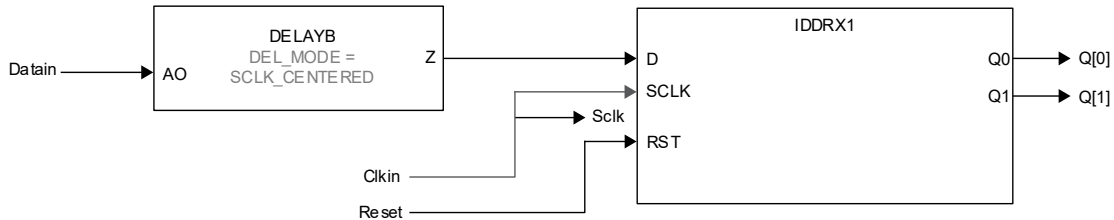


Figure 5.1. GDDR1_RX.SCLK.Centered Interface (Static Delay)

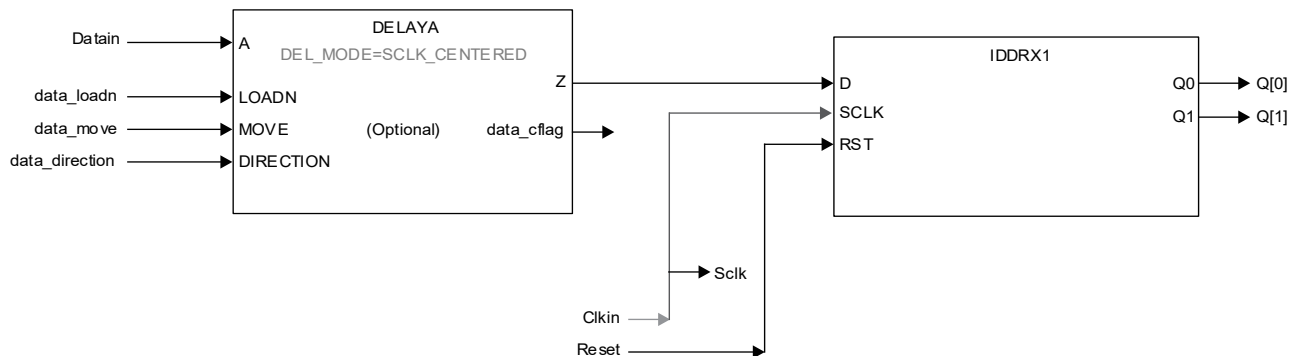


Figure 5.2. GDDR1_RX.SCLK.Centered Interface (Dynamic Data delay)

Interface Requirements

- The clock input must use a PCLK input so that it can be routed directly to the primary clock tree.

5.2. GDDR1_RX.SCLK.Aligned

This section describes the Generic Receive interface with the X1 gearing using SCLK. The clock is coming in edge aligned to the Data. This interface must be used for speeds up to 150 MHz.

This DDR interface uses the following modules:

- IDDRX1 element to capture the data
- DDRDLL/DLLDEL blocks are used to phase shift the incoming clock going to primary clock tree (SCLK).
- Static data delay element DELAYB is used to delay the incoming data enough to remove the clock injection time.
- Optionally, you can choose to use Dynamic Data delay adjustment using DELAYA element to control the delay on the DATA dynamically. DELAYA also allows you to override the input delay set. The type of delay required can be selected through IP Catalog.
- DEL_MODE attribute is used with DELAYB and DELAYA elements to indicate the interface type so that the correct delay value can be set in the delay element.
- Dynamic Margin adjustment in the DDRDLL module can be optionally used to adjust the DDRDLL delay dynamically.

The output of the DLLDEL module is also used as the clock input to the DDRDLL, which sends the delay values to the DLLDEL module. The Receiver Synchronization (RX_SYNC) soft IP is required for the aligned interfaces to prevent stability issues that may occur due to this loop at startup. The soft IP prevents any updates to the DLLDEL at start until the DDRDLL is locked. Once locked the DLLDEL is updated and FREEZE on the DDRDLL is removed. This soft IP is automatically generated by IP Catalog.

The following figures show the static delay and dynamic delay options for this interface.

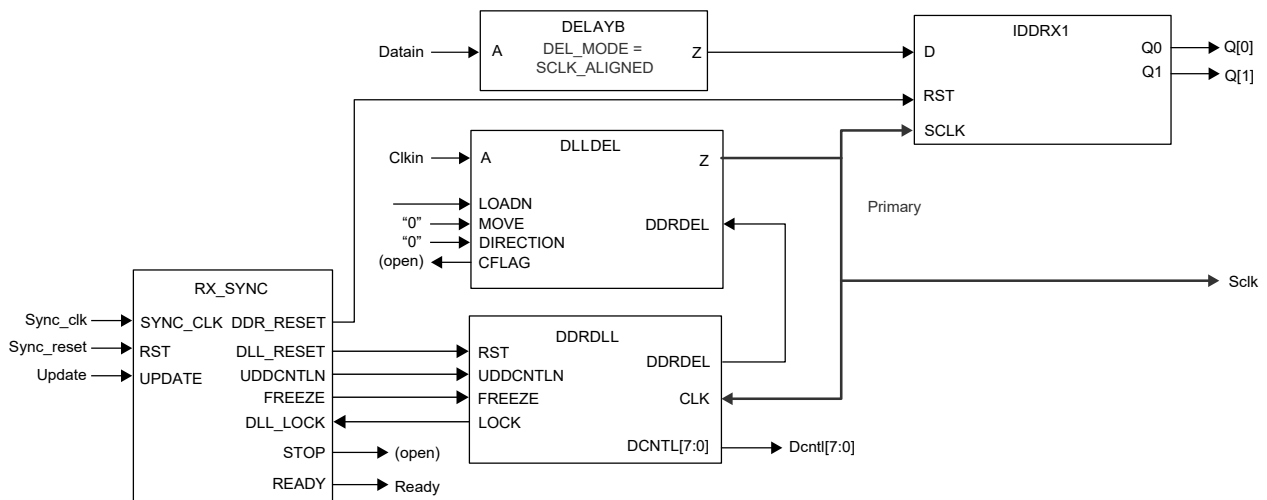


Figure 5.3. GDDR1_RX.SCLK.Aligned Interface (Static Delay)

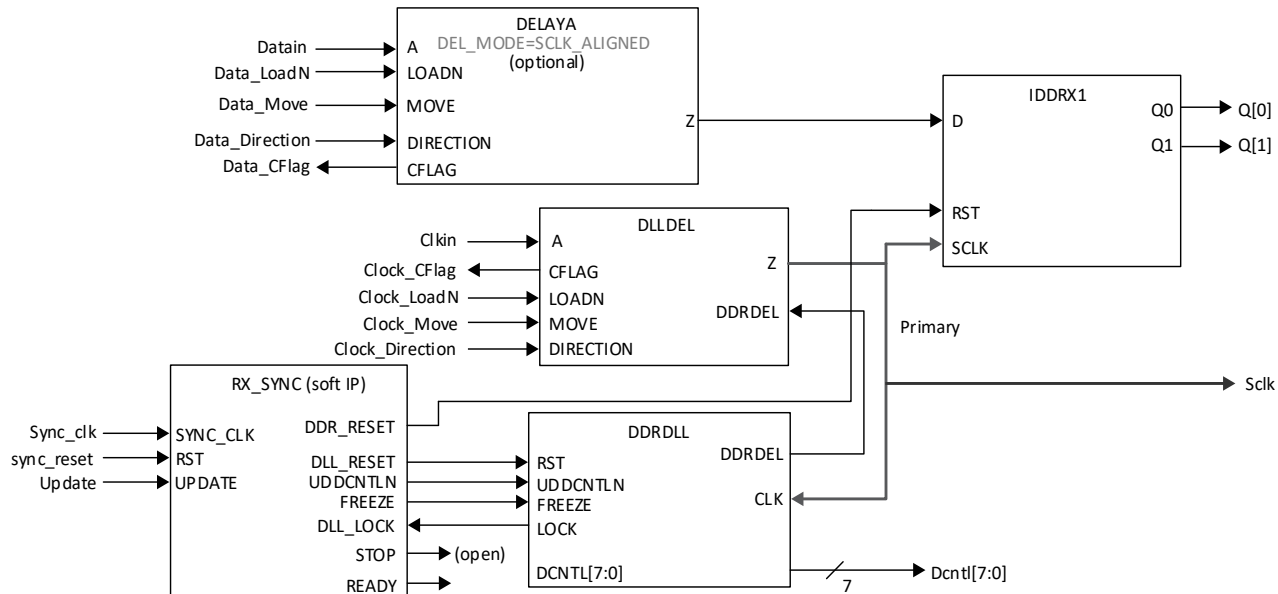


Figure 5.4. GDDR1_RX.SCLK.Aligned Interface (Dynamic Data/Clock Delay)

Interface Requirements

- The clock input must use an even-numbered PCLK input so that it can be routed directly to the DLLDELD input.

5.3. GDDR2_RX.ECLK.Centered

This section describes the Generic Receive DDR with the X2 gearing using Edge Clock Tree (ECLK). Input clock is centered to the input Data.

This DDR interface uses the following modules:

- IDDRX2 element for X2 mode to capture the data
- The incoming clock is routed to the ECLK tree through the ECLKSYNCB module.
- CLKDIVF module is used to divide the incoming clock by 2 to generate the SCLK.
- Static data delay element DELAYB to delay the incoming data enough to remove the clock injection time.
- Optionally, you can choose to use Dynamic Data delay adjustment using DELAYA element to control the delay on the DATA dynamically. DELAYA also allows you to override the input delay set. The type of delay required can be selected through IP Catalog.
- DEL_MODE attribute is used with DELAYB and DELAYA elements to indicate the interface type so that the correct delay value can be set in the delay element.
- ECLKSYNCB element. This element can be enabled through IP Catalog.
- The startup synchronization soft IP (GDDR_SYNC) is required for this interface to tolerate the skew between the ECLKSYNCB Stop input and the Reset to the DDR and CLKDIV modules.

The following figures show the static delay and dynamic delay options for this interface.

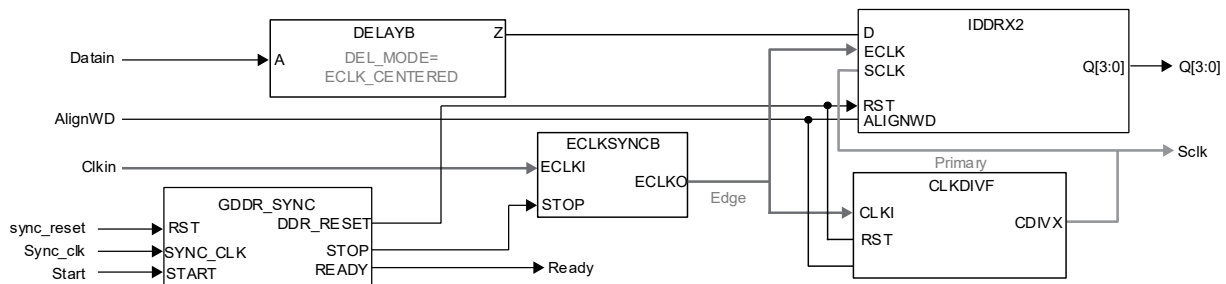


Figure 5.5. GDDR2_RX.ECLK.Centered Interface (Static Delay)

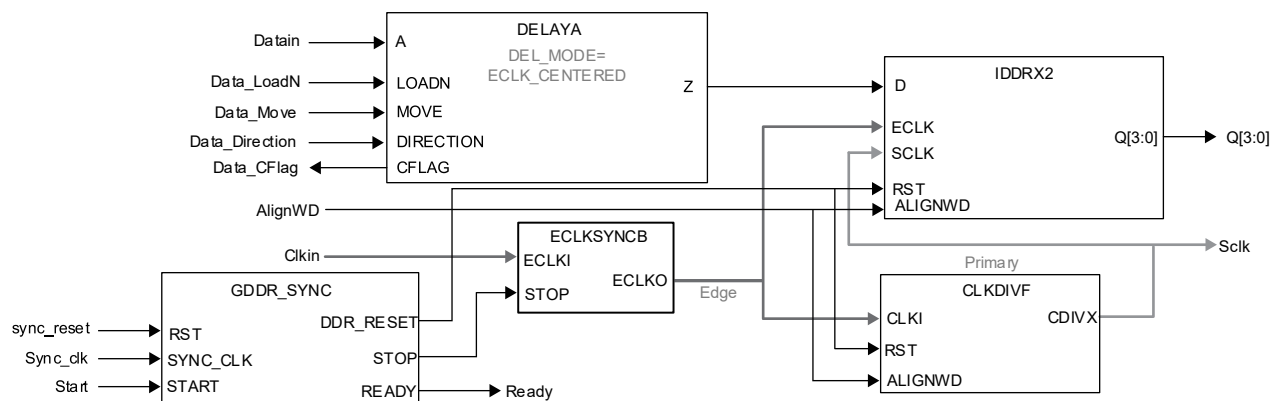


Figure 5.6. GDDR2_RX.ECLK.Centered Interface (Dynamic Data Delay)

Interface Requirements

- The clock input must use a PCLK input so that it can be routed directly to the Edge Clock tree.
- ECLK must use the Edge Clock tree and the SCLK out of the CLKDIVF must use the Primary Clock tree, software errors out if these dedicated clock routes are not used.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.4. GDDR2_RX.ECLK.Aligned

This section describes the Generic Receive DDR with the X2 gearing using ECLK. Input Clock is coming in edge aligned to the Data.

This DDR interface uses the following modules:

- IDDRX2 element for X2 mode to capture the data
- DDRDLL/DLLDEL blocks are used to phase shift the incoming clock routed to the ECLK tree through the ECLKSYNCB module.
- CLKDIVF module is used to divide the incoming clock by 2.
- Static data delay element DELAYB to delay the incoming data enough to remove the clock injection time.
- Optionally, you can choose to use Dynamic Data delay adjustment using DELAYA element to control the delay on the DATA dynamically. DELAYA also allows you to override the input delay set. The type of delay required can be selected through IP Catalog.
- DEL_MODE attribute is used with DELAYB and DELAYA elements to indicate the interface type so that the correct delay value can be set in the delay element.
- Dynamic Margin adjustment in the DDRDLLA module can be optionally used to adjust the DDRDLLA delay dynamically.

The output of the DLLDEL module is also used as the clock input to the DDRDLL, which sends the delay values to the DLLDEL module. The Receiver Synchronization (RX_SYNC) soft IP is required for the aligned interfaces to prevent stability issues that may occur due to this loop at startup. The soft IP prevents any updates to the DLLDEL at start until the DDRDLL is locked. Once locked, the DLLDEL is updated and FREEZE on the DDRDLL is removed. This soft IP is automatically generated by IP Catalog.

The following figures show the static delay and dynamic delay options for this interface.

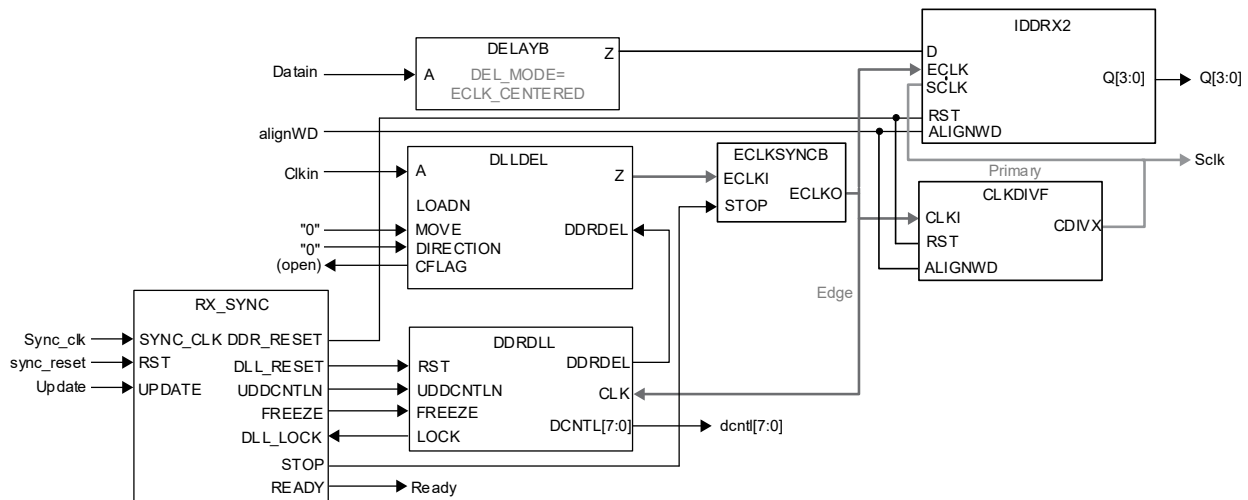


Figure 5.7. GDDR2_RX.ECLK.Aligned Interface (Static Delay)



- The clock input must use an even-numbered PCLK input so that it can be routed directly to the DLLDEL module.
- ECLK must use the Edge Cock tree and the SCLK out of the CLKDIVD must use the Primary Clock tree, software errors out if these dedicated clock routes are not used.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.5. GDDR4_RX.ECLK.Centered

This section describes the Generic Receive DDR with the X4 gearing using Edge Clock Tree (ECLK). Input clock is centered to the input Data.

This DDR interface uses the following modules:

- IDDRX4 element for X4 mode to capture the data.
- The incoming clock is routed to the ECLK tree through the ECLKSYNCB module.
- CLKDIVF module is used to divide the incoming clock by 4 to generate the SCLK.
- Static data delay element DELAYB to delay the incoming data enough to remove the clock injection time.
- Optionally, you can choose to use Dynamic Data delay adjustment using DELAYA element to control the delay on the DATA dynamically. DELAYA also allows you to override the input delay set. The type of delay required can be selected through IP Catalog.
- DEL_MODE attribute is used with DELAYB and DELAYA elements to indicate the interface type so that the correct delay value can be set in the delay element.
- The startup synchronization soft IP (GDDR_SYNC) is required for this interface to tolerate the skew between the ECLKSYNCB Stop input and the Reset to the DDR and CLKDIV modules.

The following figures show the static delay and dynamic delay options for this interface.

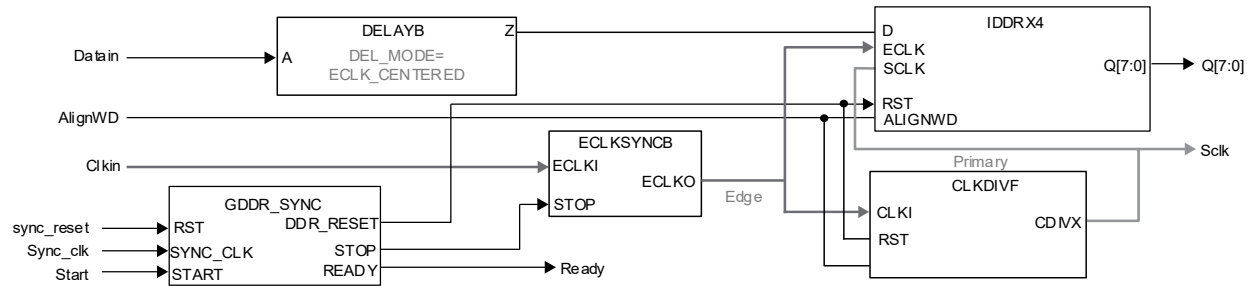


Figure 5.9. GDDR4_RX.ECLK.Centered Interface (Static Delay)

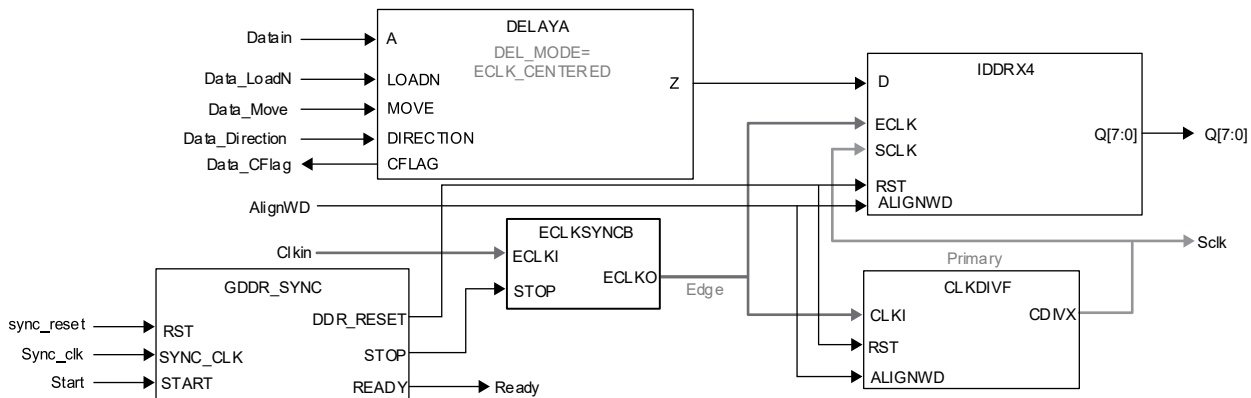


Figure 5.10. GDDR4_RX.ECLK.Centered Interface (Dynamic Data Delay)

Interface Requirements

- The clock input must use a PCLK input so that it can be routed directly to the edge clock tree.
- ECLK must use the Edge clock tree and the SCLK out of the CLKDIVF must use the Primary clock tree, software errors out if these dedicated clock routes are not used.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.6. GDDR4_RX.ECLK.Aligned

This section describes the Generic Receive DDR with the X4 gearing using ECLK. Input Clock is coming in edge aligned to the Data.

This DDR interface uses the following modules:

- IDDRX4 element for X4 mode to capture the data.
- DDRDLL/DLLDEL blocks are used to phase shift the incoming clock routed to the Edge clock (ECLK) clock tree through the ECLKSYNCB module.
- CLKDIVF module is used to divide the incoming clock by 4.
- Static data delay element DELAYB to delay the incoming data enough to remove the clock injection time
- Optionally, you can choose to use Dynamic Data delay adjustment using DELAYA element to control the delay on the DATA dynamically. DELAYA also allows you to override the input delay set. The type of delay required can be selected through IP Catalog.
- DEL_MODE attribute is used with DELAYB and DELAYA elements to indicate the interface type so that the correct delay value can be set in the delay element.
- Dynamic Margin adjustment in the DDRDLL module can be optionally used to adjust the DDRDLL delay dynamically.

The output of the DLLDEL module is also used as the clock input to the DDRDLL, which sends the delay values to the DLLDEL module. The Receiver Synchronization (RX_SYNC) soft IP is required for the aligned interfaces to prevent stability issues that may occur due to this loop at startup. The soft IP prevents any updates to the DLLDEL at start until the DDRDLL is locked. Once locked, the DLLDEL is updated and FREEZE on the DDRDLL is removed. This soft IP is automatically generated by IP Catalog.

The following figures show the static delay and dynamic delay options for this interface.

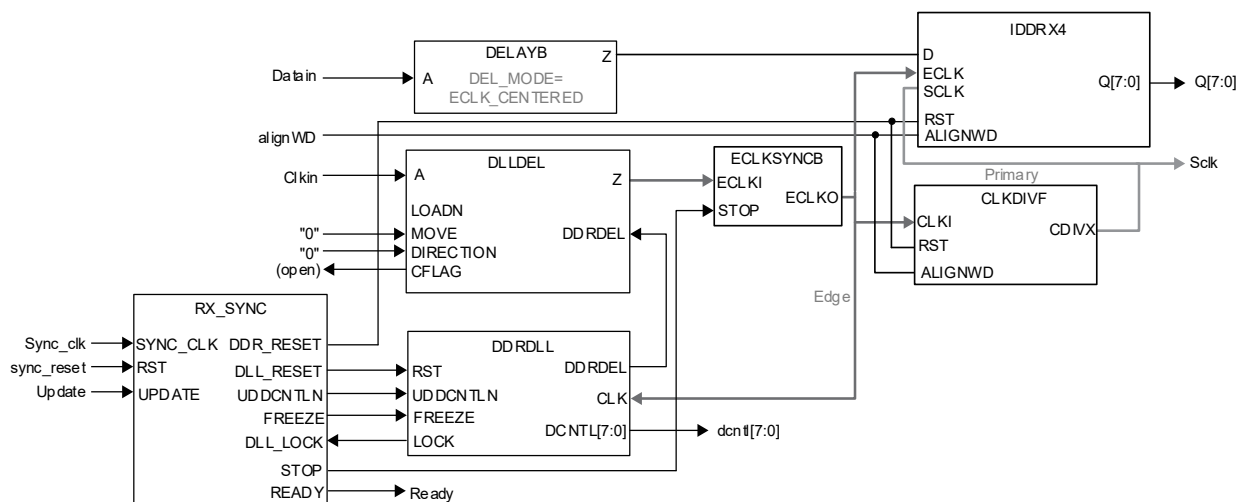


Figure 5.11. GDDR4_RX.ECLK.Aligned Interface (Static Delay)

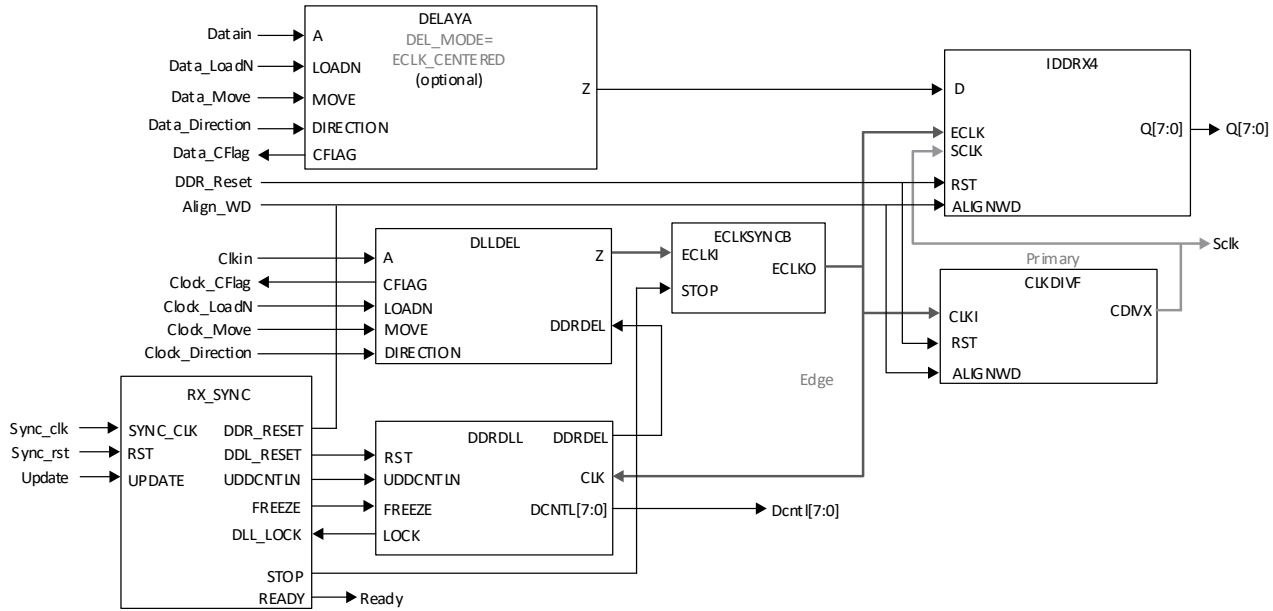


Figure 5.12. GDDR4_RX.ECLK.Aligned Interface (Dynamic Data/Clock Delay)

Interface Requirements

- The clock input must use an even-numbered PCLK input so that it can be routed directly to the DLLDEL module.
- ECLK must use the Edge clock tree and the SCLK out of the CLKDIVD must use the Primary clock tree, software errors out if these dedicated clock routes are not used.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.7. GDDR5_RX.ECLK.Centered

This section describes the Generic Receive DDR with the X5 gearing using Edge Clock Tree (ECLK). Input clock is centered to the input Data.

This DDR interface uses the following modules:

- IDDRX5 element for X5 mode to capture the data.
- The incoming clock is routed to the ECLK tree through the ECLKSYNCB module.
- CLKDIVF module is used to divide the incoming clock by 5 to generate the SCLK.
- Static data delay element DELAYB to delay the incoming data enough to remove the clock injection time.
- Optionally, you can choose to use Dynamic Data delay adjustment using DELAYA element to control the delay on the DATA dynamically. DELAYA also allows you to override the input delay set. The type of delay required can be selected through IP Catalog.
- DEL_MODE attribute is used with DELAYB and DELAYA elements to indicate the interface type so that the correct delay value can be set in the delay element.
- The startup synchronization soft IP (GDDR_X_SYNC) is required for this interface to tolerate the skew between the ECLKSYNCB Stop input and the Reset to the DDR and CLKDIV modules.

The following figures show the static delay and dynamic delay options for this interface.

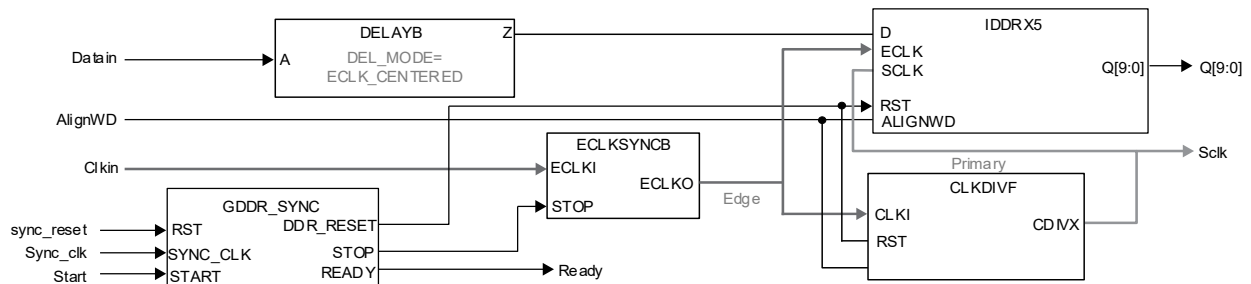


Figure 5.13. GDDR5_RX.ECLK.Centered Interface (Static Delay)

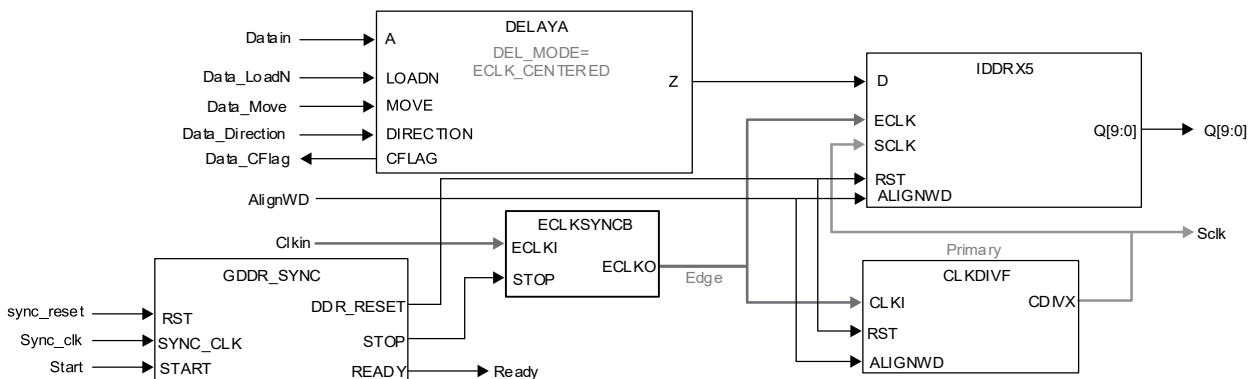


Figure 5.14. GDDR5_RX.ECLK.Centered Interface (Dynamic Data Delay)

Interface Requirements

- The clock input must use a PCLK input so that it can be routed directly to the edge clock tree.
- ECLK must use the Edge clock tree and the SCLK out of the CLKDIVF must use the Primary clock tree, software errors out if these dedicated clock routes are not used.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.8. GDDR5_RX.ECLK.Aligned

This section describes the Generic Receive DDR with the X5 gearing using ECLK. Input Clock is coming in edge aligned to the Data.

This DDR interface uses the following modules:

- IDDRX5 element for X5 mode to capture the data.
- DDRDLL/DLLDEL blocks are used to phase shift the incoming clock routed to the Edge clock (ECLK) clock tree through the ECLKSYNCB module.
- CLKDIVF module is used to divide the incoming clock by 5.
- Static data delay element DELAYB to delay the incoming data enough to remove the clock injection time
- Optionally, you can choose to use Dynamic Data delay adjustment using DELAYA element to control the delay on the DATA dynamically. DELAYA also allows you to override the input delay set. The type of delay required can be selected through IP Catalog.
- DEL_MODE attribute is used with DELAYB and DELAYA elements to indicate the interface type so that the correct delay value can be set in the delay element.
- Dynamic Margin adjustment in the DDRDLL module can be optionally used to adjust the DDRDLL delay dynamically.

The output of the DLLDEL module is also used as the clock input to the DDRDLL, which sends the delay values to the DLLDEL module. The Receiver Synchronization (RX_SYNC) soft IP is required for the aligned interfaces to prevent stability issues that may occur due to this loop at startup. The soft IP prevents any updates to the DLLDEL at start until the DDRDLL is locked. Once locked, the DLLDEL is updated and FREEZE on the DDRDLL is removed. This soft IP is automatically generated by IP Catalog.

The following figures show the static delay and dynamic delay options for this interface.

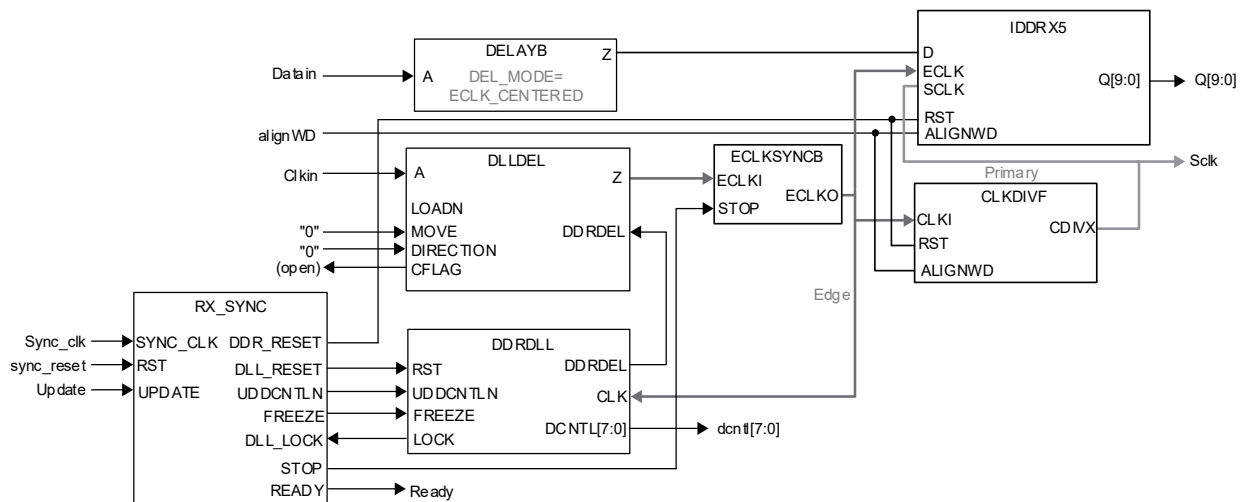


Figure 5.15. GDDR5_RX.ECLK.Aligned Interface (Static Delay)

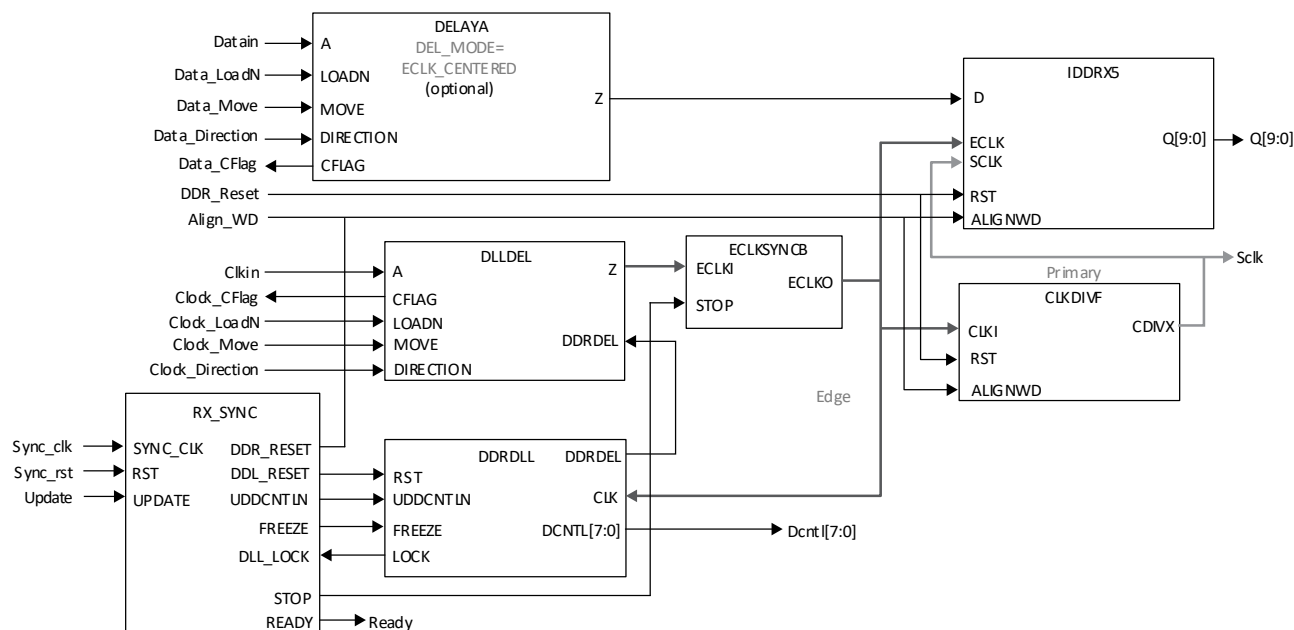


Figure 5.16. GDDR5_RX.ECLK.Aligned Interface (Dynamic Data/Clock Delay)

Interface Requirements

- The clock input must use an even-numbered PCLK input so that it can be routed directly to the DLLDEL module.
- ECLK must use the Edge clock tree and the SCLK out of the CLKDIVF must use the Primary clock tree, software errors out if these dedicated clock routes are not used.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.9. GDDR71_RX.ECLK

This interface is used to implement 7:1 LVDS Receiver interface using the 1 to 7 gearing with ECLK. The slow speed clock coming in is multiplied by 3.5X using a PLL. This clock is used to capture the data at the receiver IDDR71 module.

This DDR interface uses the following modules:

- IDDR71 element is used to capture the data.
- EHXPLL multiplies the input clock by 3.5 and phase shifts the incoming clock based on the dynamic phase shift input.
- This clock is routed to the Edge clock (ECLK) clock tree through the ECLKSYNCB module.
- CLKDIVF module is used to divide the ECLK by 3.5 and is routed to the primary clock tree used as the SCLK input.
- A second IDDR71 element is used with data connected to clock input to generate 7-bit clock phase that can be used for word alignment.
- The startup synchronization soft IP (GDDR_SYNC) is required for this interface to tolerate the skew between the ECLKSYNCB Stop input and the Reset to the DDR and CLKDIV modules.
- An optional Bit and Word alignment soft IP (BW_ALIGN) can be enabled in IP Catalog. The Bit alignment module rotates PLL 16 phases to center Edge clock to middle of data eye and the word alignment module uses ALIGNWD function of CLKDIVD and IDDR71 to achieve 7-bit word alignment.

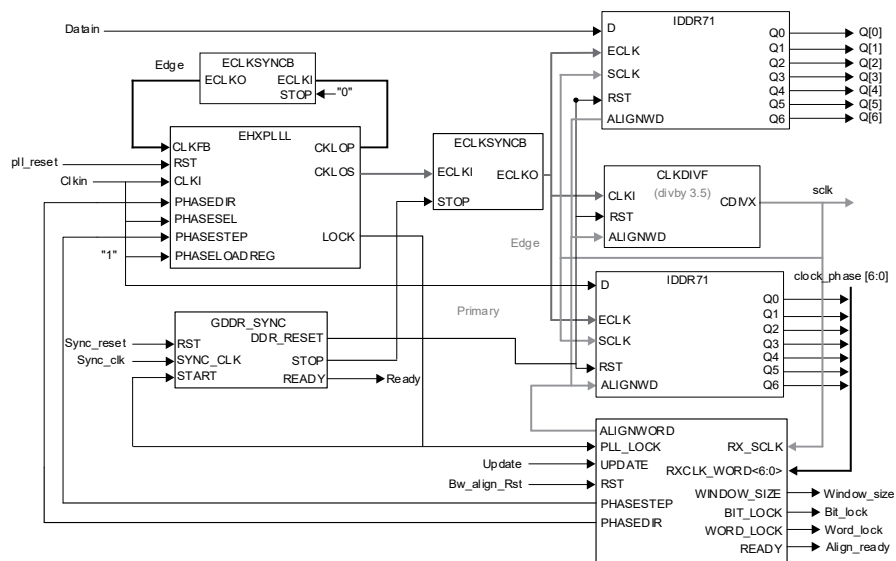


Figure 5.17. GDDR71_RX.ECLK Interface

Interface Requirements

The clock input must use a dedicated PLL input pin, so it is routed directly to the PLL.

- CLKOP output of the PLL must be used as feedback using another Edge Clock tree to compensate for ECLK tree delay used by CLKOS. Hence, this interface uses two ECLK trees.
- ECLK must use the Edge Clock tree and the SCLK out of the CLKDIVF must use the Primary Clock tree.
- *USE PRIMARY* preference may be assigned to the SCLK out of the CLKDIVF module.

5.10. Soft MIPI D-PHY Receive Interfaces

Soft MIPI D-PHY receive interface is supported for MachXO5-NX. The Input DDR elements can be configured as MIPI D-PHY inputs to receive MIPI CSI-2/DSI data using the X4 gearing with ECLK sync and clock divider elements. MIPI D-PHY uses a center-aligned clock. The interface uses the programmable LVDS I/O in Bank5 and Bank6 as MIPI input buffers.

The input and output signals are listed and described in [Table 5.1](#).

Table 5.1. MIPI D-PHY Module Signal Descriptions

Port Name	I/O	Width	Description
Clock and Reset			
sync_clk_i	In	1	GDDR SYNC low speed continuously running input clock
sync_rst_i	In	1	GDDR SYNC active high input reset
clk_byte_o	Out	1	Byte clock
clk_p_io, clk_n_io	In/Out	1	MIPI D-PHY differential clock lanes
lp_tx_clk_p_i ¹	In	1	Low power transmit positive clock
lp_tx_clk_n_i ¹	In	1	Low power transmit negative clock
lp_rx_clk_p_o ²	Out	1	Low power receive positive clock
lp_rx_clk_n_o ²	Out	1	Low power receive negative clock
MIPI D-PHY High-Speed TX			
hs_tx_en_i	In	1	High-speed transmit mode enable
hs_tx_clk_en_i	In	1	High-speed transmit mode clock enable
hs_tx_data_i	In	<i>Bus Width * Gearing Ratio</i>	High-speed transmit mode data
MIPI D-PHY High-Speed RX			
hs_rx_en_i	In	1	High-speed receive mode enable
hs_rx_data_o	Out	<i>Bus Width * Gearing Ratio</i>	High-speed receive mode data. The data is gated by clk_byte_o clock.
MIPI D-PHY Low Power Signal			
lp_tx_en_i ¹	In	1	Low power transmit enable
lp_tx_data_p_i ¹	In	<i>Bus width if Interface Type == Transmit else 1</i>	Low power transmit positive data lane
lp_tx_data_n_i ¹	In	<i>Bus width if Interface Type == Transmit else 1</i>	Low power transmit negative data lane
lp_rx_en_i ³	In	1	Low power receive enable
lp_rx_data_p_o ³	Out	<i>Bus width if Interface Type == Receive else 1</i>	Low power receive positive data
lp_rx_data_n_o ³	Out	<i>Bus width if Interface Type == Receive else 1</i>	Low power receive negative data
MIPI D-PHY			
data_p_io, data_n_io	In/Out	<i>Bus Width</i>	MIPI D-PHY differential data lanes
Misc			
pll_clkop_i ⁴	In	1	Input clock from external PLL
pll_clkos_i ⁴	In	1	90-degree shifted input clock from external PLL
pll_lock_i ⁵	In	1	Lock signal from external PLL
pd_dphy_i ⁶	In	1	Power down input
ready_o	Out	1	Ready output signal from D-PHY or from PLL

Notes:

1. These ports are available only when Interface Type == Receive and MIPI Interface Application == DSI, or Interface Type == Transmit.
2. These ports are available only when *Interface Type* == *Receive*.
3. These ports are available only when Interface Type == Transmit and MIPI Interface Application == DSI, or Interface Type == Receive.
4. These ports are available only when *Interface Type*==*Transmit* and *D-PHY PLL Mode*==*External*.
5. This port is available only when Interface Type==Transmit and D-PHY PLL Mode==External, or Interface Type==Receive.
6. These ports are available only when *Interface Type* == *Transmit*.

5.10.1. Implementation Details

- GDDR SYNC soft IP module is used to start up the RX interface with X4 gearing. This synchronizes the ECLKDIV and DDR elements and signals that RX is ready for operation.
- ECLKSYNC module provides the clock alignment function when ECLKSYNC.STOP is asserted. This alignment function is enabled when ECLKSYNC STOP_EN parameter is set to ENABLED.
- ECLKDIV provides the fix divided down frequency clock to drive the IDDRX4 SCLK input signals to support the required RX gearing data ratio.
- DELAYB is used to delay the input data. This is used with the IDDR module.
- IDDRX4 module is used to implement the X4 gearing of the RX interface.
- MIPI primitive is used to receive MIPI data and clock.
- The clock input must use a PCLK input so that it can be routed directly to the edge clock tree.

Figure 5.18 shows the available input and output ports, while Figure 5.19 shows the interconnection of the modules and primitive on MIPI D-PHY RX interface.

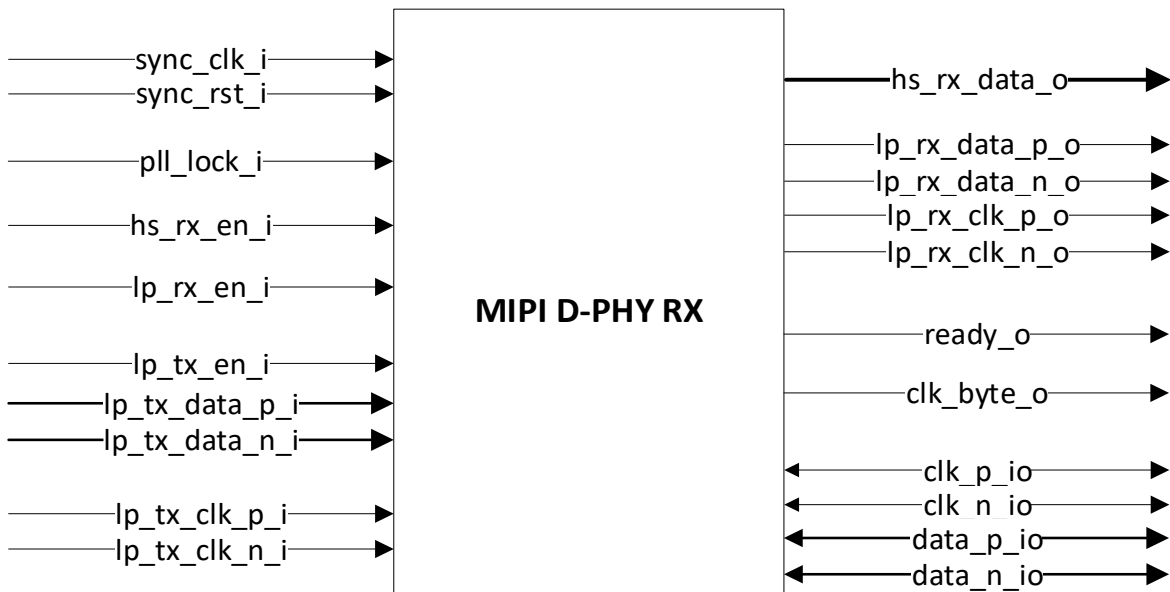
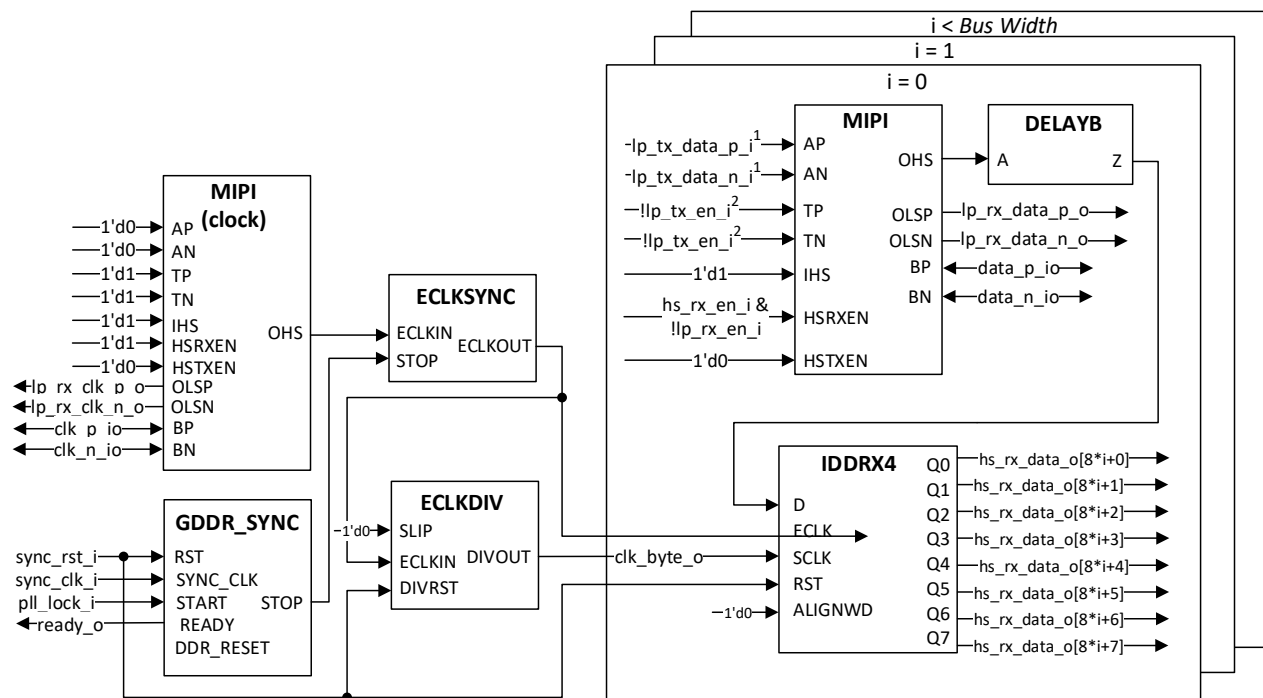


Figure 5.18. MIPI D-PHY RX Block Diagram



Notes:

1. When $i \neq 0$ this is equal to 1'd0
2. When $i \neq 0$ this is equal to 1'd1

Figure 5.19. MIPI D-PHY RX Interface Diagram

5.11. GDDR1_TX.SCLK.Aligned

This interface is used to implement Generic Transmit DDR with X1 gearing using primary clock (SCLK). The Clock output is aligned to the Data output.

This DDR interface uses the following modules:

- ODDR1 element is used to generate the data output.
- The primary clock (SCLK) is used as the clock for both data and clock generation.
- Optionally, you can choose to use the DELAYB or DELAYA element to delay the output data.
- The output data can be optionally tri-stated using either one of the tri-state input going through an I/O register.

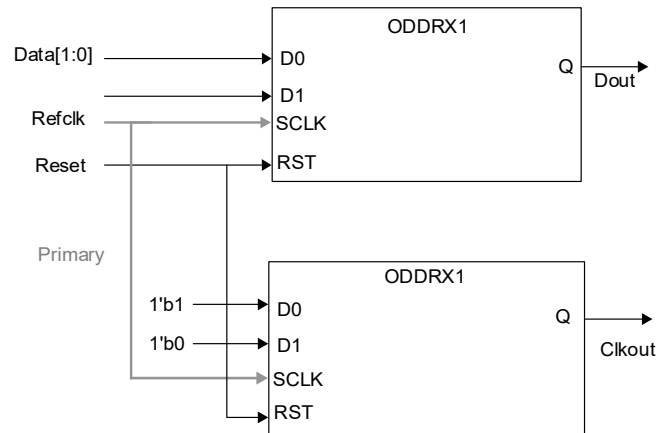


Figure 5.20. GDDR1_TX.SCLK.Aligned Interface

Interface Requirement

- The clock to the output DDR modules must be routed on the primary clock tree.

5.12. GDDR1_TX.SCLK.Centered

This section describes the Generic Transmit DDR using X1 gearing with SCLK. Clock output is centered to the Data output.

This DDR interface uses the following modules:

- ODDR1 element is used to generate the data output.
- The EHXPLL element is used to generate the clocks for the data and clock ODDR1F modules. The clock used to generate the clock output is delayed 90 degrees to center to data at the output.
- Both these clocks are routed on primary clock tree.
- Optionally, you can choose to use the DELAYB or DELAYA element to delay the output data.
- The output data can be optionally tri-stated using either one of the tri-state input going through an I/O register.

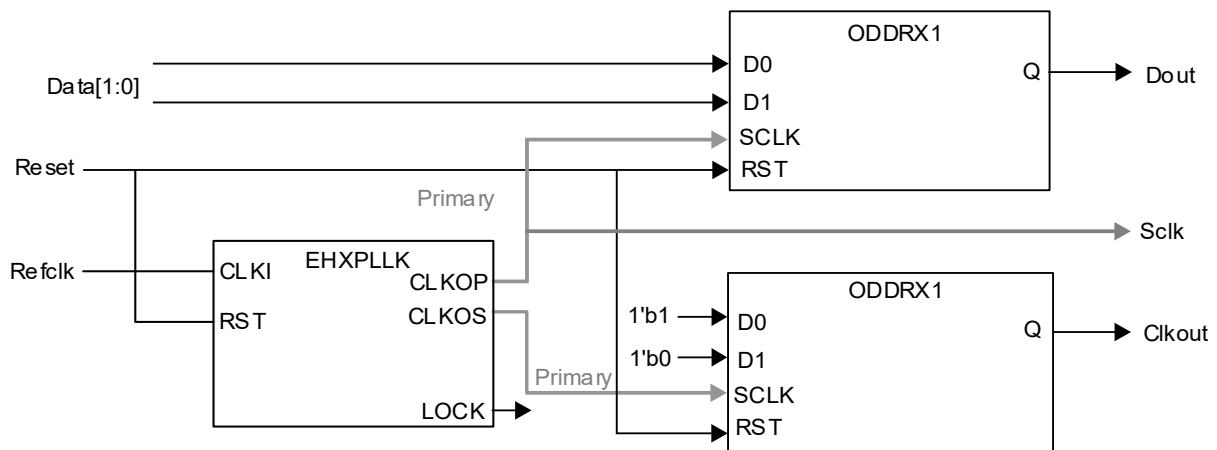


Figure 5.21. GDDR1_TX.SCLK.Centered Interface

Interface Requirement

- The clock to the output DDR modules must be routed on the primary clock tree.

5.13. GDDR_X2_TX.ECLK.Aligned

This interface is used to generate Generic Transmit DDR with X2 gearing using high-speed edge clock (ECLK). The Clock output is edge aligned to the Data output.

This DDR interface uses the following modules:

- ODDR_X2 for X2 gearing is used to generate the output data.
- The high-speed ECLK is routed to the edge clock tree through the ECLKSYN_CB module.
- The SCLK is routed on the primary clock tree and is generated from the ECLK using the CLKDIVF module.
- The same ECLK and SCLK are used for both Data and Clock generation.
- The startup synchronization soft IP (GDDR_SYNC) is required for this interface to tolerate the skew between the ECLKSYN_CB Stop input and the Reset to the DDR and CLKDIV modules.
- Optionally, you can choose to use the DELAYB or DELAYA element to delay the data output.
- The output data can be optionally tri-stated using either one of the tri-state input going through an I/O register.

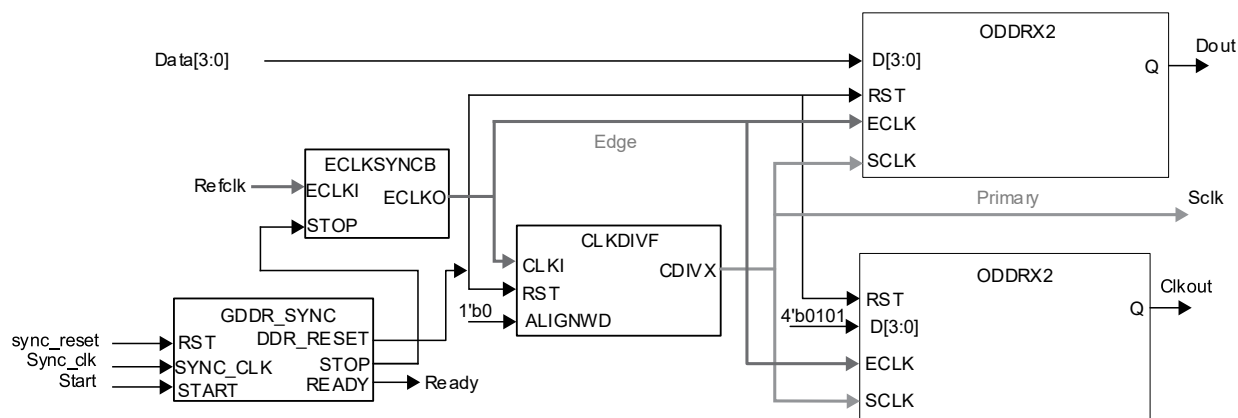


Figure 5.22. GDDR_X2_TX.ECLK.Aligned Interface

Interface Requirements

- The SCLK input to the output DDR modules must be routed on the primary clock tree and the ECLK input is routed on the Edge Clock tree.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.14. GDDR2_TX.ECLK.Centered

This interface is used to implement Generic Transmit DDR with X2 gearing using Edge Clock (ECLK). The Clock output is centered to the Data output.

This DDR interface uses the following modules:

- ODDR2 for X2 gearing is used to generate the data output.
- The high-speed ECLK is routed to the Edge Clock tree through the ECLKSYNCB module.
- The SCLK is routed on the primary clock tree and is generated from the ECLK using the CLKDIVF module.
- The same ECLK and SCLK are used for both Data and Clock generation.
- The EHXPLL element is used to generate the clocks for the data and clock ODDR modules. The clock used to generate the clock output is delayed 90 degrees to center to data at the output.
- The startup synchronization soft IP (GDDR_SYNC) is required for this interface to tolerate the skew between the ECLKSYNCB Stop input and the Reset to the DDR and CLKDIV modules.
- Optionally, you can choose to use the DELAYB or DELAYA element to delay the data output.
- The output data can be optionally tri-stated using either one of the tri-state input going through an I/O register.

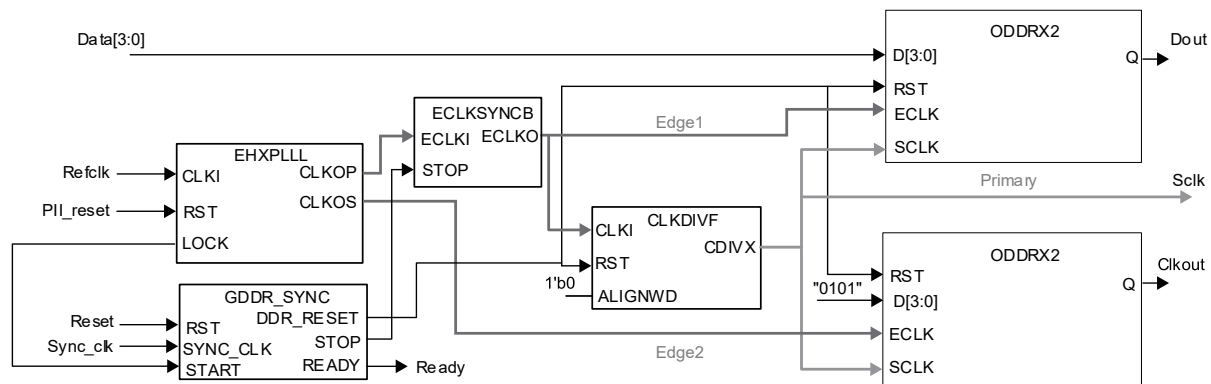


Figure 5.23. GDDR2_TX.ECLK.Centered Interface

Interface Requirements

- The SCLK input to the output DDR modules must be routed on the primary clock tree and the ECLK input is routed on the Edge Clock tree.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.15. GDDR4_TX.ECLK.Aligned

This interface is used to generate Generic Transmit DDR with X4 gearing using high-speed edge clock (ECLK). The Clock output is edge aligned to the Data output.

This DDR interface uses the following modules:

- ODDR4 for X4 gearing is used to generate the output data.
- The high-speed ECLK is routed to the edge clock tree through the ECLKSYNCB module.
- The SCLK is routed on the primary clock tree and is generated from the ECLK using the CLKDIVF module.
- The same ECLK and SCLK are used for both Data and Clock generation.
- The startup synchronization soft IP (GDDR_SYNC) is required for this interface to tolerate the skew between the ECLKSYNCB Stop input and the Reset to the DDR and CLKDIV modules.
- Optionally, you can choose to use the DELAYB or DELAYA element to delay the data output.
- The output data can be optionally tri-stated using either one of the tri-state input going through an I/O register.

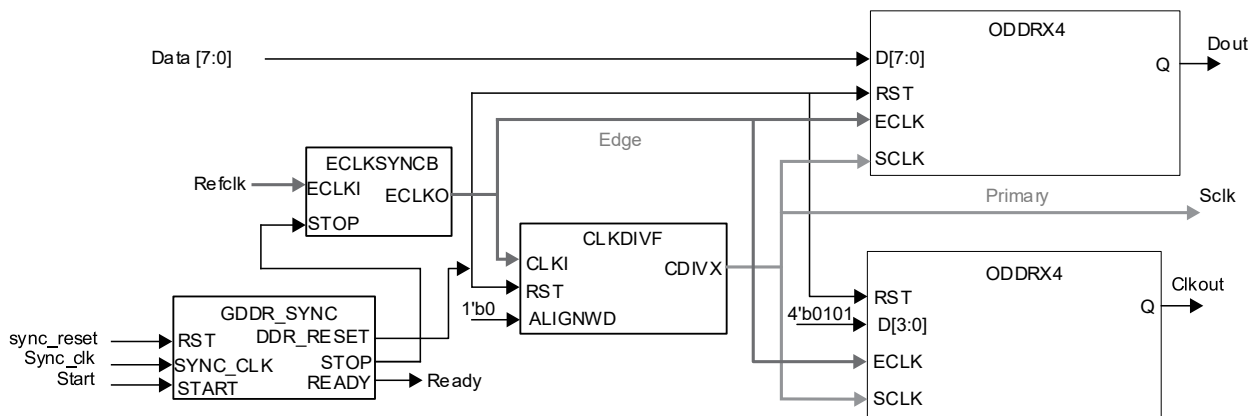


Figure 5.24. GDDR4_TX.ECLK.Aligned Interface

Interface Requirements

- The SCLK input to the output DDR modules must be routed on the primary clock tree and the ECLK input is routed on the edge clock tree.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.16. GDDR4_TX.ECLK.Centered

This interface is used to implement Generic Transmit DDR with X4 gearing using edge clock (ECLK). The Clock output is centered to the Data output.

This DDR interface uses the following modules:

- ODDR4 for X4 gearing is used to generate the data output.
- The high-speed ECLK is routed to the edge clock tree through the ECLKSYNCB module.
- The SCLK is routed on the primary clock tree and is generated from the ECLK using the CLKDIVF module.
- The same ECLK and SCLK are used for both Data and Clock generation.
- The EHXPLL element is used to generate the clocks for the data and clock ODDR modules. The clock used to generate the clock output is delayed 90 to center to data at the output.
- The startup synchronization soft IP (GDDR_SYNC) is required for this interface to tolerate the skew between the ECLKSYNCB Stop input and the Reset to the DDR and CLKDIV modules.
- Optionally, you can choose to use the DELAYB or DELAYA element to delay the data output.
- The output data can be optionally tri-stated using either one of the tri-state input going through an I/O register.

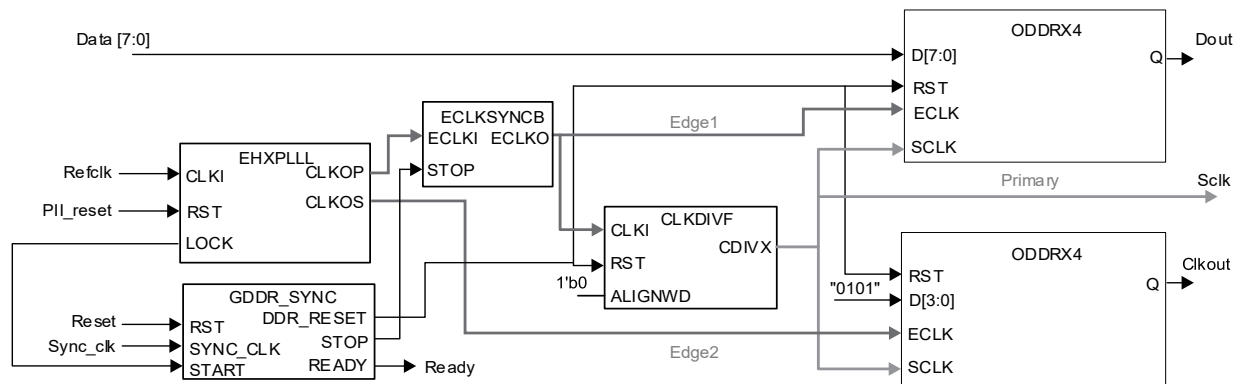


Figure 5.25. GDDR4_TX.ECLK.Centered Interface

Interface Requirements

- The SCLK input to the output DDR modules must be routed on the primary clock tree and the ECLK input is routed on the edge clock tree.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.17. GDDR5_TX.ECLK.Aligned

This interface is used to generate Generic Transmit DDR with X5 gearing using high-speed edge clock (ECLK). The Clock output is edge aligned to the Data output.

This DDR interface uses the following modules:

- ODDR5 for X5 gearing is used to generate the output data.
- The high-speed ECLK is routed to the edge clock tree through the ECLKSYNCR module.
- The SCLK is routed on the primary clock tree and is generated from the ECLK using the CLKDIVF module.
- The same ECLK and SCLK are used for both Data and Clock generation.
- The startup synchronization soft IP (GDDR_SYNC) is required for this interface to tolerate the skew between the ECLKSYNCR Stop input and the Reset to the DDR and CLKDIV modules.
- Optionally, you can choose to use the DELAYB or DELAYA element to delay the data output.
- The output data can be optionally tri-stated using either one of the tri-state input going through an I/O register.

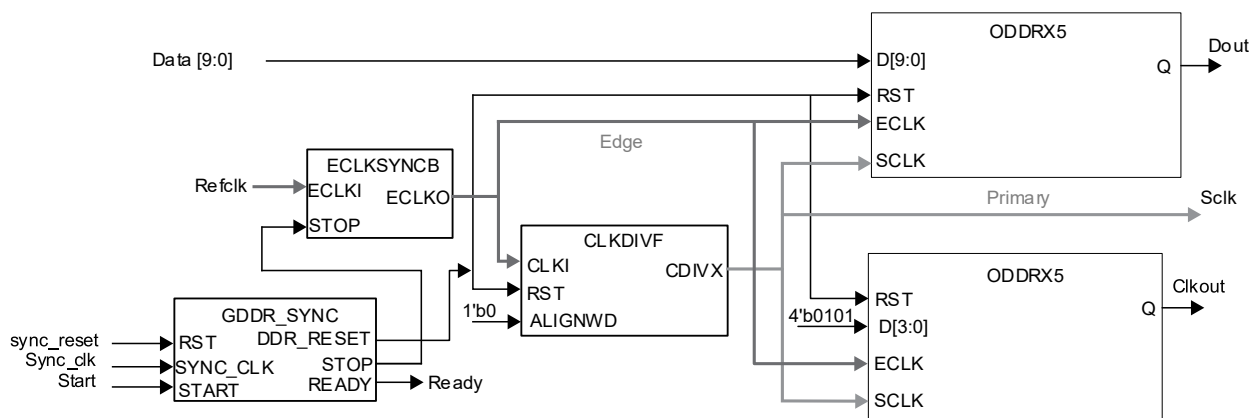


Figure 5.26. GDDR5_TX.ECLK.Aligned Interface

Interface Requirements

- The SCLK input to the output DDR modules must be routed on the primary clock tree and the ECLK input is routed on the edge clock tree.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.18. GDDR5_TX.ECLK.Centered

This interface is used to implement Generic Transmit DDR with X5 gearing using edge clock (ECLK). The Clock output is centered to the Data output.

This DDR interface uses the following modules:

- ODDR5 for X5 gearing is used to generate the data output.
- The high-speed ECLK is routed to the edge clock tree through the ECLKSYNCB module.
- The SCLK is routed on the primary clock tree and is generated from the ECLK using the CLKDIVF module.
- The same ECLK and SCLK are used for both Data and Clock generation.
- The EHXPLL element is used to generate the clocks for the data and clock ODDR modules. The clock used to generate the clock output is delayed 90 to center to data at the output.
- The startup synchronization soft IP (GDDR_SYNC) is required for this interface to tolerate the skew between the ECLKSYNCB Stop input and the Reset to the DDR and CLKDIV modules.
- Optionally, you can choose to use the DELAYB or DELAYA element to delay the data output.
- The output data can be optionally tri-stated using either one of the tri-state input going through an I/O register.

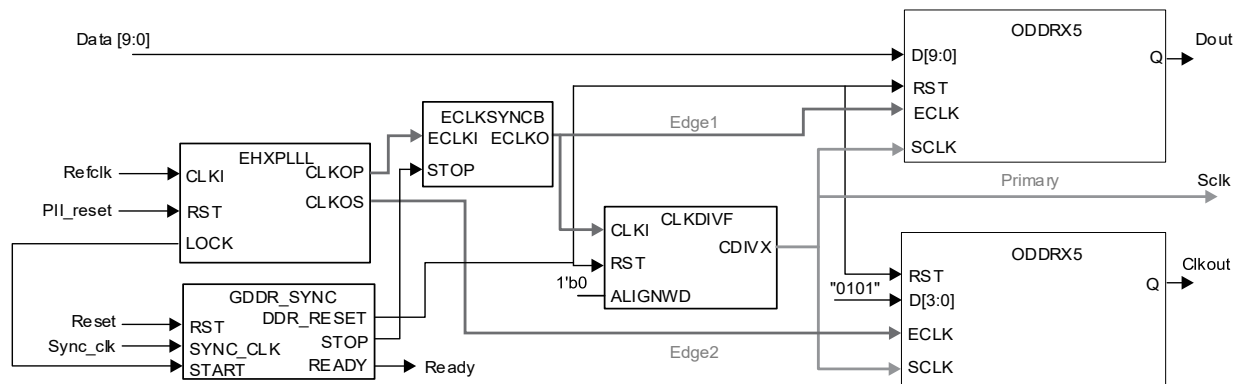


Figure 5.27. GDDR5_TX.ECLK.Centered Interface

Interface Requirements

- The SCLK input to the output DDR modules must be routed on the primary clock tree and the ECLK input is routed on the edge clock tree.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.19. GDDR71_TX.ECLK

This interface is used to implement transmit side of the 7:1 LVDS interface DDR using the 7 to 1 gearing with ECLK. The clock output is aligned to the data output.

This DDR interface uses the following modules:

- ODDR71 is used to generate the data output.
- The high-speed ECLK is routed to the Edge Clock tree through the ECLKSYNCB module.
- The SCLK is routed on the primary clock tree and is generated from the ECLK using the CLKDIVD module.
- The same ECLK and SCLK are used for both Data and Clock generation.
- The startup synchronization soft IP (GDDR_SYNC) is required for this interface to tolerate the skew between the ECLKSYNCB Stop input and the Reset to the DDR and CLKDIV modules.

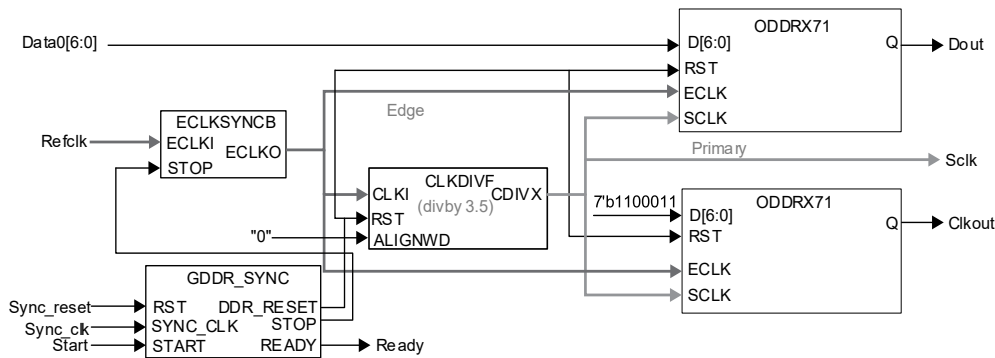


Figure 5.28. GDDR71_TX.ECLK Interface

Interface Requirements

- The SCLK input to the output DDR modules must be routed on the primary clock tree and the ECLK input is routed on the Edge Clock tree.
- *USE PRIMARY* preference may be assigned to the SCLK net.

5.20. Soft MIPI D-PHY Transmit Interfaces

Soft MIPI D-PHY transmit interface is supported for MachXO5-NX. The output DDR elements can be configured as MIPI D-PHY outputs to transmit MIPI CSI-2/DSI data using the X4 gearing with ECLK sync and clock divider elements. MIPI D-PHY uses a center-aligned clock. The interface uses the programmable LVDS I/O in Bank5 and Bank6 as MIPI output buffers.

Detailed descriptions of MIPI D-PHY TX ports are available in [Table 5.1](#).

5.20.1. Implementation Details

- GDDR SYNC soft IP module is used to start up the TX interface with X4 gearing. This synchronizes the ECLKDIV and DDR elements and signals that TX is ready for operation.
- ECLKSYNC module provides the clock alignment function when ECLKSYNC.STOP is asserted. This alignment function is enabled when ECLKSYNC STOP_EN parameter is set to ENABLED.
- ECLKDIV provides the fix divided down frequency clock to drive the ODDR4 SCLK input signals to support the required TX gearing data ratio.
- ODDR4 module is used to implement the X4 gearing of the TX interface.
- MIPI primitive is used to transmit MIPI data and clock.

[Figure 5.29](#) shows the available input and output ports, while [Figure 5.30](#) shows the interconnection of the modules and primitive on MIPI D-PHY TX interface.

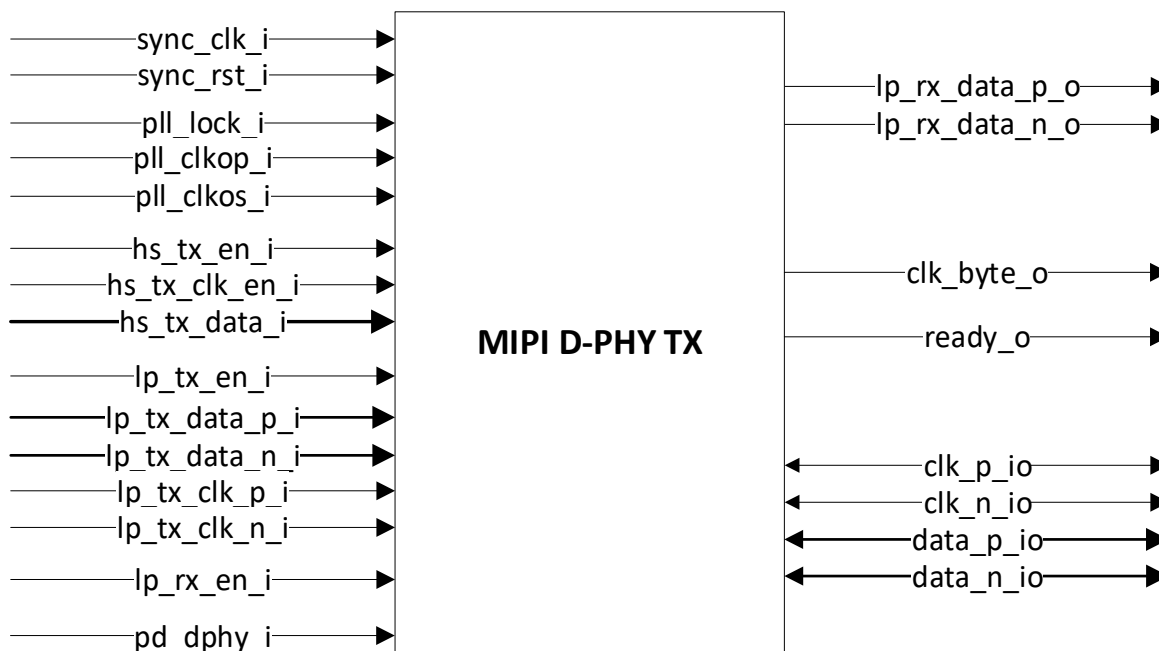
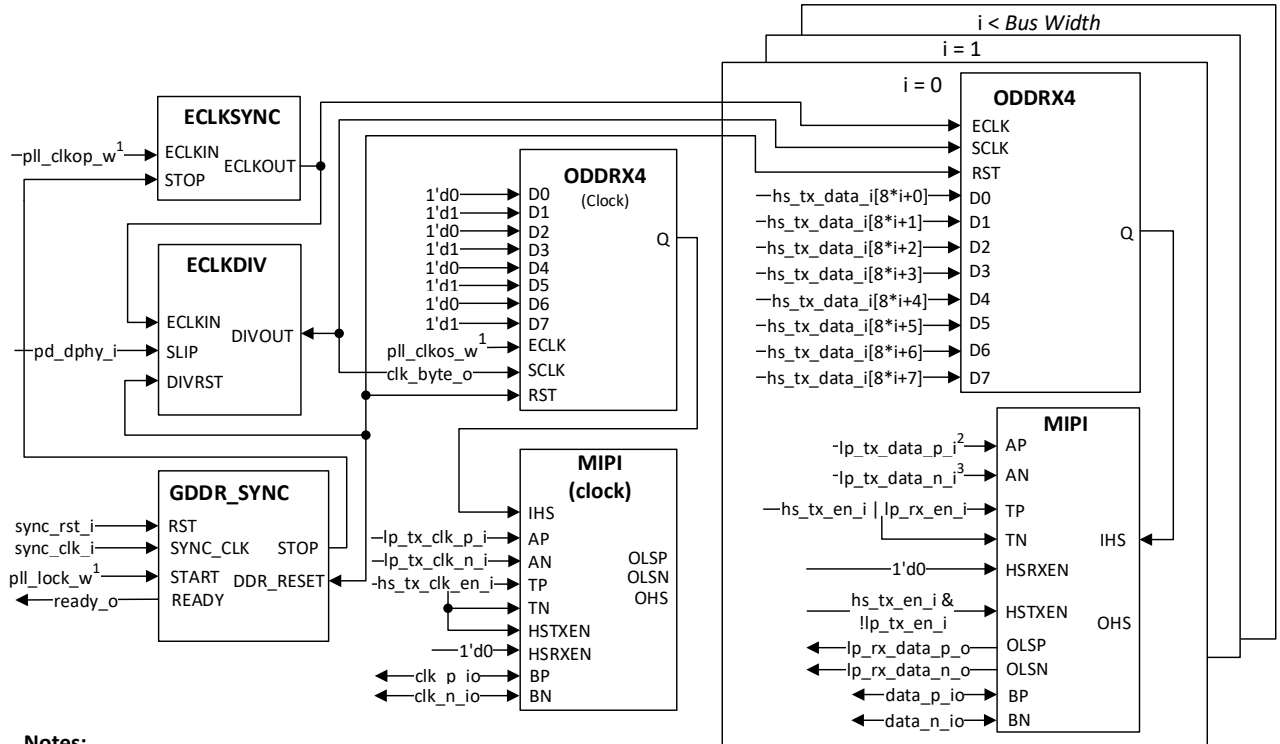


Figure 5.29. MIPI D-PHY TX Block Diagram



Notes:

1. These ports connect to internal or external PLL (pll_lock_i, pll_clkop_w and pll_clkos_w)
2. When $i == 0$ this is equal to $lp_tx_data_p_i[0]$ & $!lp_rx_en_i$
3. When $i == 0$ this is equal to $lp_tx_data_n_i[0]$ & $!lp_rx_en_i$

Figure 5.30. MIPI D-PHY TX Interface Diagram

5.21. MachXO5-NX Generic DDR Design Guidelines

This section describes the various design guidelines used for building generic high-speed DDR interfaces in MachXO5-NX devices. In addition to these guidelines, it is also required to follow the Interface Rules described for each type of interface. Refer to the [High-Speed DDR Interface Details](#) section to find the interface you are building.

5.21.1. Receive Interface Guidelines

- Differential DDR interface can be implemented on the bottom side of the device.
- There are four different Edge Clocks available on the bottom side of the device can be used to generate either a center or aligned interface.
- Each Bank on the bottom side of the device has four ECLKDIV modules, which means that you can implement four different GDDR2 RX interfaces per Bank since each 2 $\times$, 4 $\times$, or 5 $\times$ gearing would require a ECLKDIV module to generate a slower SCLK.
- There are two DDRDLLs located in the lower left and lower right corners of the device.
- Each DQSBUF/DLLDEL has access to two DDRDLLs. Hence, two different RX rates are available on the bottom side.
- The Receive clock input should be placed on a dedicated PCLK input pin. The PCLK pin has direct access to the Edge Clock tree for centered interface and it also has direct connection to the DLLDEL when implementing an aligned interface.
- When implementing IDDRX71 interface, the complementary PAD is not available for other functions since the IDDRX71 used the I/O registers of the complementary PAD as well.
- It is recommended that clock input be located on the same side as data pins.
- The top, left, and right side of the device do not have Edge Clocks. Hence, these can only be used to receive lower speed interfaces (<150 MHz) that use 1 $\times$ gearing. These can be used for single ended interfaces only.
- Interfaces using the $\times 1$ gearing use the primary clock resource. You can use as many interfaces as the number of primary clocks supported in the device.
- In addition to the dedicated PCLK pins, MachXO5-NX devices have GR_PCLK pins. These pins use the shortest general route path to get to the primary clock tree. These pins are not recommended for use with DDR interfaces. They can be used for SDR or other generic FPGA designs.

5.21.2. Transmit Interface Guidelines

- Use PADA and PADB for all TX using true LVDS interfaces.
- When implementing Transmit Centered interface, two ECLKs are required. One to generate the Data Output and the other to generate the CLK Output.
- When implementing Transmit Aligned interface, only one ECLK is required for both Data output and Clock output.
- Each Bank on the bottom side of the device has four ECLKDIV modules, which means that you can implement up to four different GDDR2 TX interfaces per Bank since each 2 $\times$, 4 $\times$, or 5 $\times$ gearing would require a ECLKDIV module to generate a slower SCLK.
- The top, left and right side of the device does not have Edge Clocks hence can only be used to receive lower-speed interfaces (<150 MHz) that use 1 $\times$ gearing. It can be used for single-ended interfaces only.
- Interfaces using the $\times 1$ gearing use the primary clock resource. You can use as many interfaces as the number of primary clocks supported in the device.

5.21.3. Clocking Guidelines for Generic DDR Interface

- The Edge Clock and Primary Clock resources are used when implementing a 2×, 4×, or 5× receive or transmit interface.
- Only the Primary Clock (PCLK) resources are used when implementing x1 receive or transmit interfaces.
- Each Edge Clock can only span up to one side of the device, hence all the data bits of the in the x2 interface must be locked to one side of the device.
- The ECLK to DDR registers can be accessed through dedicated PCLK pins, GPLL outputs, DDRDLL outputs. See [sysCLOCK PLL Design and User Guide for Nexus Platform \(FPGA-TN-02095\)](#) for details.
- Primary Clock to DDR registers can be accessed through dedicated PCLK pins, GPLL outputs, and CLKDIV outputs. See [sysCLOCK PLL Design and User Guide for Nexus Platform \(FPGA-TN-02095\)](#) for details.
- None of the clocks going to the DDR registers can come from internal general routing.
- DQS clocking is used for DDR memory interface implementation. DQS clock spans every 12 I/O including the DQS pins. Refer to the [DQS Grouping](#) section for pinout assignment rules when using DQS clocking.

6. MachXO5-NX Memory Interfaces

All of the DDR SDRAM interface transfers data at both the rising and falling edges of the clock. The I/O DDR registers in the MachXO5-NX device can be used to support DDR3, DDR3L, and LPDDR4 memory interfaces.

These memory interfaces rely on the use of a data strobe signal, called DQS, for high-speed operation. The DQS strobe is a differential signal.

Figure 6.1 and Figure 6.2 show typical DDR memory signals. DDR3, DDR3L, and LPDDR4 memory interfaces are typically implemented with eight DQ data bits per DQS. Therefore, a 16-bit DDR memory interface uses two DQS signals, and each DQS is associated with eight DQ bits, respectively. Both the DQ and DQS are bi-directional ports and are used to read and write to the memory.

When reading data from the external memory device, data coming into the FPGA controller is edge-aligned with respect to the DQS signal. This DQS strobe signal needs to be phase shifted 90° before the FPGA logic can sample the read data. When writing to a DDR memory, the memory controller (FPGA) must shift the DQS by 90° to center-align with the data signals (DQ). A clock signal is also provided to the memory. This clock is provided as a differential clock (CK and CK#) to minimize duty cycle variations. The memory also uses these clock signals to generate the DQS signal during a read through a DLL inside the memory. The figures below show DQ and DQS timing relationships for read and write cycles.

During read, the DQS signal is low for some duration after it comes out of tri-state. This state is called preamble.

The state when the DQS is low before it goes into tri-state is the postamble state. This is the state after the last valid data transition.

DDR memories also require a Data Mask (DM) signal to mask data bits during write cycles. Note that the ratio of DQS to data bits is independent of the overall width of the memory. Figure 6.1 and Figure 6.2 show typical 8-bit interface that has eight associated DQ data bits per DQS strobe signal.

The DDR3 memory module uses fly-by routing topology for the address, command, and clock signals. This requires the memory controller to support read and write leveling to adjust for leveled delay on read and write data transfers.

One major difference between DDR Memory and LPDDR Memory is lack of DLL in LPDDR Memory device. This means that in LPDDR, the clock to data output delay from memory device is not compensated by DLL as in traditional DDR Memory, thus the delay is much larger and has larger spread. Theoretically, there is no low frequency limitation on LPDDR, although most manufactures place a low limit of 10 MHz. Note that on the FPGA memory controller side, DLL is still needed to manage write and read phase shift, for all memory interfaces including LPDDR.

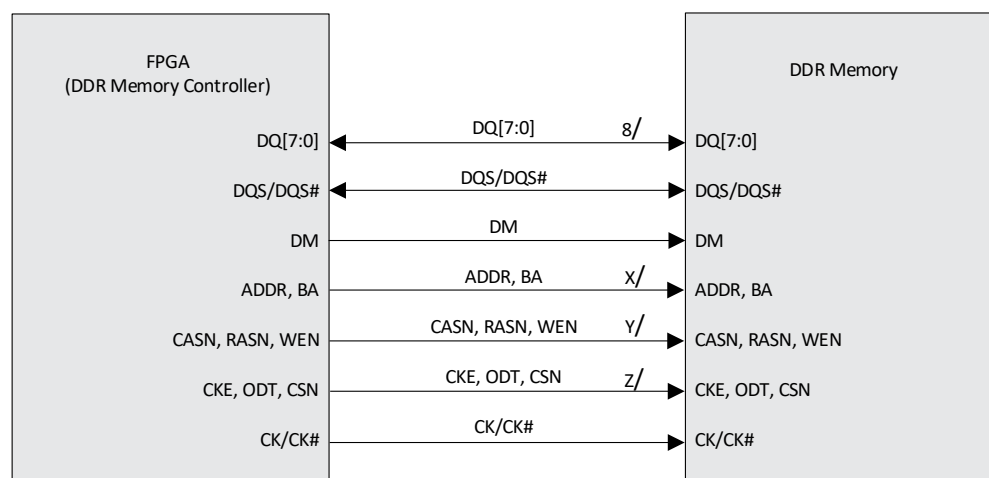


Figure 6.1. Typical DDR3/DDR3L Memory Interface

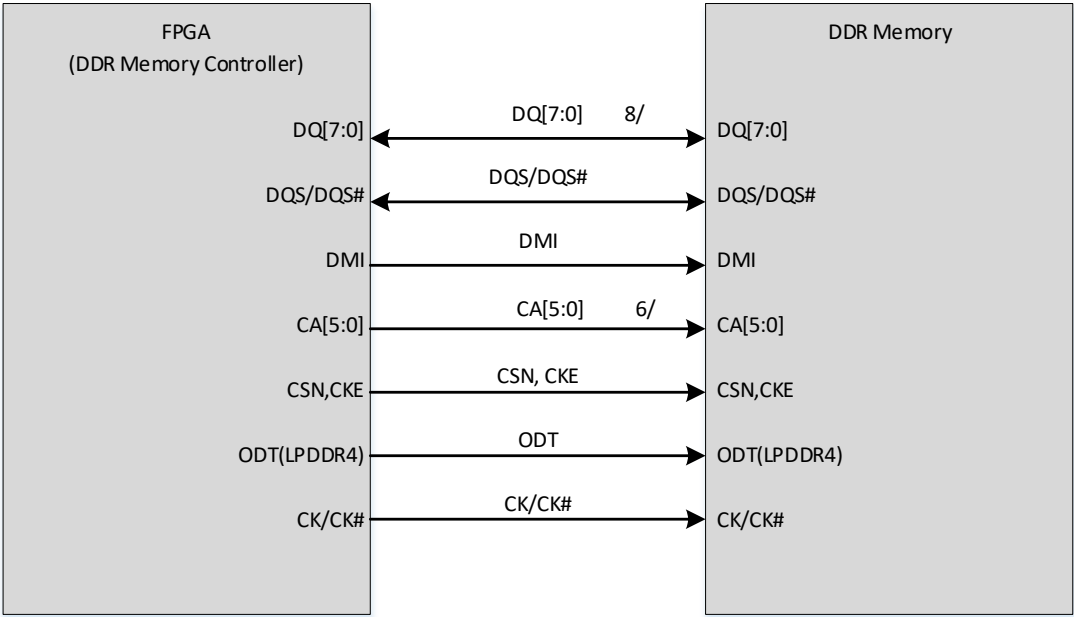


Figure 6.2. Typical LPDDR4 Memory Interface

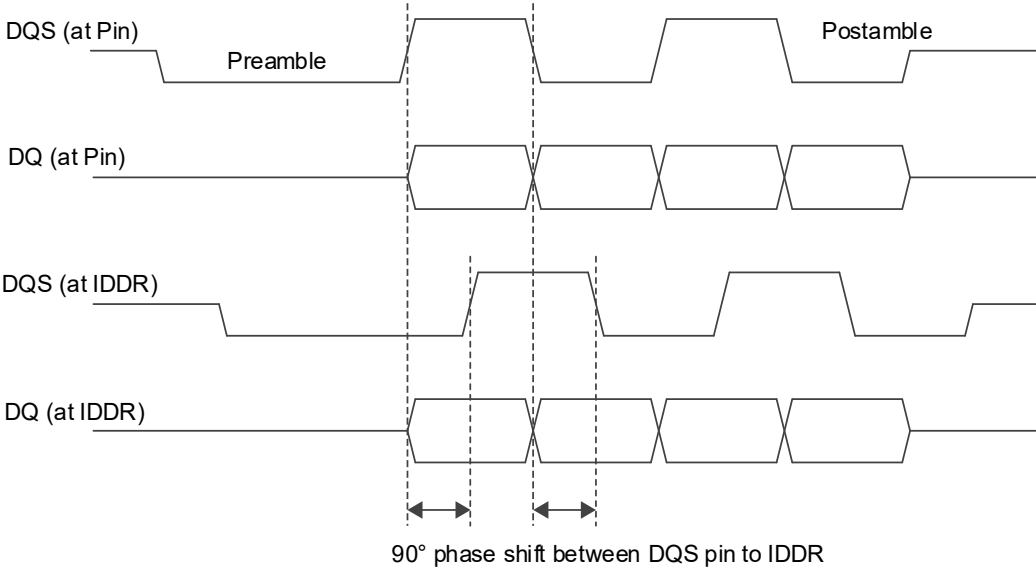


Figure 6.3. DQ-DQS During Read

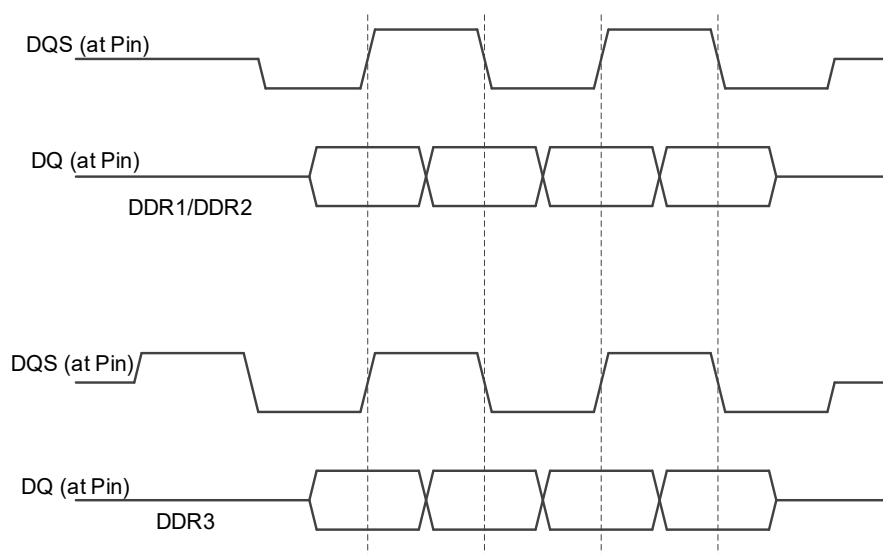


Figure 6.4. DQ-DQS During Write

Table 6.1 below shows the different DDR memory configurations and features supported by the MachXO5-NX device.

Table 6.1. DDR Memory Configurations Support

DDR Memory	Data Width	VCCIO	DQ	DQS	Modules Types	Rank	Chip Selects	Write Leveling	CMD/ADDR Timing	Fmax
DDR3	8, 16 bits	1.5 V	SSTL15_I	SSTL15D_I	UDIMM, SODIMM, RDIMM	Single, Dual	1, 2	Yes	2T ³	533 MHz
	8, 16 bits	1.5 V	SSTL15_I	SSTL15D_I	Embedded	Single, Dual	1, 2	Yes ¹	2T ³	533 MHz
DDR3L	8, 16 bits	1.35 V	SSTL135_II	SSTL135D_II	UDIMM, SODIMM, RDIMM	Single, Dual	1, 2	Yes	2T ³	533 MHz
	8, 16 bits	1.35 V	SSTL135_II	SSTL135D_II	Embedded	Single, Dual	1, 2	Yes ¹	2T ³	533 MHz
LPDDR4	16,32,64 bits	1.1 V	LVSTL11	LVSTL11D	Embedded (Single Channel)	Single	1, 2,4	Yes ¹	2T ³	533 MHz

Notes:

1. If fly-by wiring is implemented.
2. Fly-by wiring is emulated using board traces (guidelines are in the [DDR3 Memory Interface Termination Guidelines](#) section below).
3. CSN uses 1T timing.

6.1. DDR Memory Interface Requirements

As described in the overview section, all the DDR memory interfaces rely on the use of a data strobe signal, called DQS, for high-speed operation. When reading data from the external memory device, data coming into the MachXO5-NX device is edge-aligned with respect to the DQS signal. Therefore, the MachXO5-NX device needs to shift the incoming DQS (90° phase shift) before using it to sample the read data.

To implement the write portion of a DDR memory interface, parallel single data rate data must be multiplexed depending on the IDDR and ODDR register gearing mode together with data transitioning on both edges of the clock. In addition, during a write cycle, the MachXO5-NX devices generate a DQS signal that is center aligned with DQ, the data signal. This is accomplished by ensuring a DQS strobe is 90-degree shifted relative to the DQ data. The MachXO5-NX devices provide the solutions to achieve the following design challenges to implement DDR memory write functions:

- DQ/DM needs to be center-aligned to DQS.
- DQS needs to be edge-aligned to CK. In DDR3 interfaces where fly-by routing is used, write leveling should be used to compensate for skews between CK and DQS.
- The DDR output data must be multiplexed into a single outgoing DDR data stream.
- Generate ADDR/CMD signal edge-aligned to CK falling edge to maximize the tIS and tIH timing parameters.
- Differential CK signals (CK and CK#) need to be generated.
- The controller must meet the DDR interface specification for the tDSS and tDSH parameters, defined as DQS falling edge setup and hold time to/from CK rising edge, respectively. The skews, if caused by the fly-by topology, are compensated by write-leveling.
- In case of LPDDR4 the CA[5:0] bus, needs to be 90 degrees from the CLKP/CLKN signal.
- For DDR3 memory, the memory controller also needs to handle the write leveling required by the interface when the fly-by topology is applied.
- For LPDDR4 memory, the memory controller needs to perform write training to determine tDQS2DQ.
- For LPDDR4 memory, Command-Address Bus Training centers the internal VREFCA in the Command and Address (CA) data eye, and at the same time allows timing adjustments of the CS and CA signals to meet setup/hold requirements.
- For LPDDR4 memory, the memory controller needs include VREF training, read DQS gate leveling and read data eye leveling.

6.2. Features for Memory Interface Implementation

The MachXO5-NX devices contain a variety of features to simplify implementation of the read and write operations of a DDR interface:

- DQS Clock Tree spanning the DQS group
- DDRDLL used to generate the 90-degree delay codes
- DLL-compensated DQS delay elements
- Input FIFO for read data clock domain transfer
- Dedicated DDR Memory input and output registers
- Dynamic Margin Control Circuit to adjust Read and Write delays
- Input/Output Data Delay used to compensate for DQS clock tree delay

6.2.1. DQS Grouping

In DDR interfaces with eight DQ pads associated to one DQS pad, each DQS group generally consists of at least 11 I/O (two DQS, eight DQ, one DM) to implement a complete 8-bit DDR3/DDR3L/LPDDR4 memory interface.

In MachXO5-NX devices, a DQS group consists of 12 I/O, supporting DQS signals on the bottom side of the device.

Each DQS signal has 12 I/O. Any 11 (for DDR3/DDR3L/LPDDR4) of these 12 I/O spanned by the DQS can be used to implement an 8-bit data side interface. For LPDDR4, any group with six I/O is required for CA bus. Another group with five I/O is required to generate the Control and CLKP/CLKN outputs. In addition to the DQS grouping, you must also assign the reference voltage (VREF) input to an I/O in that bank required to implement the referenced I/O standard.

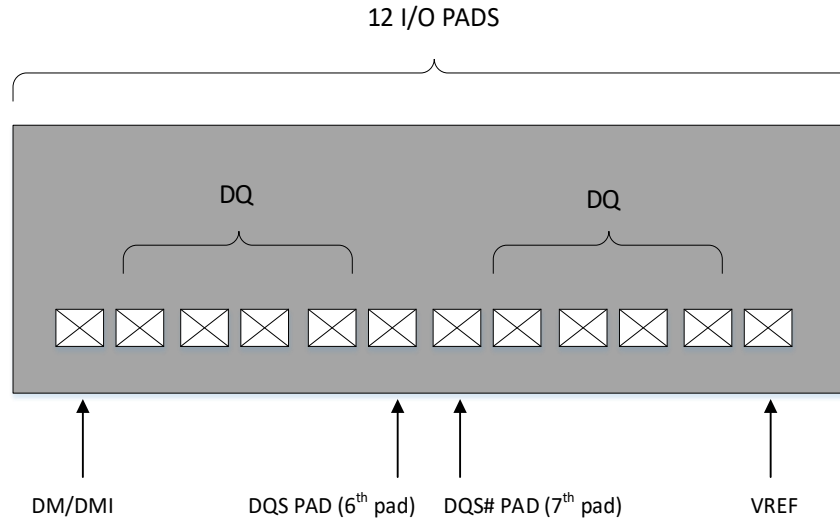


Figure 6.5. DQ-DQS Grouping

Figure 6.5 shows a typical DQ-DQS group for MachXO5-NX devices. The 6th I/O Pad of this 12 I/O group is the dedicated DQS pin. All the five pads before the DQS and six pads after the DQS are covered by this DQS bus span. If a differential DQS pair is required, then the 7th pad is used by the DQS# signal. You can assign any other I/O pad to be DQ data or DM pins. Therefore, for example, to implement a 16-bit wide memory interface, you would need to use two such DQ-DQS groups when eight-to-one DQ-DQS association is used. For BBG256 package there are only 10 I/O in one DQS group, one DQS group only be able implement eight DQ and DQS/DQS#, VREF need implement at another DQS group and data mask function will not support.

In case of LPDDR4, additional DQS groups are required to assign the CA bus and the control signals.

In case of DDR3/DDR3L, additional I/O pads are required to implement address, command, and control. They do not have to be I/O in DQS groups, but need to use 1× gearing generic output DDR capable pads.

Each of the dedicated DQS pins is internally connected to the DQS phase shift circuitry. The pin out sheets included as part of [MachXO5-NX Family Data Sheet \(FPGA-DS-02102\)](#), the MachXO5-NX Pin Information Summary section, shows pin locations for each of the DQS groups.

6.2.2. DLL-Compensated DQS Delay Elements

The DQS to and from the memory is connected to the DQS delay element inside the MachXO5-NX device. The DQS delay block receives the delay control code, DDRDEL, from the on-chip DDRDLL. The code generated by DDRDLL is connected to the DQSBUF circuit to perform 90-degree read phase shift and 90-degree write phase shift. DDRDLL requires the frequency reference from PLL, normally going through the Edge Clock tree.

MachXO5-NX devices support one DDRDLL module in each corner of the device. The DQSBUF modules receive the DDRDEL code from either bottom left or bottom right DDRDLL (Table 6.2). Hence, each side can support up to two different rate DDR memory interfaces.

Table 6.2. DDRDLL Connectivity

DDRDLL Location	Left DQSBUFs	Right DQSBUFs
DDRDLL_BR	—	X
DDRDLL_BL	X	—

The DQS received from the memory is delayed in the DQS delay element in the DQSBUF block, and this delayed DQS is used to clock the first set stage DDR input registers (Figure 6.6).

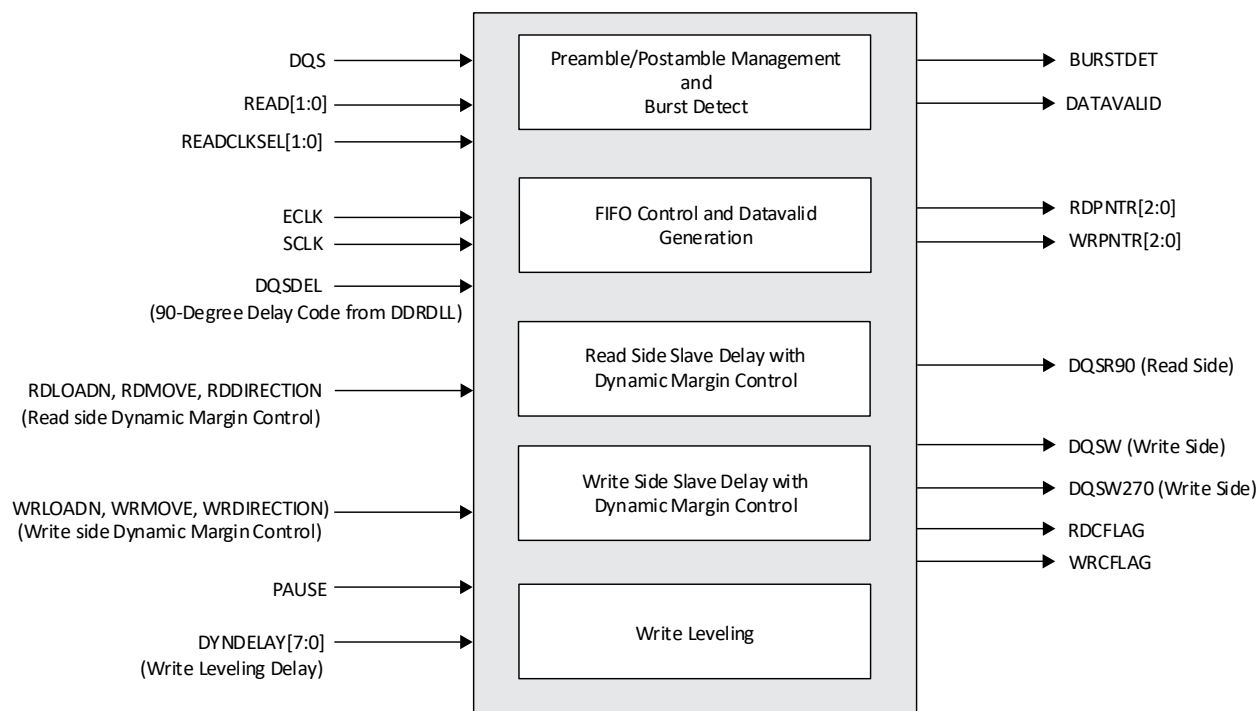


Figure 6.6. DQSBUF Block Functions

6.2.3. Data Valid Module

The DQSBUF block generates a DATAVALID signal. This signal indicates the timing that the IDDR module drives the valid read data transmitting to the FPGA fabric. DATAVALID is a level-sensitive active high signal and indicates that the read data output from the IDDR module is valid while it is asserted high. The DATAVALID signal can stay asserted during the IDDR module outputs back-to-back valid read data until all consecutive read operations are completed.

6.2.4. READ Pulse Positioning Optimization

The memory controller is required to provide the READ1/0 signal to the DQSBUF block to position the internal READ pulse, and generate the DATAVALID output that indicates the proper timing window of the valid read data. The internal READ pulse is also used to get a clean internal DQS signal between the preamble and postamble periods. The clean DQS is 90-degree shifted internally to be used to capture the read data.

Due to the DQS round trip delay that includes PCB routing and I/O pad delays, proper positioning of the READ pulse is crucial for successful read operations. The MachXO5-NX device DQSBUF block provides the dynamic READ pulse positioning function, which allows the memory controller to locate the READ pulse to an appropriate timing window for the read operations by monitoring the positioning result.

The READCLKSEL2/1/0 and BURSTDET signals are used to accomplish the READ pulse positioning function for a corresponding DQSBUF block. The READ1/0, READCLKSEL2/1/0 signals are driven by the user logic and are part of the DDR memory controller.

The READ1/0 signal needs to be asserted high a certain amount of time before the read preamble starts. The suggested READ1/0 signal assertion timing and the required duration of assertion are listed in [Table 6.3](#). When the internal READ pulse is properly positioned, BURSTDET is asserted high and guarantee that the generated DATAVALID signal properly indicates the valid read data time window. The READ1/0 signal must stay asserted as long as the number of SCLK cycles that is equal to one fourth of the total burst length as listed in [Table 6.3](#).

Table 6.3. DDRDLL Connectivity

Gearing Mode	READ Control	DQSBUF Block	Initial READ Assertion Position ¹	READ Width in SCLK
X2 Gearing (All DDR Memory Interfaces)	READ1 READ0 READCLKSEL2 READCLKSEL1 READCLKSELO	DQSBUFM	At least 5.5T before preamble	Total Burst Length/4

Note:

1. Subject to change after validation tests. The number shown does not include DQS round trip delay.

1T = 1 tCK memory clock cycle

Once the controller initially positions the internal READ pulse using the READ1/0 and READCLKSEL2/1/0 signals, BURSTDET can be used to monitor the positioning result to optimize the READ pulse position. The BURSTDET signal provides a feedback mechanism to inform the memory controller whether the READ pulse has reached the optimal position for the read operations or not with the current READ1/0 and READCLKSEL2/1/0 values. When it reaches the optimal position, BURSTDET is asserted High after a read operation. Otherwise, BURSTDET remains Low. A minimum burst length of eight on the memory bus must be used in the training process. This can be done either with two consecutive BL4 (BL=4) read accesses or one BL8 read access. Any even number of BL4, or any multiplication of BL8 (BL=8) can also be used. This read pulse training process must be performed during the initial training and can also be periodically calibrated during normal operations.

The BURSTDET signal is asserted after the last DQS transition is completed during a read operation and lasts until the next read cycle is started. Once a read operation is started, the memory controller should wait until the DATAVALID signal from DQSBUFM is asserted and then sample the BURSTDET signal at the next cycle to monitor the READ pulse positioning result. If there is no assertion on BURSTDET, it means that the READ pulse has not been located to the optimal position yet. Then, the memory controller needs to shift the READ1/0 signal and/or increase the READCLKSEL2/1/0 value until it detects a BURSTDET assertion. It is recommended that at least 128 read operations be performed repetitively at a READ pulse position during the initialization for getting jitter immunity. 16 read operations can be performed in a periodic calibration if used during the normal operation. The memory controller can determine the proper position alignment when there is no failure on BURSTDET assertions during these multiple trials.

To reposition the internal READ pulse:

1. The memory controller sets READ1/0 to an initial position before starting the read pulse training. READ1/0 must be asserted for the number of SCLK cycles that is equal to one-fourth of the current read burst length, as listed in [Table 6.3](#). Each READ bit (READ1 or READ0) in the system clock domain is translated to a 1T time slot of the memory clock domain, as shown in [Figure 6.7](#).
2. Once READ1/0 positions the READ pulse, READCLKSEL2/1/0 can be used to shift the READ pulse by 1/4T per step. With the total eight possible combinations from 000 to 111, READCLKSEL2/1/0 covers the READ pulse shift up to a whole 2T timing window. If BURSTDET is asserted with a certain READCLKSEL2/1/0 value, it indicates that the READ pulse has been located to the optimal position. If no BURSTDET is asserted during this step, the READ pulse needs to be moved to the next timing window.
3. To shift the READ pulse timing window, READ1/0 can be moved to the next cycle. If a READ bit is asserted in the next cycle while the other READ bit remains in the current cycle, only the corresponding time slot on the READ pulse moves to the next allotted slot. Therefore, only READ0 must be moved to the next cycle, if the READ pulse needs to be shifted only by 1T. However, if only READ1 is moved to the next SCLK cycle, then the READ pulse gets two short pulses in wrong timing. Since READCLKSEL2/1/0 covers a whole 2T timing, it is recommended that both READ1 and READ0 be moved to the next cycle together to shift the READ pulse to the next 2T window as the example shown in [Figure 6.7](#).

Repeat *steps 2 and step 3* until BURSTDET is asserted.

[Figure 6.7](#) shows an example of a burst length 8 (BL8) read operation. The bottom side of the diagram indicates the case that the incoming DQS (DQSI) gets slightly more than 2T delay after a round trip. Due to this round trip delay, both READ1 and READ0 need to be shifted to the next SCLK cycle so that the internal READ pulse gets a 2T shift. Then, the READCLKSEL2/1/0 signals can be used to fine-tune the READ signal position throughout the training process. When any of READCLKSEL2/1/0 is changed at any time after a system reset, the PAUSE input to DQSBUFM must be asserted before 4T of the change and remain asserted for another 4T after the change to avoid glitches and malfunction.

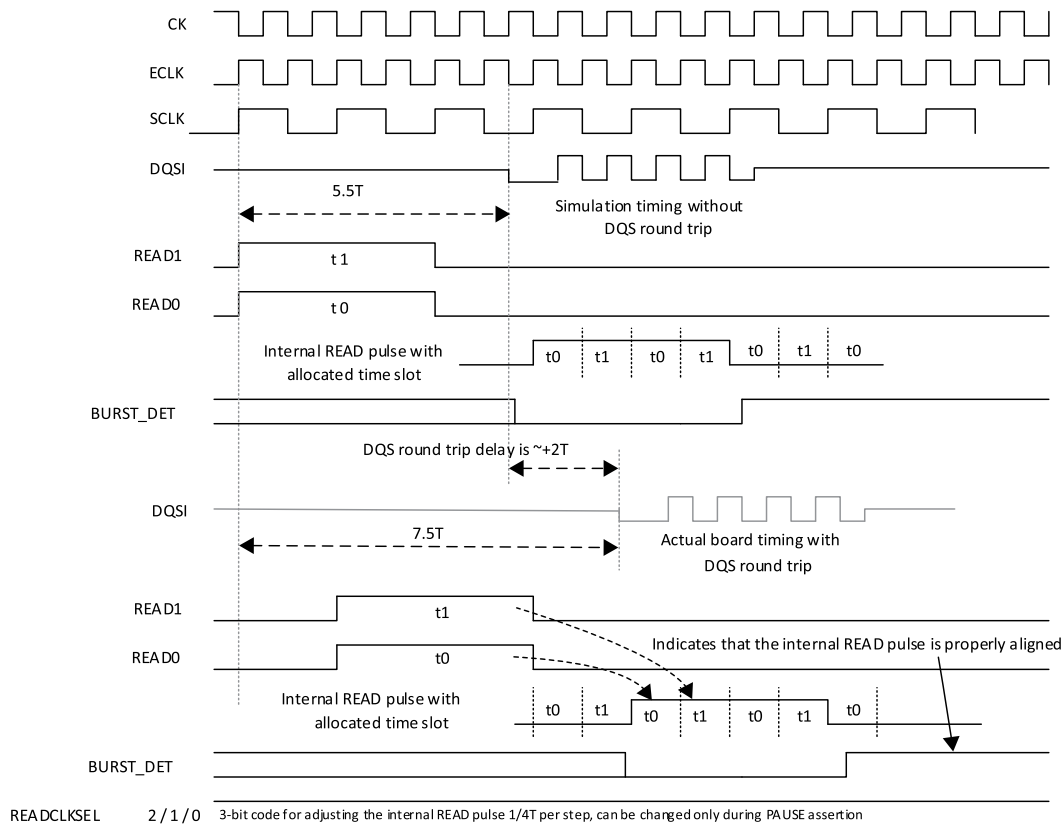


Figure 6.7. READ Signal Training Process

Note that the DYNDELAY[7:0] signal, margin control signals (WR/RDMOVE, WR/RDLOADN), and DDRDLL update signal (UDDCNTLN) also have the same PAUSE requirement.

6.2.5. Dynamic Margin Control on DQSBUF

The MachXO5-NX device family includes dynamic margin control signals in the DQSBUF module allowing you to dynamically adjust the read or write side DQS delays generated in the DDRDLL.

Once the margin control mode is enabled by de-asserting WRLOADN (=1) or RDLOADN (=1), the DQSBUF phase shift control for making a center-aligned interface is no longer controlled by the DDRDLL component. You must complete the margin control training to maximize the valid window and then continuously monitor the DDRDLL delay code (DCNTL7~DCNTL0) and controls the DQSBUF delays accordingly using the WR/RDMOVE and WR/RDDIRECTION signals to compensate the PVT variations.

6.2.6. Read Data Clock Domain Transfer Using Input FIFO

Each IDDR module in the MachXO5-NX device has a dedicated input FIFO to provide a safe clock domain transfer from the DQS domain to the ECLK or SCLK domain. The input FIFO is eight-level deep with three-bit write and read pointers. It transfers the read data from the non-continuous DQS domain to the continuous ECLK. The FIFO is written by the DQS strobe and read back by ECLK, which has the identical frequency rate as DQS.

The input FIFO also performs the read leveling function. When each DQS strobe signal and its associated DQ data signals arrive at slightly different times with others to the FPGA, the input FIFO allows the skewed read data to be captured and transferred properly.

Each DQS group has one FIFO control in the DQSBUF block. It distributes the FIFO read/write pointers, WRPNTR [2:0] and RDPNTR [2:0], to each memory IDDR module in the same DQS group. Safe domain crossing between ECLK and SCLK is guaranteed by the MachXO5-NX device hardware design.

6.2.7. DDR Input and Output Registers (IDDR/ODDR)

MachXO5-NX devices provide dedicated input DDR (IDDR) and output DDR (ODDR) functions supporting 4:1(x2) and 8:1(x4) gearing modes that are used to implement the DDR memory functions. The input DDR (IDDR) and output DDR (ODDR) automatically handle the transfer of data from ECLK domain to the SCLK (FPGA clock) domain.

6.3. Memory Interface Implementation

The following sections explain the DDR3/DDR3L and LPDDR4 memory interfaces implementation using the x2 gearing mode. MachXO5-NX devices support these memory interfaces generation through the IP Catalog tool. IP Catalog generates one module that includes the Read and Write side implementation, as shown below.

All the memory interfaces use DQS clock, one ECLK, and one SCLK to implement the read and write side operations. ECLK must always be routed on the Edge Clock tree and SCLK on the primary clock tree.

6.3.1. Read Implementation

The read side implementation is shown in Figure 6.8.

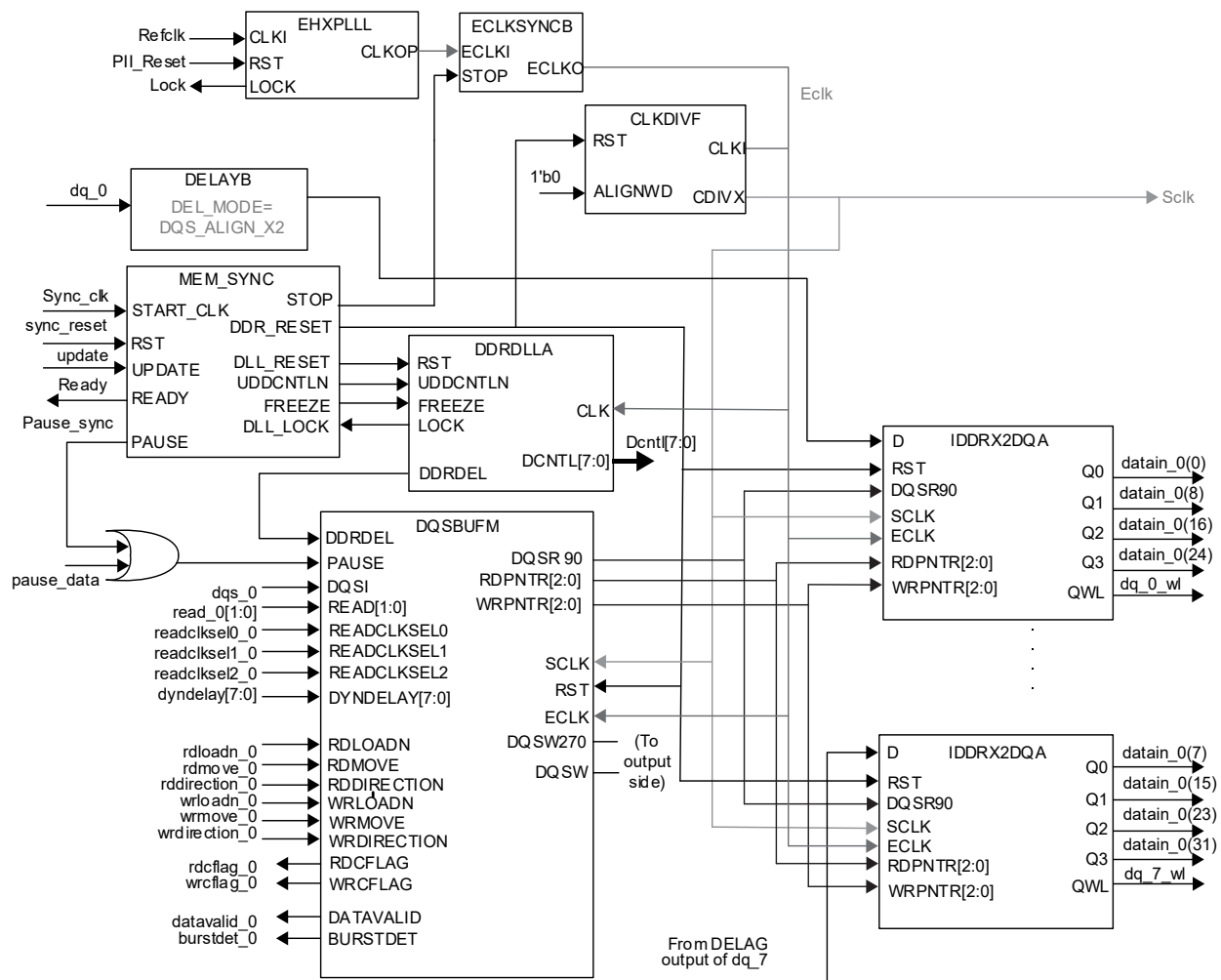


Figure 6.8. DDR3/DDR3L and LPDDR4 Read Side Implementation

The read side is implemented using the following software elements.

- DDRX2DQA element is used to capture data.
- DDRDLLA is used to generate the delay code for DQSBUFM to get the 90-degree phase shift on the DQS input (DQSR90).
- The incoming DQS clock (DQSI) is routed through the DQSBUFM module to the DQS clock tree.
- The DQSBUFM receives the delay code from DDRDLLA and generates the delayed DQS signal to IDDRX2DQA.
- The DQSBUFM is used to generate the Read and Write pointers that are used to transfer data from the DQS to ECLK inside the IDDRX2DQA module.
- Read 1, 0, and Readclkssel_2, 1, 0 signals of DQSBUFM are used by the user logic to obtain the optimal READ pulse position and driven by the user logic to generate a clean DQS output signal based on the trained READ pulse with respect to preamble and postamble.
- The dynamic delay control ports are available on the DQSBUFM module when you select the *enable dynamic margin control* option.
- DYNDELAY[7:0] of DQSBUFM is used to perform write leveling. If write leveling is not used, it is connected to 0.
- Port QWL of IDDRX2DQA is used for DDR3/DDR3L/LPDDR4 to support write leveling. It is used to deliver the write leveling monitor signals from the memory device to the FPGA user logic.
- MEM_SYNC soft IP must always be included in the interface. It is required to avoid issues on DDR memory bus and update code in operation without interrupting interface operation. When a DDR memory interface IP is generated from IP Catalog, the MEM_SYNC soft IP block is also generated and included.
- The Pause_sync output of the MEM_SYNC soft IP is used to request DQSBUFM pause for the DDRDLL update and goes to an output port of the IP Catalog module. The input port Pause_data goes to DQSBUFM. It is required by user logic, to OR the Pause_sync output of the MEM_SYNC module with the user pause to drive the Pause_data input of the DQSBUFM. This OR would need to be implemented outside of the IP Catalog module in your design.
- CLKDIVF set to divide by 2 function is used to generate the SCLK from the ECLK.

6.3.2. Write Implementation (DQ, DQS, and DM)

Figure 6.9 and Figure 6.10 show the DDR3/DDR3L and LPDDR4 memory interface write side implementation to generate DQ, DQS, and DM outputs.

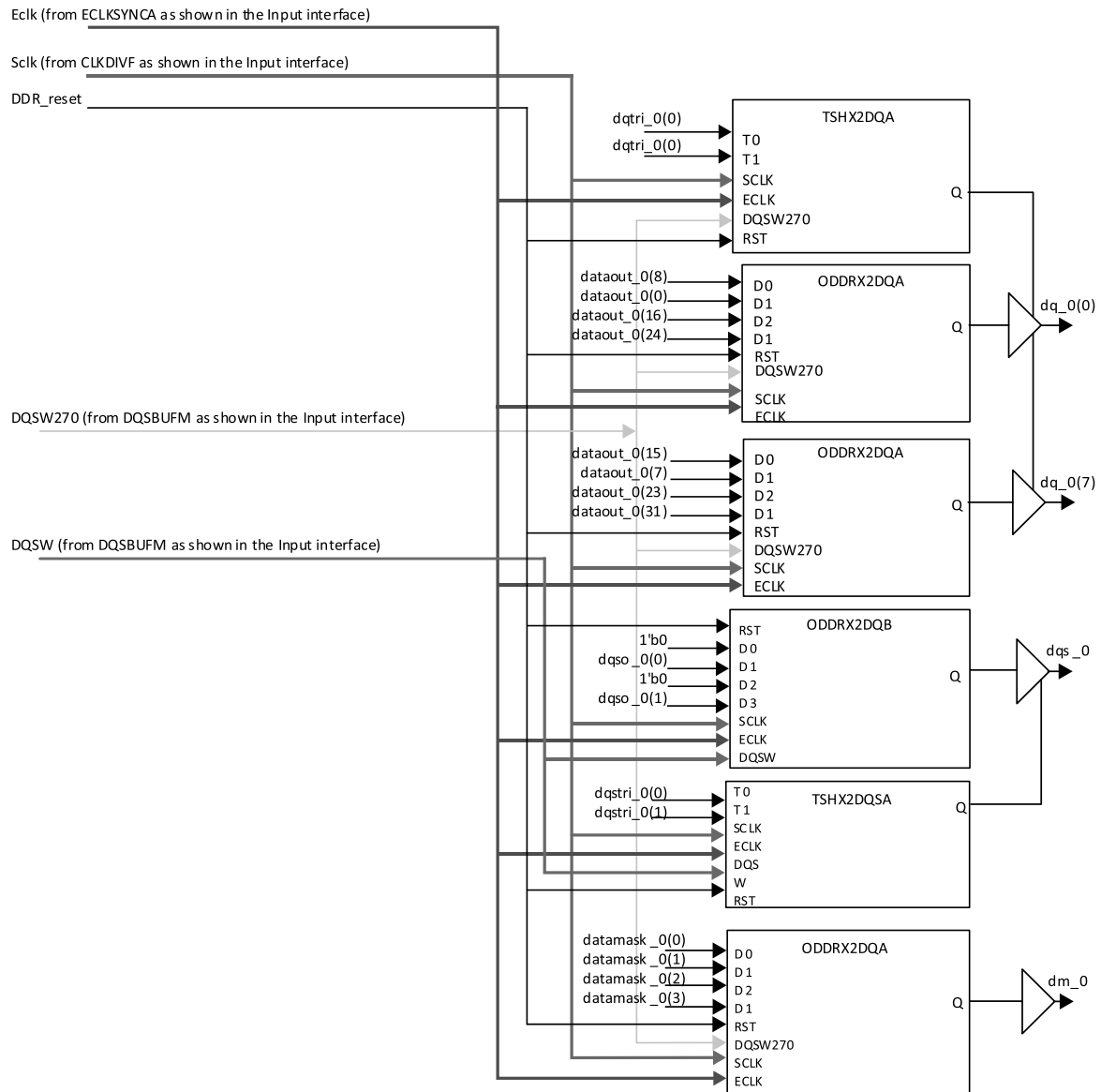


Figure 6.9. DDR3/DDR3L Write Side (DQ, DQS, and DM)

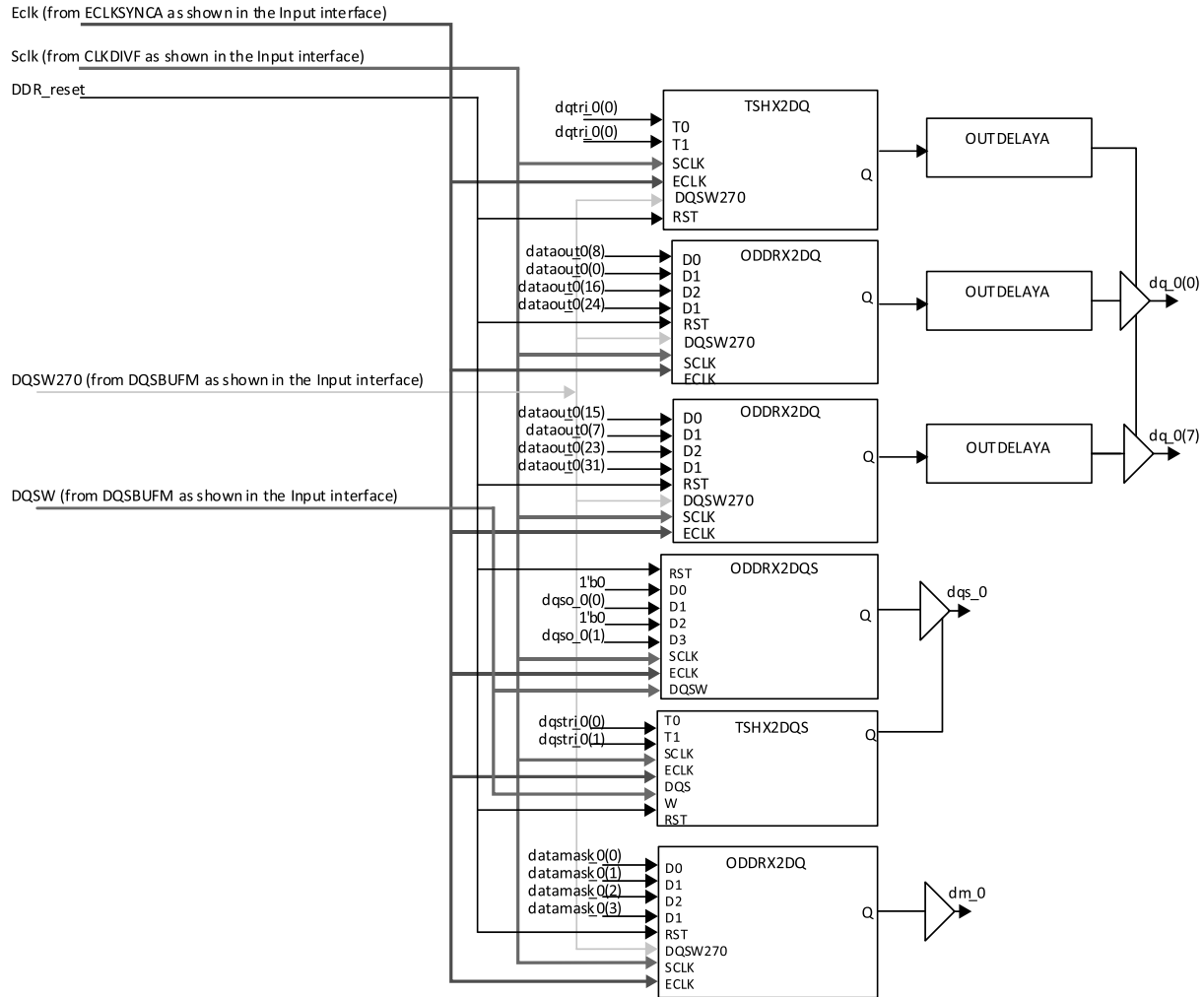


Figure 6.10 LPDDR4 Write Side (DQ, DQS, and DM)

This interface uses the following modules:

- ODDR2DQA to generate the data DQ and DM signals. TSHX2DQA is used to generate the tri-state control for the DQ output.
- ODDR2DQSB to generate DQS output. TSHX2DQSA is used to generate the DQS tri-state control.
- DQSW270, the 270-degree delayed DQS signal, is used to generate the DQ and DM outputs.
- DQSW, 90 degrees shifted from the DQSW270, is used to generate DQS output.
- The DQSW270 and DQSW clocks are generated in the DQSBUFM module, as shown on the Read side Implementation figure (Figure 6.8).
- When write leveling is enabled, the dynamic delay for write leveling (DYNDelay[7:0]) is applied to both DQSW and DQSW270 so that the DQ and DQS phase relationship is maintained.
- ECLK and SCLK are used inside the ODDR2 module before data is transferred to the DQSW270 and DQSW clocks. The ECLK is generated by the EHXPLL module and the SCLK is generated by the CLKDIVF module, both shown in the Read side implementation.
- One tri-state is shown in Figure 6.9. The software generates one tri-state element for each DQ port.

6.3.3. Write Implementation (DDR3/DDR3L Address, Command, and Clock)

DDR3 and DDR3L write side interface side to generate the Clock, Address and Command using the following modules:

- ODDRX2F with inputs tied to constants to generate the DDRCLK output.
- The ADDR, BA, CASN, RASN, WEN, CKE, and ODT command and address signals are generated using the ODDRX1F. CSN output is generated using OSHX2A.
- Both ECLK and SCLK are used in these elements. These ECLK and SCLK elements are the same as those generated in the Read side.

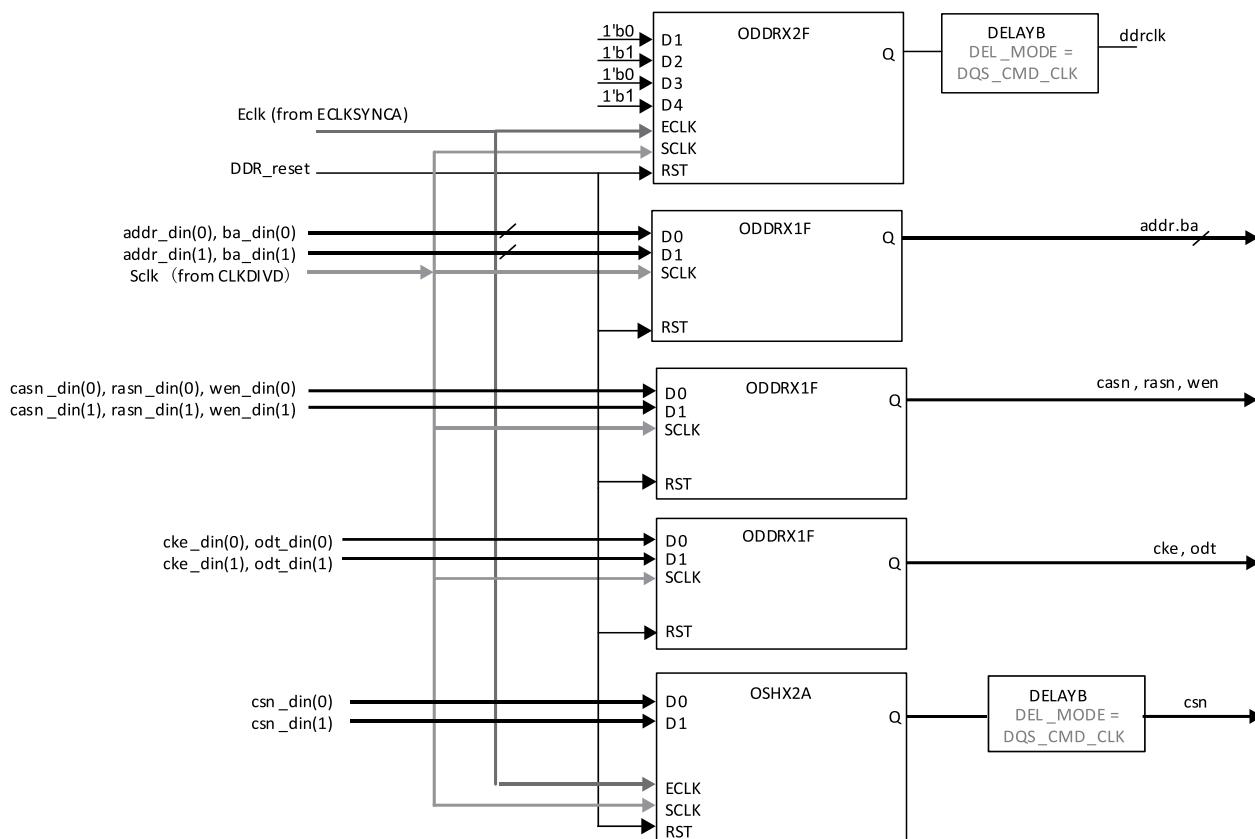


Figure 6.11. DDR3/DDR3L Address, Command, and Clock Generation

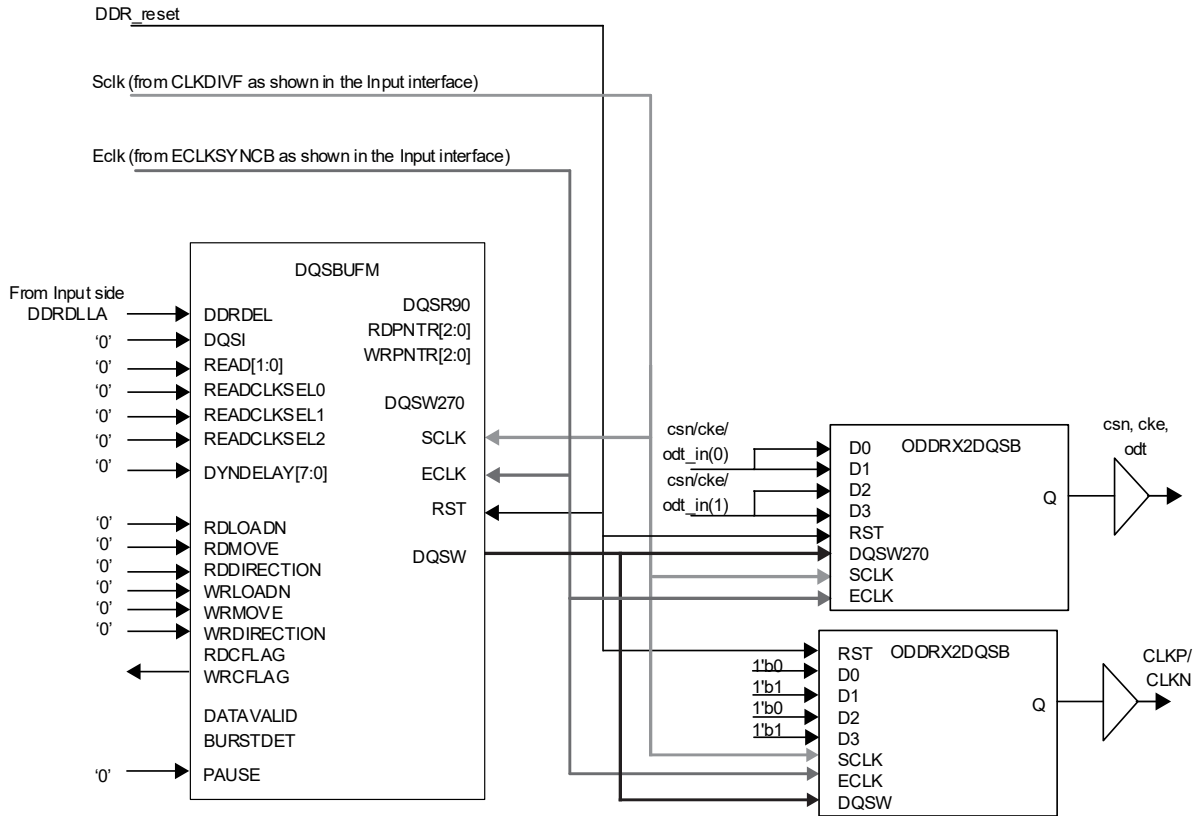


Figure 6.13. LPDDR4 Output for CSN, CKE, and CLOCK Generation

6.4. DDR Memory Interface Design Rules and Guidelines

Listed below are some rules and guidelines to keep in mind when implementing DDR memory interfaces in MachXO5-NX devices. MachXO5-NX devices have dedicated DQS banks with the associated DQ pads.

- DDRDLLA primitive should be instantiated for all DDR memory interfaces. Each DDRDLLA generates 90-degree digital delay code for all the connected DQS delay blocks based on the reference clock input to the DDRDLLA. Therefore, all the DDR memory interfaces under the same DDRDLLA coverage must run at the same frequency.
- There are two DDRDLLs on each device, one DDRDLL in each bottom corner of the device. Each DQSBUF module can receive delay codes from either of the DDRDLLs in bottom corner of the device.
- When a DDR memory interface is added to the side where another DDR memory interface is running at a different frequency, another available DDRDLLA for the side must be instantiated and used for the new interface.
- The reference clock input to the PLL used in the DDR memory interface implementation must be located to the dedicated PLL pin or a PCLK pin. The dedicated PLL input pin is preferred due to less skew.
- Each DDR memory interface must use its corresponding I/O standard.
 - For the DDR3 memory interface, these signals should be connected to the SSTL15 standards.
 - For the DDR3L memory interface, these signals should be connected to the SSTL135 standards.
 - For the LPDDR4 memory interface, the interface signal should use the LVSTL11 standard.
 - DDR3/DDR3L and LPDDR4 memory interfaces also require differential DQS signals.

Table 6.4 shows the IO_TYPE setup for each of the DDR memory interfaces.

Table 6.4. I/O Standards for DDR Memory

	DDR3	DDR3L	LPDDR4
DQ	SSTL15_I, SSTL15_II	SSTL135_I, SSTL135_II	LVSTL11
DQS	SSTL15D_I, SSTL15D_II	SSTL135D_I, SSTL135D_II	LVSTL11D
Cmd/Addr	SSTL15_I, SSTL15_II	SSTL135_I, SSTL135_II	LVSTL11
CK	SSTL15D_I, SSTL15D_II	SSTL135D_I, SSTL135D_II	LVSTL11D

Note: When implementing the DDR interface, the VREF1 of the bank is used to provide the reference voltage for the interface pins.

6.5. DDR3 Memory Interface Termination Guidelines

Proper termination of a DDR memory interface is an important part of implementation that ensures reliable data transactions at high-speed. Below is the general termination guideline for the MachXO5-NX device DDR memory interface.

6.5.1. Termination for DQ, DQS, and DM

- Do not locate any termination on the memory side. The memory side termination on DQ, DQS, and DM is dynamically controlled by the DDR3 SDRAM ODT function.
- Do not locate any termination on the FPGA side. The MachXO5-NX device has internal termination on DQ and DQS, which is dynamically controlled. Use the TERMINATION preference for DQ and DQS pads to enable the internal parallel termination to VCCIO/2. The TERMINATION preference has the OFF, 50 Ω , 60 Ω , and 75 Ω options.

6.5.2. Termination for CK

DDR memory clocks require differential termination because they use a differential signaling. Use SSTL15D in DDR3 to drive the clock signals. You can locate an effective 100 Ω termination resistance on the memory side to achieve the differential termination using one of the following guidelines:

- Locate a 100 Ω resistor between the positive and negative clock signal.
- Connect one end of an Rtt resistor to the positive pin and one end of another Rtt to the negative pin of a CK pair, then connect the other ends of two Rtt resistors together and return to VDD or GND through a Ctt capacitance. Note that the JEDEC CK termination scheme defined in the DIMM specifications uses 36- Ω for Rtt with 0.1 μ F Ctt for DIMM for DDR3 DIMMs returning to VDD. 50 Ω Rtt can also be used for non-DIMM applications.

Note: Use of series termination resistors at the FPGA side is not recommended. When fly-by wiring is used in DDR3, the CK termination resistor should be located after the last DDR3 SDRAM device.

6.5.3. Termination for Address, Commands, and Controls

- Parallel termination to VTT on address, command, and control lines is typically required at the DDR3/DDR3L memory side.
- Locate a 50 Ω parallel-to-VTT resistor, or a best known resistance obtained from your SI simulation, to each address, command, and control line on the memory side.
- Series termination resistors can be optionally used on the address, command, and control signals to suppress overshoot/undershoot and to help decrease overall SSO noise level. 22 Ω or 15 Ω series termination is recommended when used.
- When fly-by wiring is used in DDR3, the address, command, and control termination resistors should be located after the last DDR3 SDRAM device.

No termination is required on the LPDDR4 CA bus and control lines. They use point-to-point connections.

6.5.4. Termination for DDR3/DDR3L DIMM

The DDR3 DIMMs incorporate internal termination following the requirements defined by the JEDEC DIMM specification. For this reason, the user termination requirement for the DDR3 DIMM is slightly different from that of DDR3 SDRAM devices:

- Do not locate any termination on the memory side. The memory side termination on DQ, DQS, and DM is dynamically controlled by the DDR3 SDRAM ODT function.
- Do not locate differential termination on CK at the memory side because the DIMM already has termination on the module.
- Do not locate parallel termination to VTT on address, command, and control signals at the memory side because the DIMM already has termination on the module.
- Follow the termination for DQ, DQS, and DM guidelines above for the FPGA side termination.

6.6. DDR Memory Interface Pinout Guidelines

The MachXO5-NX device contains dedicated I/O functions for supporting DDR memory interfaces. The following pinout rules must be followed to properly use the dedicated I/O functions.

- The DQS-DQ association rule must be followed.
- All associated DQs to a DQS must be in the same DQS group.
- A data mask (DM) must be part of the corresponding DQS group.
Example: DM[0] must be in the DQS-12 group that has DQ[7:0], DQS[0].
- A DQS pad must be allocated to a dedicated DQS True (+) pad.
- A DQS# pad is auto-placed when a differential SSTL type (SSTL15D in DDR3, SSTL135D in DDR3L, LVSTL11 in LPDDR4) is selected.
- Do not assign any signal to a DQS# pad if used as differential strobe. The software automatically places DQS# when a differential I/O type is applied.
- DQS signal must use the DQS/DQS# pads only.
- Data group signals (DQ, DQS, DM) can use only bottom side of the MachXO5-NX device, and they keep the DQS-DQ association rule.
- It is recommended that the CK/CK# outputs be located on the same side where the DQ and DQS pads are located to minimize the skew.
- Place the address, command, and control signals either on the same side as where the DQ and DQS pads are located, or on the top side for DDR3/DDR3L memory interfaces.
- In DDR3 interface, the RST# can be located anywhere an output is available as long as the same I/O Standard as the memory interface is applicable.
- The input reference clock to the PLL must be assigned to use dedicated clock routing. The dedicated PLL input pads are recommended while PCLK inputs can also be used.
- VREF1 of the bank where the DQ, DQS, and DM pads are located must be available to be used as a reference voltage input.
 - Do not assign an I/O signal to VREF1 in the preference file. VREF1 for the bank has to be available for the DDR memory interface.
 - Unused VREF1 can be taken as a general purpose I/O in the bank where no DQ/DQS pad is located.

6.7. Pin Placement Considerations for Improved Noise Immunity

In addition to the general pinout guidelines, you need to pay attention to additional pinout considerations to minimize simultaneous switching noise (SSN) impact. The following considerations are generally necessary to control SSN within the required level:

- Properly terminated interface
- SSN optimized PCB layout
- SSN considered I/O pad assignment
- Use of pseudo power pads

The guidelines listed below address the I/O pad assignment and pseudo power pad usage. Unlike the pinout guidelines, they are not absolute requirements. However, it is recommended that the pin placement follow the guidelines as much as possible to increase the SSO/SSI immunity.

- Place the DQS groups for data implementation starting from the middle of the right or left edge of the MachXO5-NX device. Allow a corner DQS group to be used as a data group only when necessary to implement the required width.
- Locate a spacer DQS group between the data DQS groups, if possible. A DQS group becomes a spacer DQS group if the I/O pads inside the group are not used as data pads, DQ, DQS, or DM.
 - In DDR3/DDR3L, the pads in a spacer group can be used for address, command, control, or CK pads as well as for user logic or the pseudo power pads.
 - Avoid more than two data DQS groups being consecutively placed can provide better noise immunity. If more data DQS groups need to be placed consecutively, use the pseudo power pads as many as possible to isolate each DQS group more effectively from others.
- It is recommended that you locate a few pseudo VCCIO/ground (GND) pads inside a spacer DQS group and at least one pseudo VCCIO in the data DQS group. An I/O pad becomes a pseudo power pad when it is configured to OUTPUT with its maximum driving strength. The maximum driving strength is SSTL15, 10 mA for DDR3. And the I/O pad is connected to the external VCCIO or ground power source on the PCB.
 - Your design needs to drive the pseudo power I/O pads according to the external connection. You assign them as OUTPUT and let your design drive 1 for pseudo VCCIO pads and 0 for pseudo GND pads in your RTL coding.
 - Locating two to four pseudo power pads in a spacer DQS group should be sufficient to provide suppressing the SSN impact.
 - Locate a pseudo power pad in a location where it can provide the best balanced and isolated separation.
- You may have one or more remaining pads in a data DQS group, which are not assigned as a data pad in a DDR memory interface. Assign them to pseudo VCCIO or pseudo GND. Preferred location is in the middle of the group, right next to a DQS pad pair, if the DQS group is isolated by a spacer DQS group. If consecutively placed, locating the pseudo power pads to the edge of the group may be more effective. Note that you may not have this extra pad if the DQS group has 12 pins only and includes a VREF pad for the bank.

The additional guidelines below are not as effective as the ones listed above. However, following them is still recommended to improve the SSN immunity further:

- Assign the data mask (DM) pad in a data DQS group close to the other side of DQS pads where a pseudo power pad is located. If the data DQS group includes VREF1, locate DM to the other side of VREF with respect to DQS. It can be used as an isolator due to its almost static nature in most applications.
- Other DQS groups, neither data nor spacer groups, can be used for accommodating DDR memory interface address, command, control, and clock pads.
- You can assign more unused I/O pads to pseudo power, if you want to increase the SSN immunity. Note that the SSN immunity does not get increased at the same rate as the increased number of pseudo power pads. The first few pseudo power pad placements described above are more crucial. Keep the total pseudo power pad ratio, VCCIO versus GND, between 2:1 to 3:1.
- It is a good idea to shield the VREF pad by locating pseudo power pads around it if extra pins are available in the bank where the VREF1 pad is not located.

7. Using IP Catalog to Build and Plan High-Speed DDR Interfaces

The IP Catalog tool is used to configure, build, and plan placement all DDR interfaces.

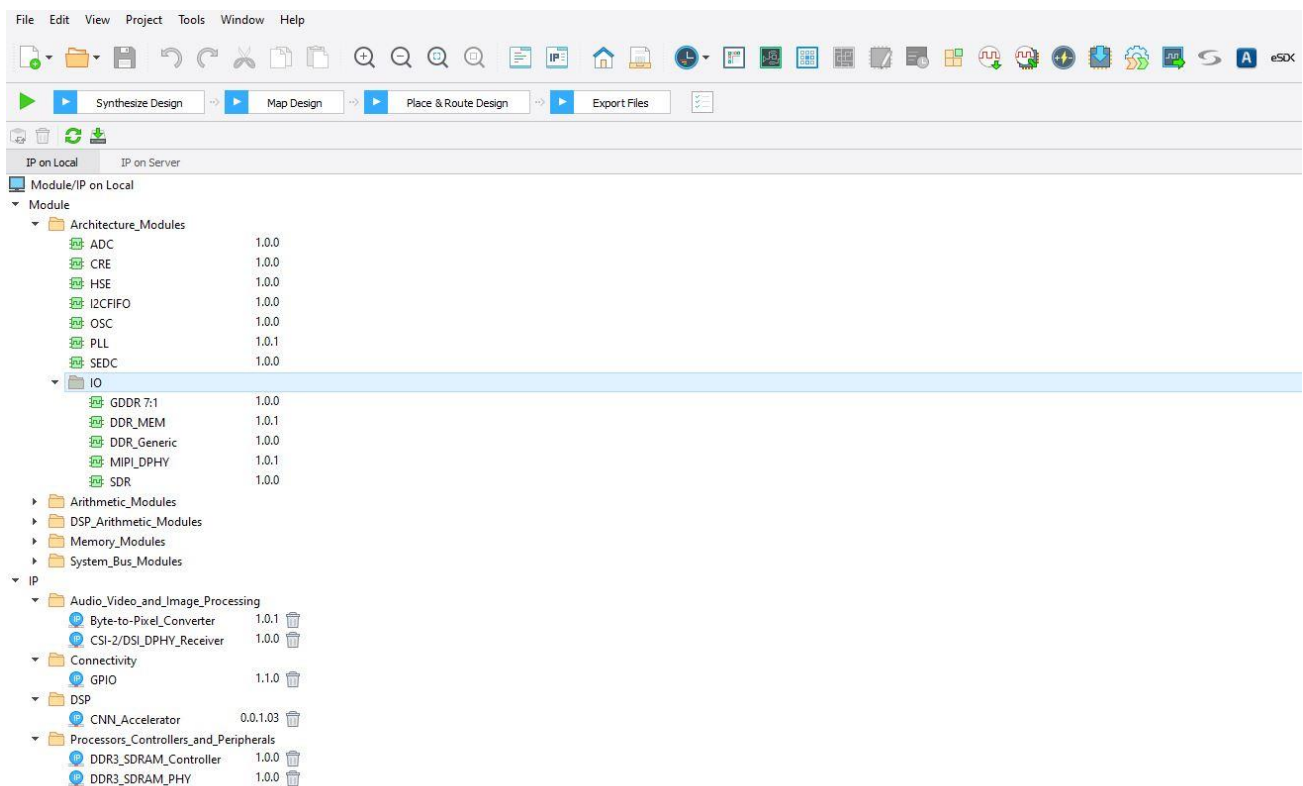


Figure 7.1. IP Catalog Main Window

Note: It is recommended that all the DDR modules required for the current design be generated in the same project. This allows the Design Rule Check and the Resource Conflict Check for all the modules at the same time.

7.1. Configuring DDR Modules in IP Catalog

IP Catalog lists all the DDR architecture modules available on MachXO5-NX devices.

All the DDR modules are located under Architecture Modules – I/O. This includes:

- SDR – Select to build SDR Modules.
- DDR_GENERIC – Select to build any DDR Generic Receive and Transmit Interfaces.
- GDDR_7:1 – Select to build 7:1 LVDS Receiver and Transmit Interface.
- DDR_MEM – Select to build DDR Memory Interfaces.
- MIPI_DPHY – Select to build MIPI D-PHY Receiver and Transmit Interface

To see the detailed block diagram for each interface generated by IP Catalog, see the [High-Speed DDR Interface Details](#) section.

7.2. Configuring SDR Modules

To build an SDR interface, select SDR option under Architecture Modules – I/O in the IP Catalog tab. Enter the name of the module. [Figure 7.2](#) shows the type of interface selected as SDR and the module name entered. This module can then be configured by clicking the Next button.

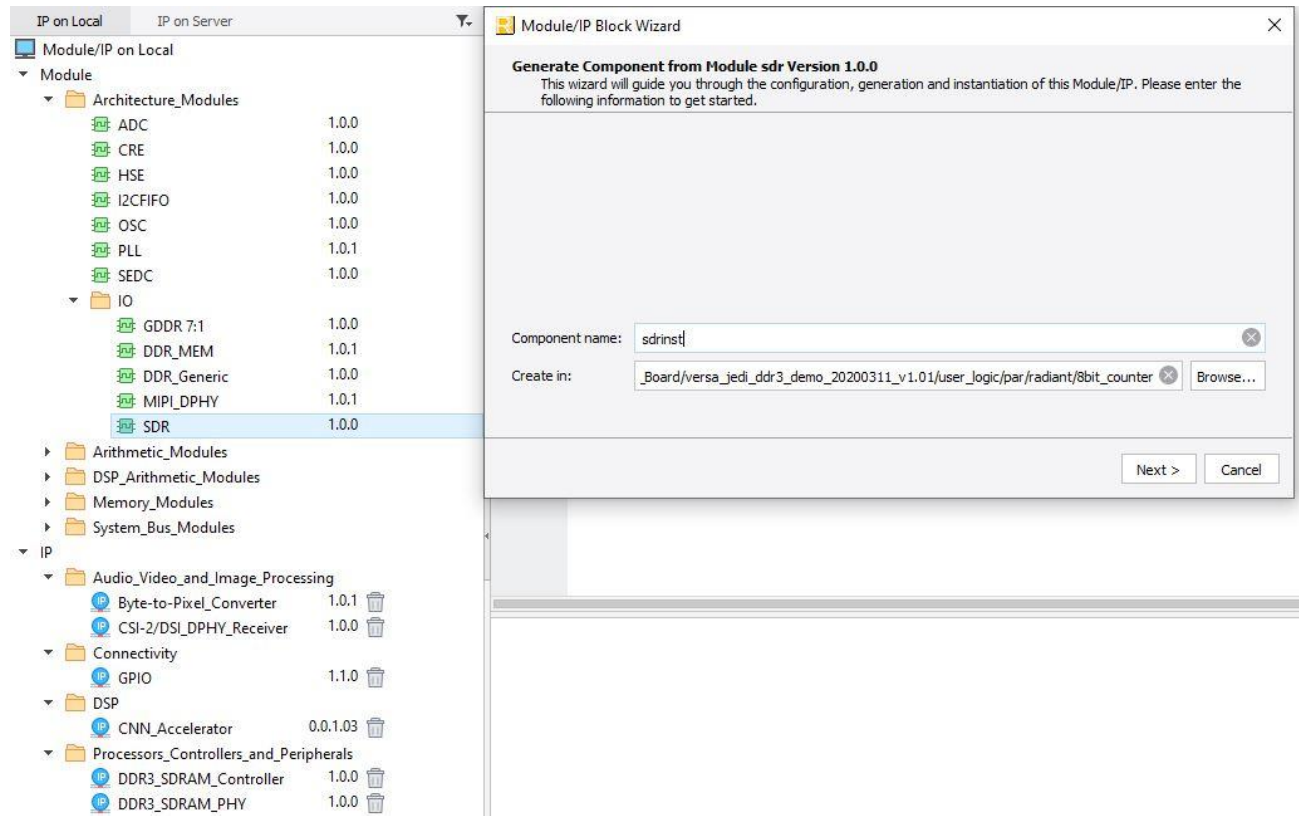


Figure 7.2. SDR Option Selected in the IP Catalog Tab

Figure 7.3 shows the Configuration tab for SDR module. You can make selections and then click Generate.

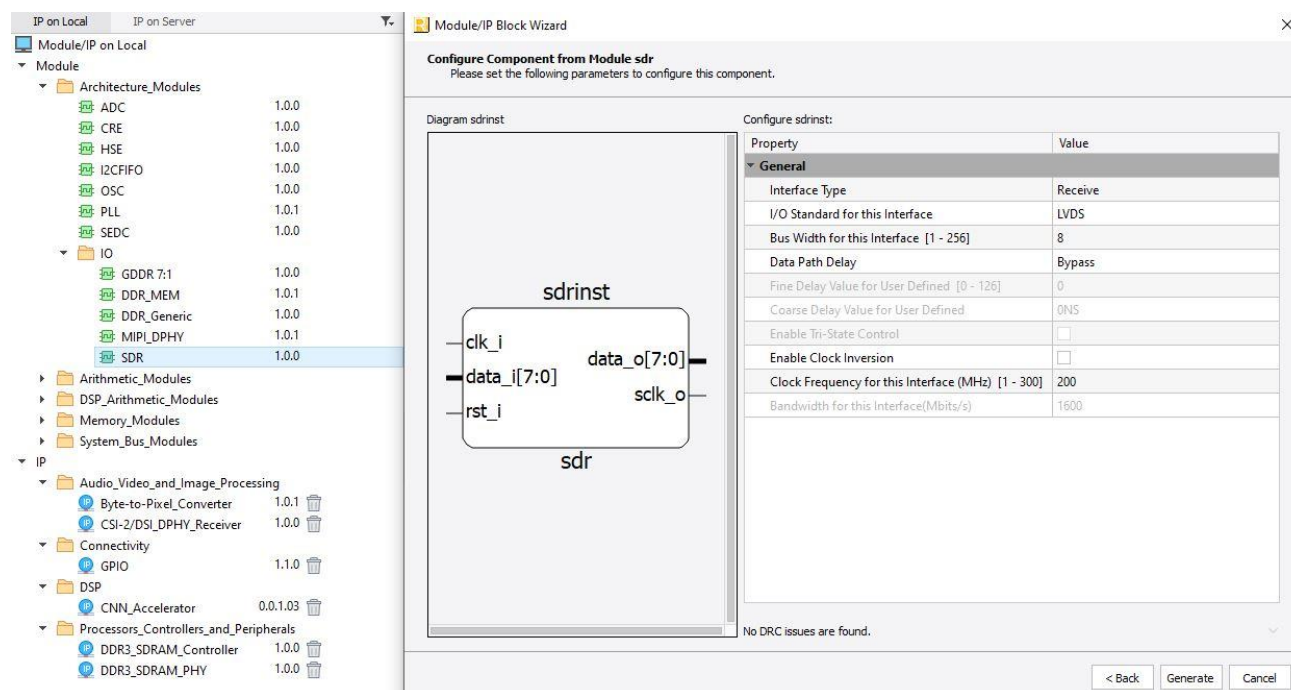


Figure 7.3. SDR Configuration Tab

Table 7.1 explains the various configurations options available for SDR modules.

Table 7.1. EBR-Based Single-Port Memory Port Definitions

User Interface Option	Description	Values	Default
Interface Type	Type of Interface (Transmit or Receive)	Transmit, Receive	Receive
I/O Standard for this Interface	I/O Standard to be used for the interface	All Valid IO_TYPES	LVDS
Bus Width for this Interface	Bus size for the interface	1 – 256	8
Clock Frequency for this Interface (MHz)	Interface Speed	1 – 300	200
Bandwidth (Calculated) (Mbps)	This is the calculated from the Clock frequency entered.	(Calculated)	(Calculated)
Interface	Interface selected based on previous entries	Transmit: GOREG_TX.SCLK Receive: GIREG_RX.SCLK (default)	GIREG_RX.SCLK
Data Path Delay ¹	Data input can be optionally delayed using the DELAY block.	If Interface Type = Receive then: Bypass, Static Default Dynamic Default Static User Defined Dynamic User Defined If Interface Type = Transmit then: Bypass, Static User Defined Dynamic User Defined	Bypass
Fine Delay Value for User Defined	If Delay type selected above is <i>user defined</i> , delay values can be entered with this parameter.	0 to 126	0
Coarse Delay Value for User Defined	If Delay type selected above is <i>user defined</i> , delay values can be entered with this parameter.	0ns, 0.8ns, 1.6ns	0ns
Enable Tri-State Control	If Delay type selected above is <i>user defined</i> .	Disable, Enable	Disable
Enable Clock Inversion	Option to invert the clock input to I/O Register.	Disable, Enable	Disable

Note:

- When Data Path Delay value is:
 - Bypass: No delay cell is used.
 - Static Default: Static delay element DELAYB is used with attribute DEL_MODE set to SCLK_ZEROHOLD.
 - Static User Defined: Static delay element DELAYB is used with attribute DEL_MODE set to USER_DEFINED.
 - Dynamic Default: Dynamic delay element DELAYA is used with attribute DEL_MODE set to SCLK_ZEROHOLD.
 - Dynamic User Defined: Dynamic delay element DELAYA is used with attribute DEL_MODE = USER_DEFINED.

7.3. Configuring DDR Generic Modules

To build a DDR Generic interface, select the DDR_Generic option under Architecture Modules – I/O in the IP Catalog tab. Enter the name of the module. Figure 7.4 shows the type of interface selected as DDR_Generic and the module name entered. This module can then be configured by clicking the Next button.

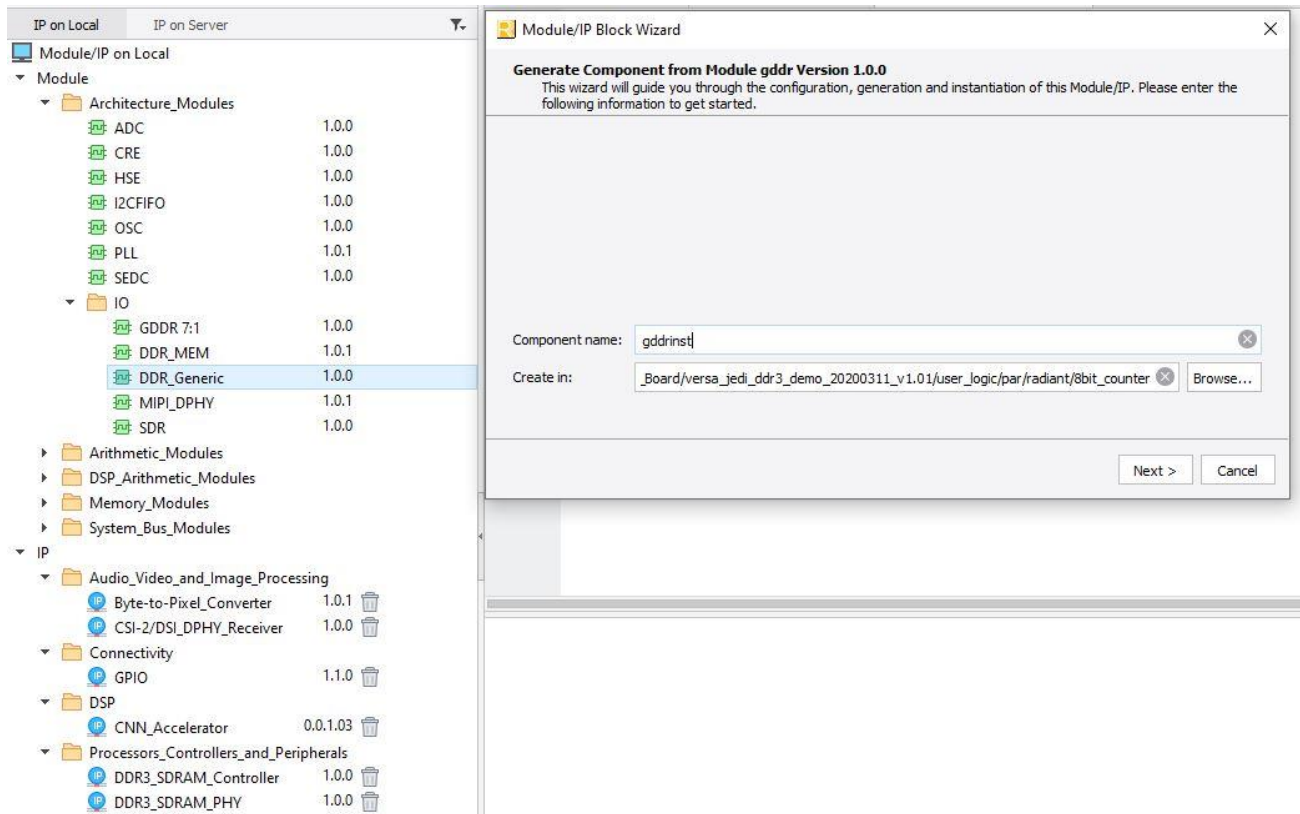


Figure 7.4. DDR_Generic Option Selected in the IP Catalog Tab

Figure 7.5 shows the Configuration tab.

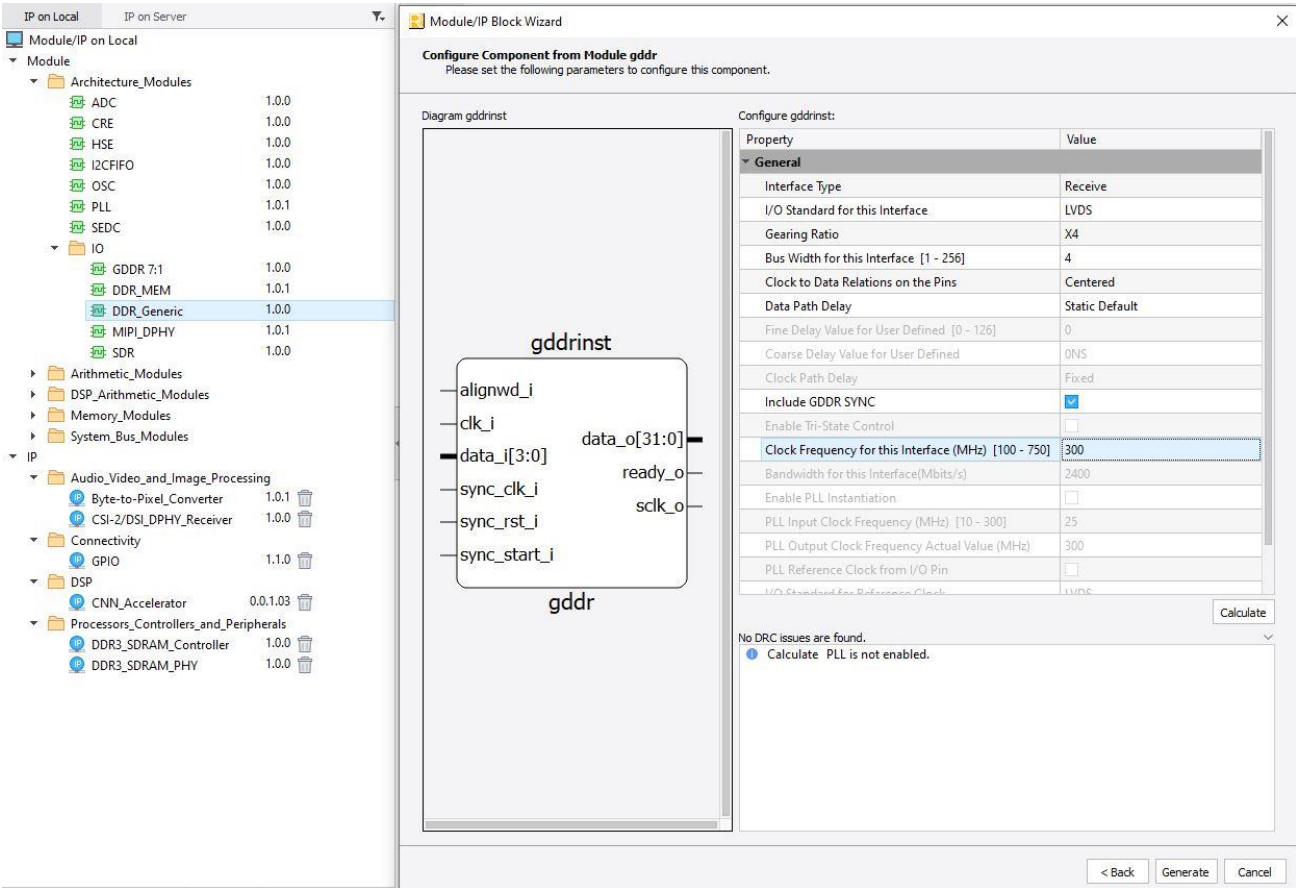


Figure 7.5. DDR_Generic Configuration Tab

Table 7.2 explains the various parameters in the Configuration tab.

Table 7.2. DDR_Generic Configuration Tab Parameters

User Interface Option	Description	Values	Default
Interface Type	Type of Interface (Transmit or Receive)	Transmit, Receive	Receive
I/O Standard	I/O Standard used for the interface	All Legal Input & Output standards	LVDS
Gearing Ratio	DDR register gearing ratio	×1,×2,×4,×5	×1
Bus Width	Bus width for each interface	1 – 256	8
Clock To Data Relations on the pins	Clock to Data alignment	Edge-to-Edge or Centered	Edge-to-Edge
Data Path Delay	Data input can be optionally delayed using the DELAY block. Default Value is selected based on Interface Type.	If Interface Type = Receive: Bypass Static Default Dynamic Default Static User Defined Dynamic User Defined If Interface Type = Transmit: Bypass Static User Defined Dynamic User Defined	Bypass
Fine Delay Value for User Defined	When Data Path Delay of user defined is selected, you also need to set the number of delay steps to be used.	0 – 126	0
Coarse Delay Value for the User Defined	If Delay type selected above is <i>user defined</i> , delay values can be entered with this parameter	0 ns, 0.8 ns, 1.6 ns	0 ns
Clock Path Delay	If Interface Type is receiver	Fixed, Dynamic	Fixed
Include GDDR Sync	—	Disable, Enable	Disable
Enable Tristate Control	Generate Tristate control for Transmit Interfaces	Disable, Enable	Disable
Clock Frequency (MHz)	Speed of the Interface	100 MHz – 600 MHz	150 MHz
Interface Bandwidth (Calculated) (Mbps)	—	Clock Frequency for *2* Bus Width	—
Enable PLL Instantiation	When this option is enabled for Transmit interfaces, the PLL used to generate the clocks is included in the generated module.	Disable, Enable	Disable
PLL Input Clock Frequency	Frequency of the clock used as PLL Input	10 MHz – 150 MHz	25
PLL Output Clock Frequency Actual Value	Displays the achieved PLL output clock frequency	Actual PLL output clock frequency achieved based on interface requirement	150
PLL Reference Clock from I/O Pin	—	Disable, Enable	Disabled
I/O Standard for Reference Clock	—	All I/O Standard	LVDS
PLL Out Clock Tolerance (%)	—	Disable, Enable	0.0

Table 7.3 shows how the interfaces are selected.

Table 7.3. IP Catalog DDR_Generic Interface Selection

Interface Type	Gearing Ratio	Alignment	Default Interface
Receive	2:1 (×1)	Edge-to-Edge	GDDR1_RX.SCLK.Aligned
Receive	2:1 (×1)	Centered	GDDR1_RX.SCLK.Centered
Receive	4:1 (×2)	Edge-to-Edge	GDDR2_RX.ECLK.Aligned
Receive	4:1 (×2)	Centered	GDDR2_RX.ECLK.Centered
Receive	8:1 (×4)	Edge-to-Edge	GDDR4_RX.ECLK.Aligned
Receive	8:1 (×4)	Centered	GDDR4_RX.ECLK.Centered
Receive	10:1 (×5)	Edge-to-Edge	GDDR5_RX.ECLK.Aligned
Receive	10:1 (×5)	Centered	GDDR5_RX.ECLK.Centered
Transmit	2:1 (×1)	Edge-to-Edge	GDDR1_TX.SCLK.Aligned
Transmit	2:1 (×1)	Centered	GDDR1_TX.SCLK.Centered
Transmit	4:1 (×2)	Edge-to-Edge	GDDR2_TX.ECLK.Aligned
Transmit	4:1 (×2)	Centered	GDDR2_TX.ECLK.Centered
Transmit	8:1 (×4)	Edge-to-Edge	GDDR4_TX.ECLK.Aligned
Transmit	8:1 (×4)	Centered	GDDR4_TX.ECLK.Centered
Transmit	10:1 (×5)	Edge-to-Edge	GDDR5_TX.ECLK.Aligned
Transmit	10:1 (×5)	Centered	GDDR5_TX.ECLK.Centered

Refer to the [High-Speed DDR Interface Details](#) section to see implementation details for each of these interfaces.

7.4. Configuring 7:1 LVDS Interface Modules

To build a 7:1 LVDS DDR interface, select GDDR_7:1 option under Architecture Modules – I/O in the IP Catalog. Enter the name of the module.

Figure 7.6 shows the type of interface selected as GDDR_7:1 and module name entered. This module can then be configured by clicking the Next button.

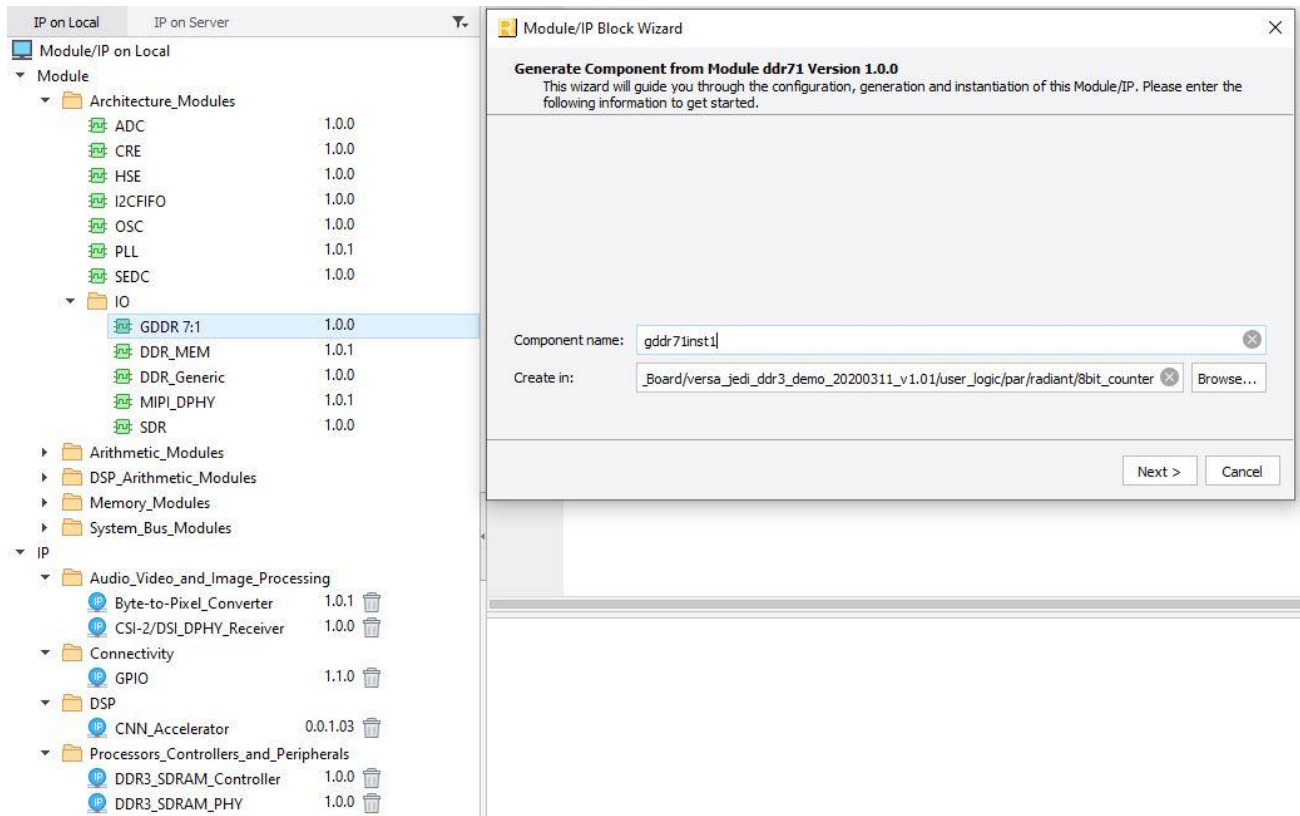


Figure 7.6. GDDR_7:1 Option Selected in the IP Catalog Tab

Clicking Customize displays the Configuration tab where the 7:1 LVDS interface can be configured. Figure 7.7 shows the Configuration tab for 7:1 LVDS interfaces.

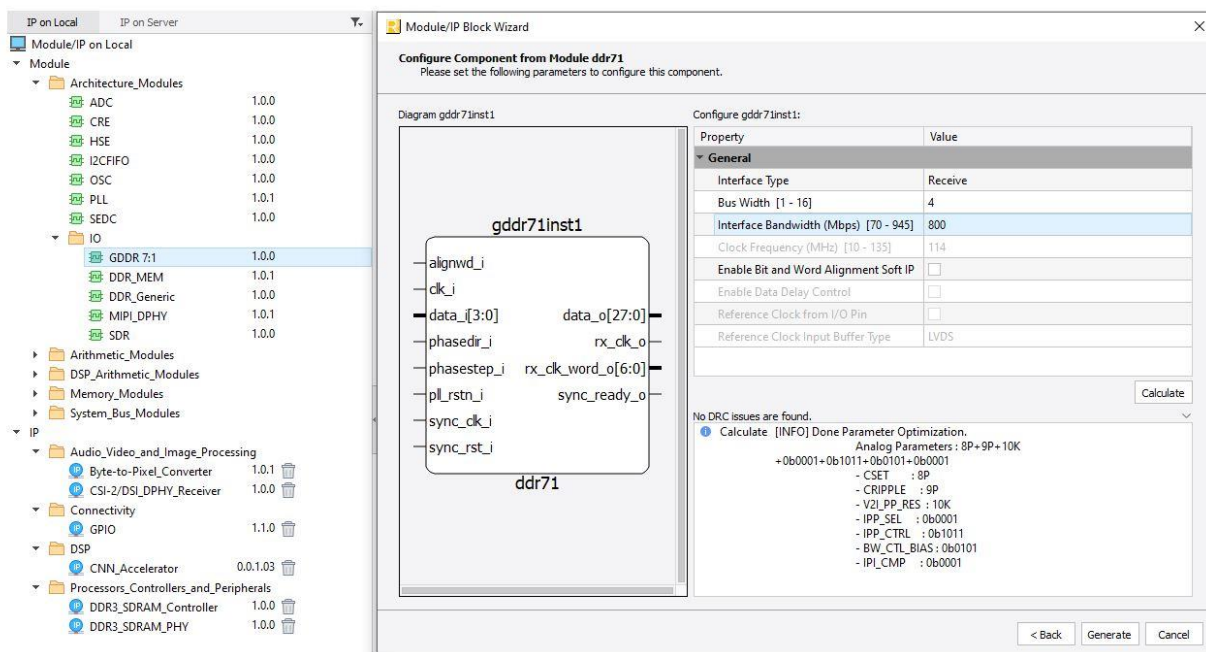


Figure 7.7. GDDR_7:1 LVDS Configuration Tab

Table 7.4 explains the various parameters for GDDR_7:1 configuration.

Table 7.4. GDDR_7:1 LVDS Configuration Parameters

User Interface Option	Description	Values
Interface Type	Type of interface (Receive or Transmit)	Transmit, Receive
Bus Width	Bus width for one channel of 7:1 LVDS interface	1 – 16
Clock Frequency (MHz)	Pixel clock speed	10 MHz – 135 MHz
Interface Bandwidth (Mbps)	Interface bandwidth	70 Mbps – 945 Mbps
Enable Bit and Word Alignment Soft IP	Soft IP included with the module to implement Bit and Word alignment for receive interface	Enable, Disable
Enable Data Delay Control	Only As Enable Bit and Word Alignment soft IP is selected	Enable, Disable
Reference Clock from I/O pin	For transmit interface	Enable, Disable
Reference Clock Input Buffer Type	Only as Reference Clock from I/O Pins is selected	All I/O types (LVDS as default)

7.5. Configuring DDR Memory Interfaces

IP Catalog is used to configure the PHY portion of the DDR3, DDR3L, LPDDR4 memory interfaces. For the detailed block diagram for each interface, see the [Memory Interface Implementation](#) section.

To build a DDR Memory interface, select DDR_MEM option under Architecture Modules – I/O in the IP Catalog tab. Enter the name of the module.

Figure 7.8 shows the type of interface selected as GDDR_MEM and module name entered. This module can then be configured by clicking the Next button.

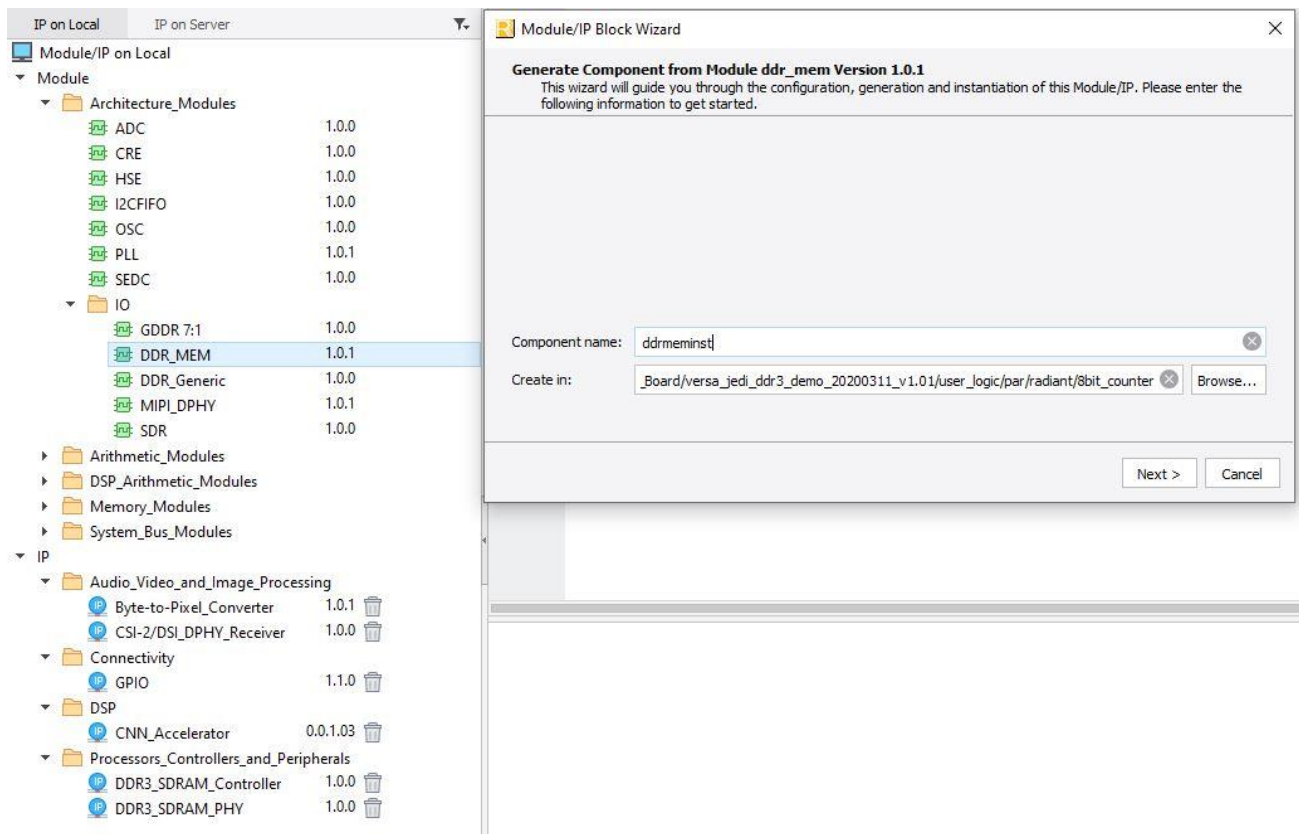


Figure 7.8. DDR_MEM Option Selected in the IP Catalog Tab

Figure 7.9 shows the General tab for the DDR_MEM interface.

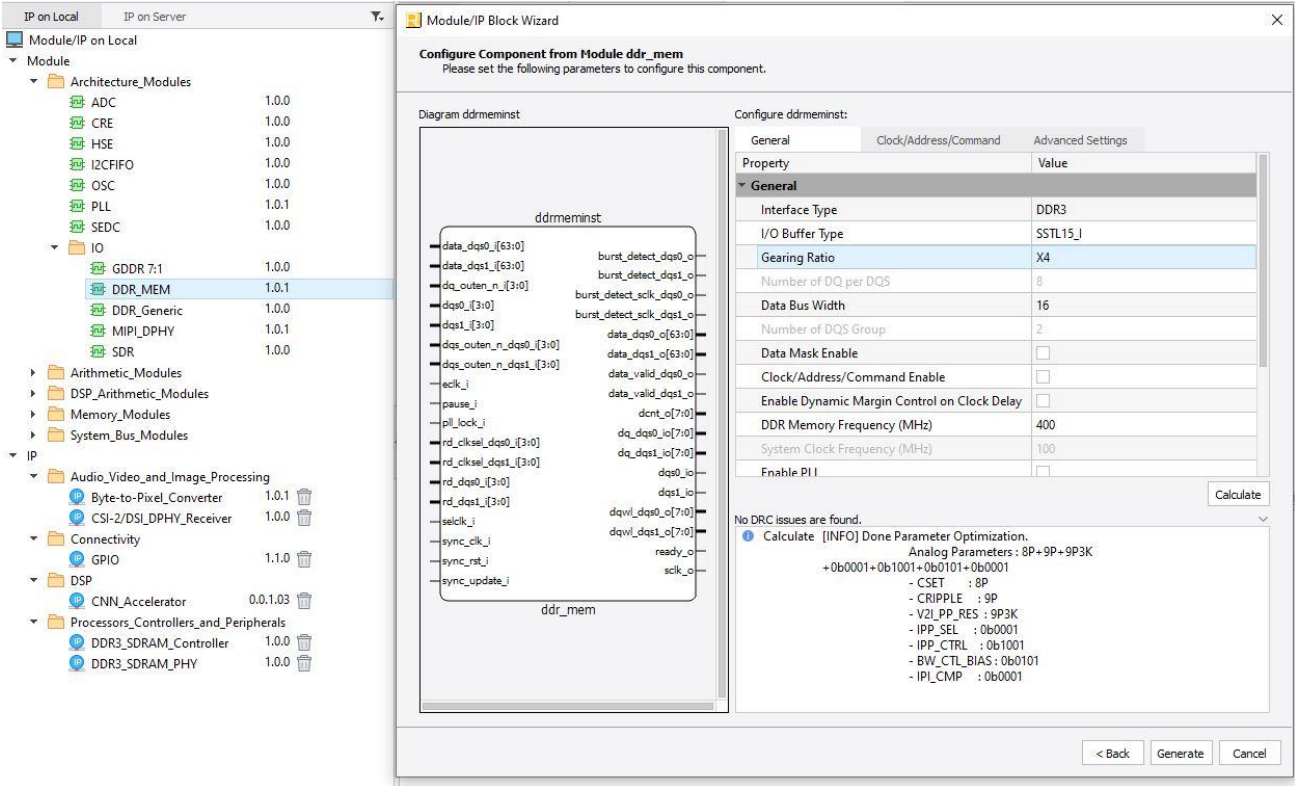


Figure 7.9. DDR_MEM Configuration

Table 7.5 below describes the various settings shown in the General tab.

Table 7.5. DDR_MEM General Tab Parameters

User Interface Option	Description	Values	Default
Interface	DDR memory interface type	DDR3, DDR3L, LPDDR4	DDR3
I/O Buffer Configuration	I/O type configuration for DDR pins	DDR3: SSTL15_I, SSTL15_II DDR3L: SSTL135_I, SSTL135_II LPDDR4: LVSTL11	DDR3: SSTL15_I DDR3L: SSTL135_I LPDDR4: LVSTL11
Gearing Ratio	DDR Register gearing ratio	×2, ×4	×2
Number of DQ per DQS	Number of associated DQ per DQS pin	8	8
Data Bus Width	DDR memory interface data bus width	DDR3/DDR3L: 8, 16 LPDDR4: 16, 32, 64	16
Number of DQS Group	Total number of DQS groups. Not user-selectable, display only.	1, 2, 3, 4	2
Data Mask Enable	Data mask pins added with this option checked	Enable, Disable	Disable
Clock/Address/Command Enable	Clock/address/command pins added with this option checked	Enable, Disable	Disable
Enable Dynamic Margin Control on the Clock Delay	Dynamic margin control ports added with this option checked	Enable, Disable	Disable
DDR Memory Frequency (MHz)	Target DDR memory interface frequency	DDR3: 400, 533 DDR3L: 400, 533 LPDDR4: 400, 533	DDR3: 400 MHz DDR3L: 400 MHz LPDDR4: 400MHz
System Clock Frequency (Calculated) (MHz)	Calculated system clock frequency. Not user-selectable, display only.	SCLK Frequency Value, DDR Memory Frequency/2	200
Enable PLL	PLL included with this option checked	Enable, Disable	Disabled
PLL Input Clock (CLK1) Frequency (MHz)	Input reference clock frequency	10 MHz – 800 MHz	100
PLL Reference Clock from I/O Pin	—	Enable, Disable	Disabled
I/O Standard for Reference Clock	—	All I/O standard	LVDS
PLL Out Clock (CLKOP) Tolerance (%)	—	—	0.0
Actual DDR Memory Frequency (MHz)	Calculated actual memory bus frequency. Not user-selectable, display only.	—	—

If you choose to generate the Clock/Address/Command signals, then the settings in the Clock/Address/Command tab are active and can be set up as required.

Figure 7.10 shows the Clock/Address/Command tab.

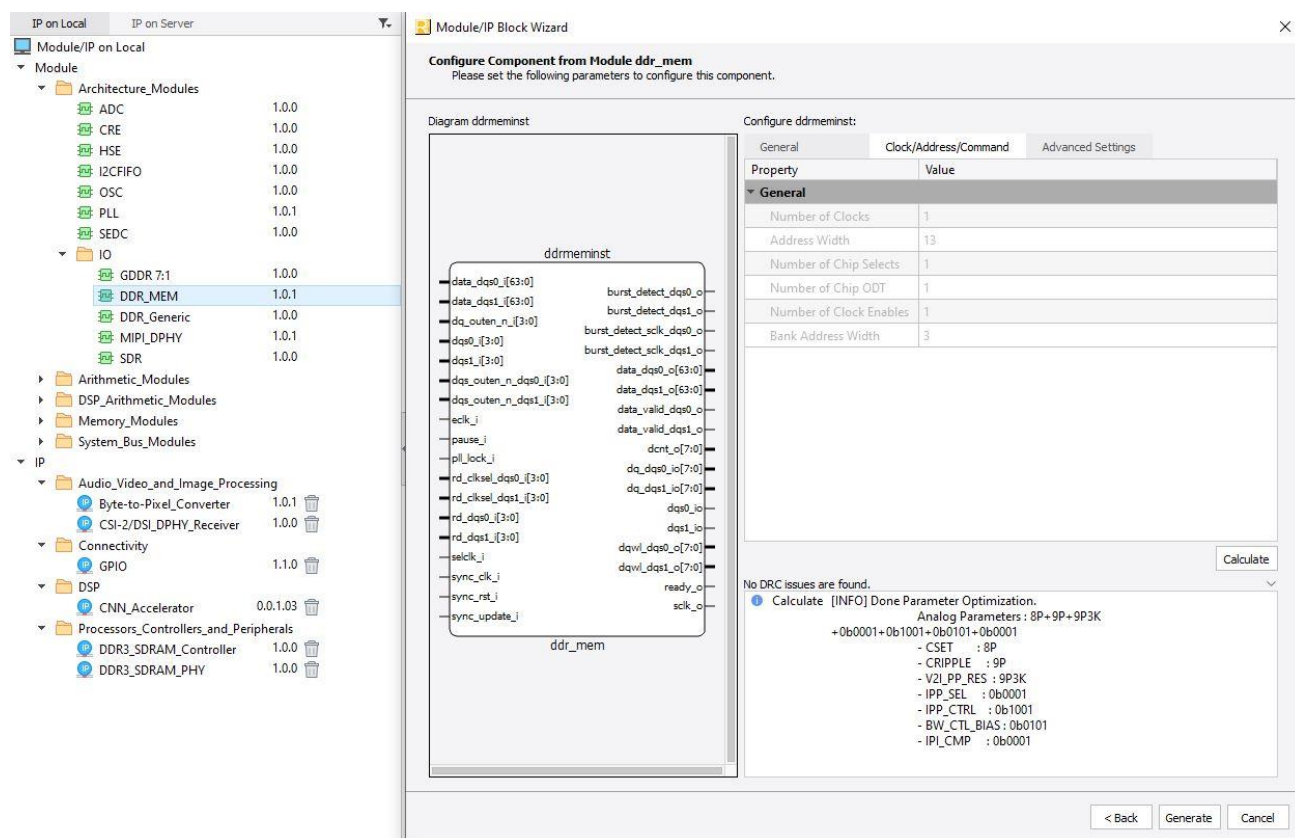


Figure 7.10. DDR_MEM Clock/Address/Command Tab

Table 7.6 lists the values that can be used for the Clock/Address/Command settings.

Table 7.6. DDR_MEM Clock/Address/Command Parameters

User Interface Option	Range	Default Value
Number of Clocks	DDR3/DDR3L: 1, 2 LPDDR4: 1, 2, 4	DDR3/DDR3L: 1 LPDDR4: 1
Address Width	DDR3/DDR3L: 13 – 16 LPDDR4: Blank	DDR3/DDR3L: 13 LPDDR4: Blank
Bank Address Width	DDR3/DDR3L: 3 DDR3L: 3 LPDDR4: Blank	DDR3/DDR3L: 3 LPDDR4: Blank
Number of Chip Selects	DDR3/DDR3L: 1, 2 LPDDR4: 1,2,4	DDR3/DDR3L: 1 LPDDR4: 2
Number of Clock Enables	= Number of Chip Selects	= Number of Chip Selects
Number of ODT	DDR3, DDR3L = Number of Chip Selects LPDDR4 = Number of Chip Selects	DDR3, DDR3L = Number of Chip Selects LPDDR4 = Number of chip Selects

An additional tab called Advanced Settings for the MachXO5-NX device can be used to adjust the default DQS Read and Write Delay settings, as shown in Figure 7.11.

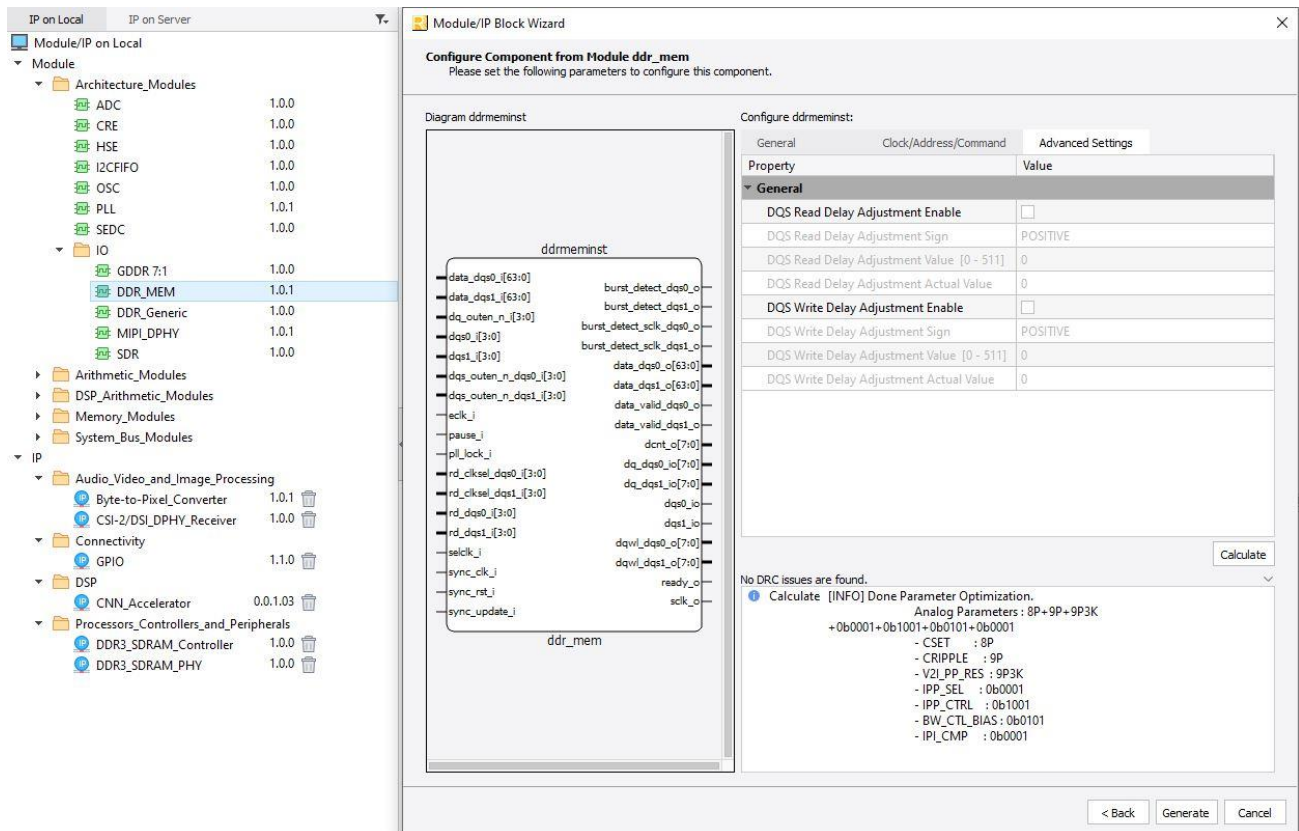


Figure 7.11. DDR_MEM Advanced Settings Tab

Table 7.7 lists the available values in this Advanced Settings tab (Figure 7.11).

Table 7.7. DDR_MEM Advanced Settings Tab Parameters

User Interface Option	Range	Default Value
DQS Read Delay Adjustment Enable	Enable, Disable	Disable
DQS Read Delay Adjustment Sign	Positive, Complement	Positive
DQS Read Delay Adjustment Value	0 – 511	0
DQS Write Delay Adjustment Enable	Enable, Disable	Disable
DQS Write Delay Adjustment Sign	Positive, Complement	Positive
DQS Write Delay Adjustment Value	0 – 511	0
DQS Write Delay Adjustment Actual Value	Display Value	0

7.6. Configuring MIPI D-PHY Modules

To build a MIPI D-PHY interface, select the MIPI_DPHY option under Architecture Modules – I/O in the IP Catalog tab. Enter the name of the module. [Figure 7.12](#) shows the type of interface selected as MIPI_DPHY and the module name entered. This module can then be configured by clicking the Next button.

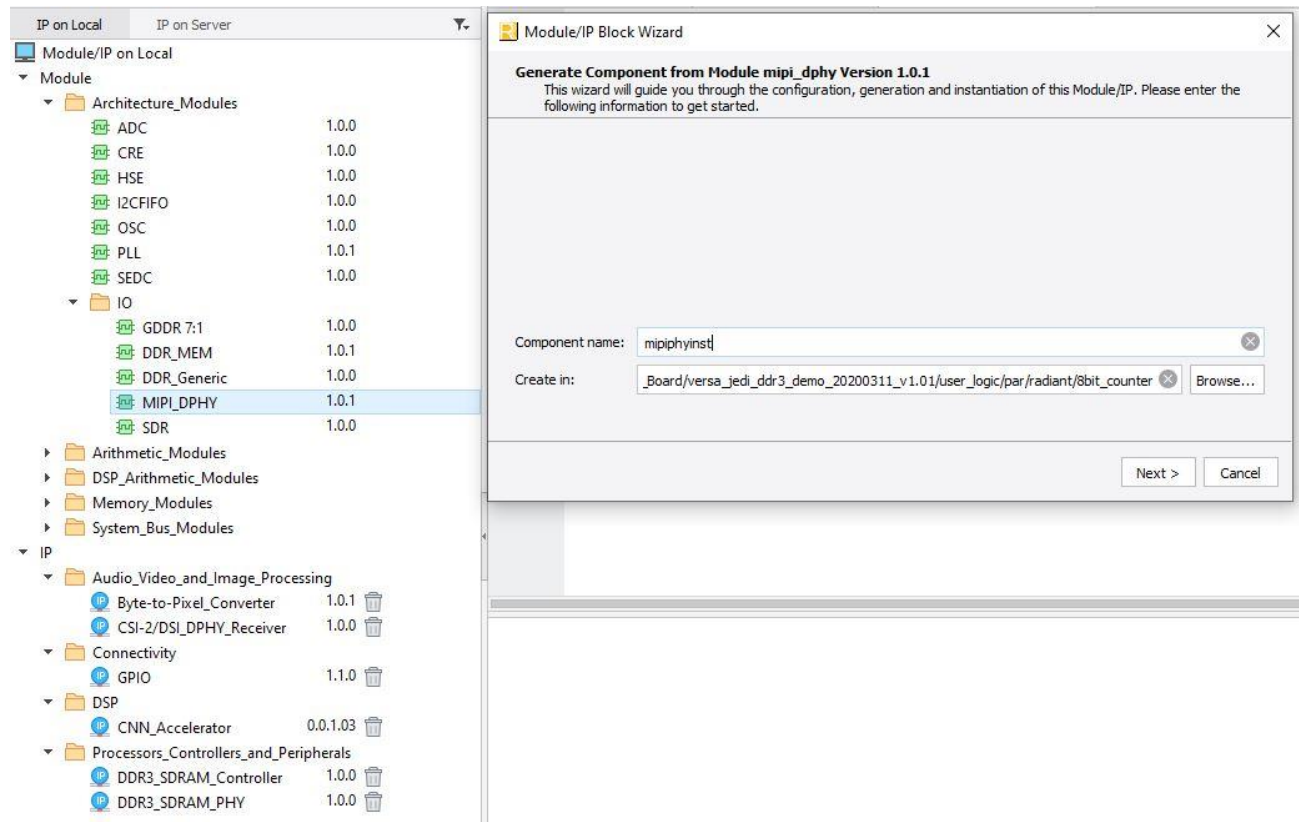


Figure 7.12. MIPI_DPHY Option Selected in the IP Catalog Tab

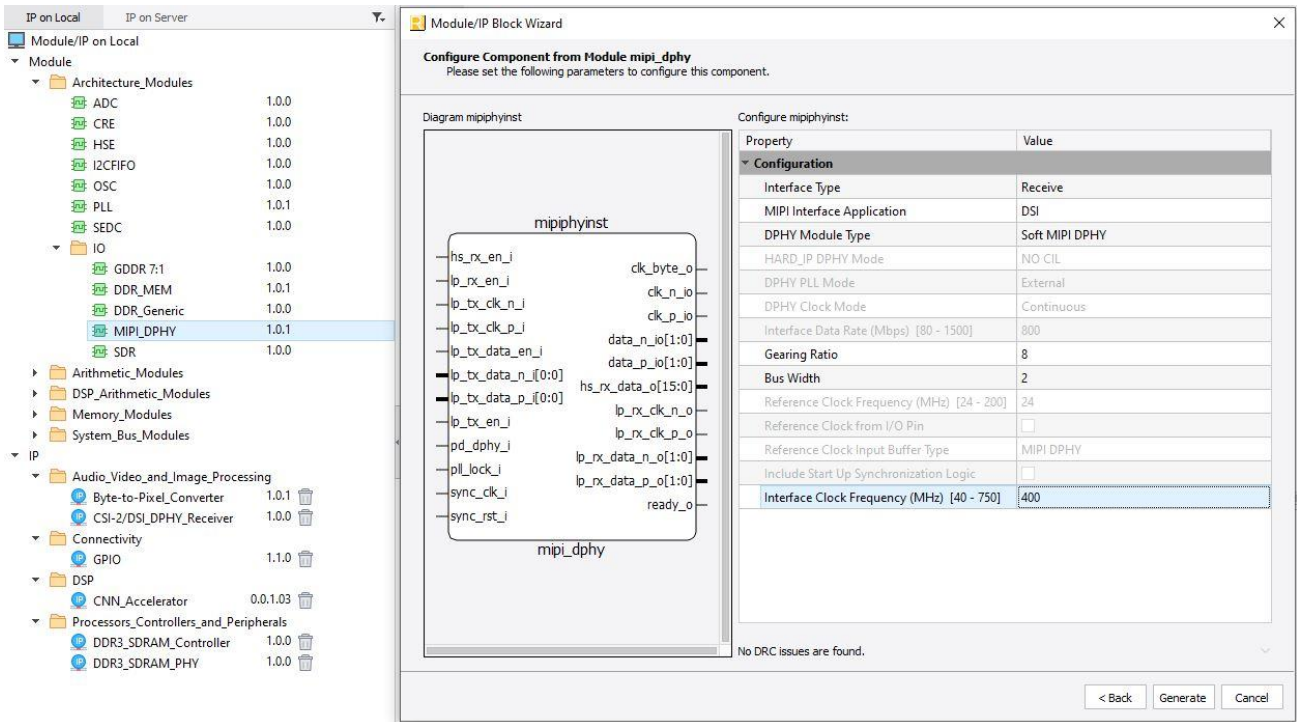


Figure 7.13. MIPI_DPHY Configuration Settings Tab

Table 7.8 explains the various configurations options available for MIPI D-PHY Interface.

Table 7.8. Configuration Options for MIPI D-PHY Interface

User Interface Option	Range	Default Value
Interface Type	Receiver, Transmit	Receiver
MIPI Interface Application	DSI, CSI-2	DSI
DPHY Module Type	Soft MIPI DPHY	Soft
DPHY PLL Mode	External, Internal for Transmit Interface	External
DPHY Clock Mode	Continuous, Non-Continuous	Continuous
Interface Data Rate (Mbps)	Calculated display value: Interface clk frequency ×2, 80 Mbps – 1200 Mbps	1200
Gearing Ratio	Soft MIPI DPHY : 8	8
Bus Width	1, 2, 4	1
Reference Clock Frequency (MHz)	24 MHz – 200 MHz for Transmit Interface only	100
Reference Clock from I/O Pin	Enable, Disable	Disable
Reference Clock Input Buffer Type	MIPI DPHY	MIPI DPHY
Include Start Up Sync Logic	Enable, Disable	Disable
Interface Clock Frequency (MHz)	Soft MIPI DPHY: 40 MHz – 600 MHz	160

8. I/O Logic (DDR) User Primitives and Attributes

This section describes the user primitives for I/O logic that can be used to implement all the DDR interfaces. These primitives are divided into ones that are used to implement the DDR data and ones for DDR Strobe signal or the Source Synchronous clock. The DQSBUF primitives are used to generate the signals required to correctly capture the data from the DDR memory.

Table 8.1. Software Primitives

Type	Primitive	Description
Input/Output Delay	DELAYA	Dynamic Input/Output Delay Element
	DELAYB	Static Input/Output Delay Element
DDR Data Input	IDDRX1	Generic $\times 1$ IDDR
	IDDRX2	Generic $\times 2$ IDDR
	IDDRX4	Generic $\times 4$ IDDR
	IDDRX5	Generic $\times 5$ IDDR
	IDDR71	7:1 LVDS IDDR
DDR Data Output	ODDRX1	Generic $\times 1$ ODDR
	ODDRX2	Generic $\times 2$ ODDR
	ODDRX4	Generic $\times 4$ ODDR
	ODDRX5	Generic $\times 5$ ODDR
	ODDR71	7:1 LVDS ODDR
DDR Mem Addr/Cmd	OSHX2	CS_N for DDR3 interface
	OSHX4	CS_N for DDR3 interface
DDR Mem Data Input	IDDRX2DQ	DQ Input for DDR3 memory
	IDDRX4DQ	DQ Input for DDR3 memory
DDR Mem Data Output	ODDRX2DQ	DQ output for DDR3 memory
	ODDRX4DQ	DQ output for DDR3 memory
DDR Mem Data Tristate	TSHX2DQ	DQ tri-state control for DDR3 memory
	TSHX4DQ	DQ tri-state control for DDR3 memory
DDR Mem DQS	ODDRX2DQS	DQS Output for DDR3 memory
	ODDRX4DQS	DQS Output for DDR3 memory
DDR Mem DQS Tristate	TSHX2DQS	DQS tri-state control for DDR3 memory
	TSHX4DQS	DQS tri-state control for DDR3 memory
LPDDR4 Output Delay	OUTDELAYA	Dynamic delay module

8.1. Input/Output DELAY

The DELAY block can be used to delay the input data from the input pin to the IDDR or IREG or FPGA fabric or to delay the output data from the ODDR, OREG or FPGA fabric to the output pin. It is useful to adjust for any skews amongst the input or output data bus. It can also be used to generate skew between the bits of output bus to reduce SSO noise.

The DELAY block can be used with IDDR or ODDR modules, SDR modules, as well as on the direct input to the FPGA. The DELAY is shared by the input and output paths and hence can only be used either to delay the input data or the output data on a bi-direction pin.

The data input to this block can be delayed using:

- Pre-determined delay value (for Zero Hold time, delay based on Interface Type)
- Fixed Delay values that you enter
- Counter up and down controls, which can be dynamically updated

You can optionally bypass the DELAY block completely as well.

8.2. DELAYA

By default, the DELAYA is configured to factory delay settings based on the clocking structure. You can overwrite the DELAY setting using the MOVE and DIRECTION control inputs. The LOADN resets the delay back to the default value.

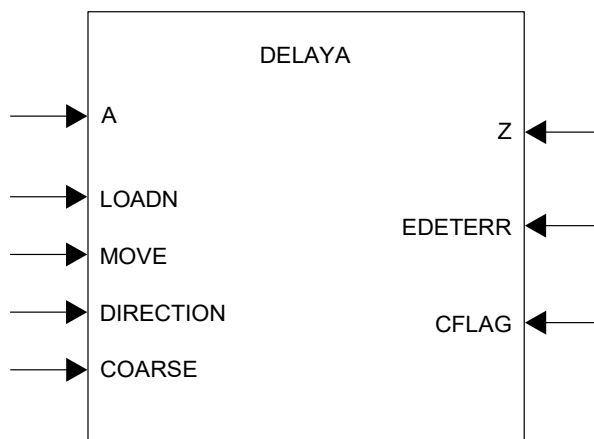


Figure 8.1. DELAYA Primitive

Table 8.2. DELAYA Port List

Port	I/O	Description
A	I	Data input from pin or output register block.
LOAD_N	I	0 on LOADN resets to default delay setting.
MOVE	I	Pulse on MOVE changes delay setting. DIRECTION is sampled at the falling edge of MOVE.
DIRECTION	I	1 to decrease delay and '0' to increase delay
COARSE[1:0]	I	Dynamic coarse delay control (2 bits) 00: no coarse delay 01: 800ps delay 10: 1600ps delay 11: invalid
Z	O	Delayed data to input register block or to pin.
EDETERR	O	Error detected when using the edge monitor logic.
CFLAG	O	Flag indicating the delay counter has reached the max (when moving up) or min (when moving down) value.

8.3. DELAYB

By default, the DELAYB is configured to factory delay settings based on the clocking structure. You cannot change the delay when using this module.

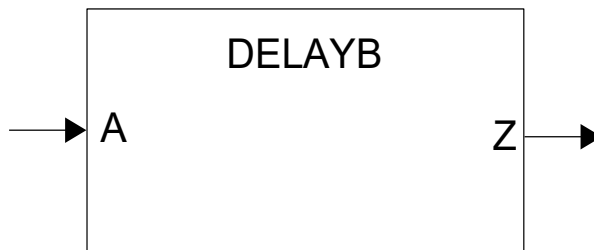


Figure 8.2. DELAYB Primitive

Table 8.3. DELAYB Port List

Port	I/O	Description
A	I	Data input from pin or output register block
Z	O	Delayed data to input register block or to pin

8.4. DELAY Attribute Description

Table 8.4 describes the attributes available for the DELAYA and DELAYB elements.

Table 8.4. DELAYA and DELAYB Attributes

Attribute	Description	Values ^{1, 2, 3}	Default	DELAY
DEL_MODE	Sets the delay mode to be used	USER_DEFINED SCLK_ZEROHOLD ECLK_ALIGNED ECLK_CENTERED SCLK_ALIGNED SCLK_CENTERED DQS_CMD_CLK DQS_ALIGNED_X2 DQS_ALIGNED_X4 DQS_CENTERED_X2 DQS_CENTERED_X4	USER_DEFINED	DELAYA DELAYB
DEL_VALUE	Sets delay value when DEL_MODE is set to USER_DEFINED	0..127	0	DELAYA DELAYB Step is 12.5ps
COARSE_DELAY_MODE	Select MC1 or CIB coarse delay code control; 0—Selects from MC1 (STATIC), 1—Selects from CIB (DYNAMIC)	STATIC DYNAMIC	STATIC	DELAYA
COARSE_DELAY	Coarse delay setting for lol delay cell	0NS 0P8NS 1P6NS	0NS	DELAYA
EDGE_MONITOR	To enable edge monitor when in an IDDR x2, x7to1, x4, or x5 mode	ENABLED; DISABLED	ENABLED	DELAYA
WAIT_FOR_EDGE	Used for SPI4.2 implementation	ENABLED; DISABLED	ENABLED	DELAYA

Notes:

1. DQS_CMD_CLK is only for the DDR Memory CMD and CLK outputs.
2. DQS_ALIGNED_x2/x4 is shared by DQS generic and the DDR memory inputs.
3. DQS_CENTERED_x2/x4 is used for DQS generic inputs.

8.5. DDRDLL (Master DLL)

The DDRDLL is used to generate a 90-degree delay for the DQS Strobe Input during a memory interface or for the clock input for a generic DDR interface.

There is one DDRDLL module on each corner of the device. The DDRDLL outputs delay codes that are used in the DQSBUF elements to delay the DQS input, or in the DLLDEL module to delay the input clock. DDRDLL, by default, generates 90-degree phase shift.

8.5.1. DDRDLLA

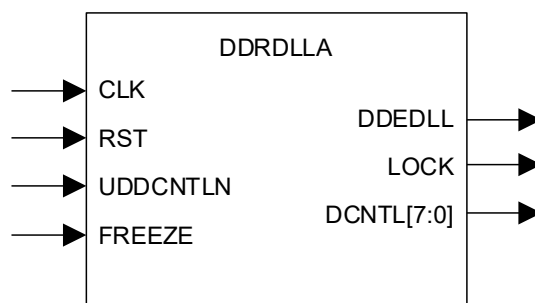


Figure 8.3. DDRDLLA Primitive

Table 8.5. DDRDLLA Port List

Port	I/O	Description
CLK	I	Reference clock input to the DDRDLL. Should run at the same frequency as the clock to be delayed.
RST	I	Reset input to the DDRDLL.
UDDCNTLN	I	Update control to update the delay code. When low, the delay code out of the DDRDLL is updated. Should not be active during a read or a write cycle.
FREEZE	I	Releases the DDRDLL input clock.
DDRDEL	O	The delay codes from the DDRDLL are to be used in DQSBUF or DLLDEL.
LOCK	O	Lock output to indicate the DDRDLL has valid delay output.
DCNTL [7:0]	O	The delay codes from the DDRDLL are available for the user IP.

Table 8.6. DDRDLL Attributes

Attribute	Description	Values	Default
FORCE_MAX_DELAY ¹	Bypass DLL locking procedure at low frequency.	YES, NO	NO

Note: When F_{in} is ≤ 30 MHz. The software sets Force_max_delay to YES. DDRDLL does not go through the locking process but is locked to maximum delay steps under such conditions.

8.6. DLL Delay (DLLDEL)

The DLLDEL receives delay codes from the DDRDLL to generate a delayed clock output from a PCLK input. Take note that only even numbered PCLK pins (PCLK<Bank Number>_<PCLK number>) can be used as inputs to the DLLDEL.

The delayed clock output of the DLLDEL can be connected to the IDDR module. The delay from the DLLDEL can be dynamically adjusted using counter margin control signals that can shift the delay up or down DLLDEL.

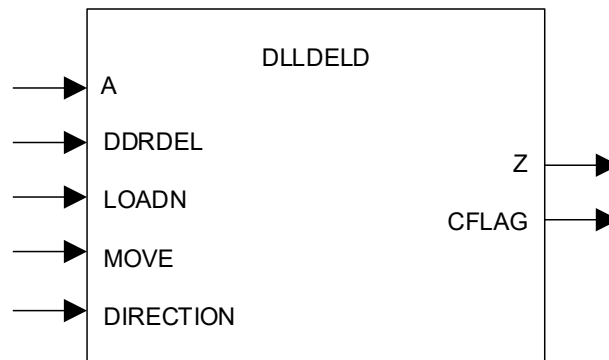


Figure 8.4. DLLDELD Primitive

Table 8.7. DLLDELD Port List

Port	I/O	Description
A	I	Clock input.
DDRDEL	I	Delay inputs from DDRDLL.
LOADN	I	Used to reset back to 90-degree delay.
MOVE	I	Pulse is required to change delay settings. The value on Direction is sampled at the falling edge of MOVE.
DIRECTION	I	Indicates delay direction. 1 to decrease delay and 0 to increase delay.
CFLAG	O	Indicates the delay counter has reached its maximum value when moving up or minimum value when moving down.
Z	O	Delayed clock output.

Table 8.8. DLLDELD Attributes

Attribute	Description	Values	Default
DEL_ADJ ²	Sign bit for READ delay adjustment, DDR input	PLUS, MINUS	PLUS
DEL_VAL ²	Value of delay for input DDR.	0 to 255 (PLUS) 1 to 256 (MINUS)	Note ²

Notes:

- Attributes are only available through EPIC and ECL Editor. It is recommended that values of this attribute are not updated without consulting Lattice Semiconductor Technical Support.
- Default value is set based on device characterization to achieve the 90-degree phase shift.

8.7. Input DDR Primitives

The following are the primitives used to implement various Generic DDR Input configurations.

8.7.1. IDDRX1

This primitive is used for the Generic x1 IDDR implementation.

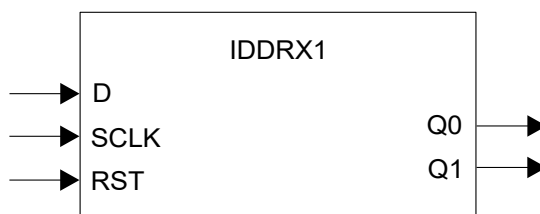


Figure 8.5. IDDRX1 Primitive

Table 8.9. IDDRX1 Port List

Port	I/O	Description
D	I	DDR data input
SCLK	I	Primary Clock input
RST	I	Reset to DDR registers
Q0	O	Data at the positive edge of the clock
Q1	O	Data at the negative edge of the clock

8.7.2. IDDRX2

This primitive is used for the Generic x2 IDDR implementation.

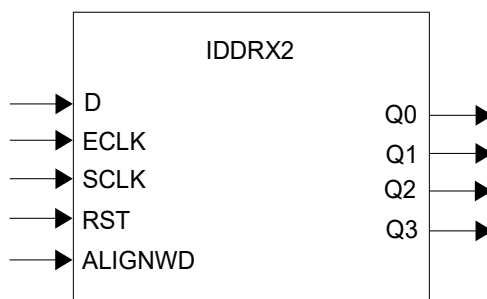


Figure 8.6. IDDRX2 Primitive

Table 8.10. IDDRX2 Port List

Port	I/O	Description
D	I	DDR data input
SCLK	I	Primary clock input (divide-by-2 of ECLK)
RST	I	Reset to DDR registers
ECLK	I	Fast edge clock
ALIGNWD	I	This signal is used for word alignment. It shifts the word by one bit.
Q[3:0]	O	Parallel data output. Q0, Q2 are the data at the positive edges of the input ECLK. Q1 and Q3 are data at negative edge of input ECLK.

8.7.3. IDDRX4

This primitive is used for the Generic x4 IDDR implementation.

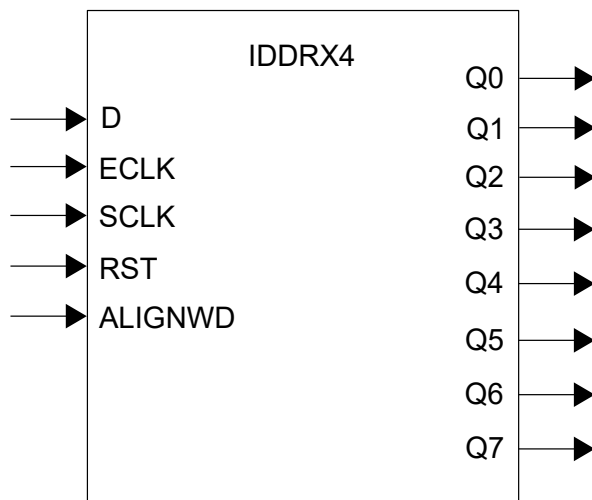


Figure 8.7. IDDRX4 Primitive

Table 8.11. IDDRX4 Port List

Port	I/O	Description
D	I	DDR data input
SCLK	I	Primary clock input (divide-by-4 of ECLK)
RST	I	Reset to DDR registers
ECLK	I	Fast edge clock
ALIGNWD	I	This signal is used for word alignment. It shifts the word by one bit.
Q[7:0]	O	Parallel data output. Q0, Q2, Q4, Q6 are the data at the positive edges of the input ECLK. Q1, Q3, Q5, Q7 are data at negative edge of input ECLK.

8.7.4. IDDRX5

This primitive is used for the Generic x5 IDDR implementation.

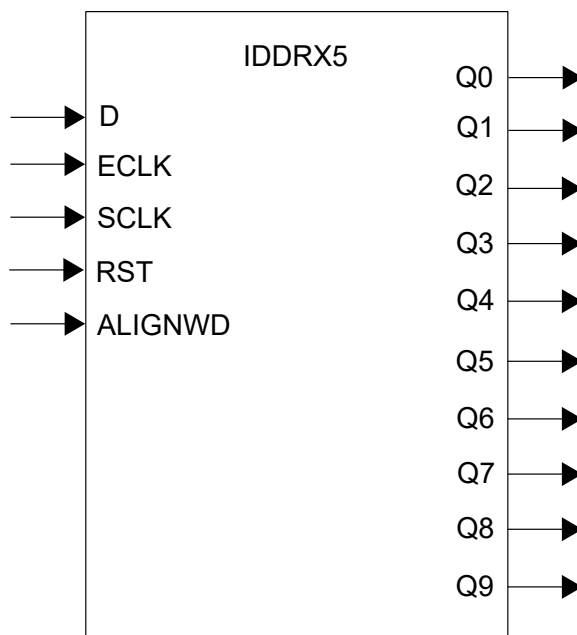


Figure 8.8. IDDRX5 Primitive

Table 8.12. IDDRX5 Port List

Port	I/O	Description
D	I	DDR data input
ECLK	I	Fast edge clock
SCLK	I	Primary clock input (divide-by-5 of ECLK)
RST	I	Reset to DDR registers
ALIGNWD	I	This signal is used for word alignment. It shifts the word by one bit.
Q[9:0]	O	Parallel data output. Q0, Q2, Q4, Q6, Q8 are the data at the positive edges of the input ECLK. Q1, Q3, Q5, Q7, Q9 are data at negative edge of input ECLK.

8.7.5. IDDR71

This primitive is used for 7:1 LVDS input side implementation.

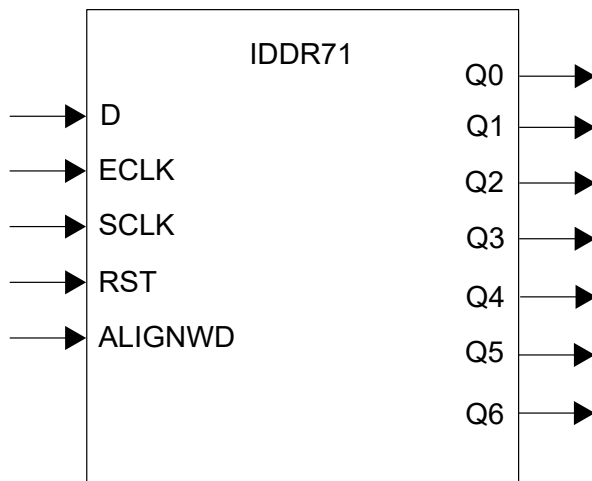


Figure 8.9. IDDR71

Table 8.13. IDDR71 Port List

Port	I/O	Description
D	I	DDR data input
ECLK	I	Fast edge clock
SCLK	I	Primary clock input (divide-by-3.5 of ECLK)
RST	I	Reset to DDR registers
ALIGNWD	I	This signal is used for word alignment. It shifts the word by one bit.
Q[6:0]	O	7 bits of output data.

8.8. Output DDR Primitives

The following are the primitives used to implement various Generic ODDR output configurations.

8.8.1. ODDRX1

This primitive is used for Generic x1 ODDR implementation.

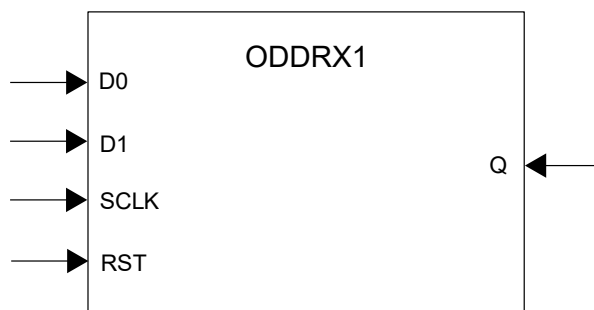


Figure 8.10. ODDRX1

Table 8.14. ODDRX1F Port List

Port	I/O	Description
D0, D1	I	Parallel data input to ODDR (D0 is sent out first then D1)
SCLK	I	SCLK input
RST	I	Reset input
Q	O	DDR data output on both edges of SCLK

8.8.2. ODDRX2

This primitive is used to receive Generic x2 ODDR implementation.

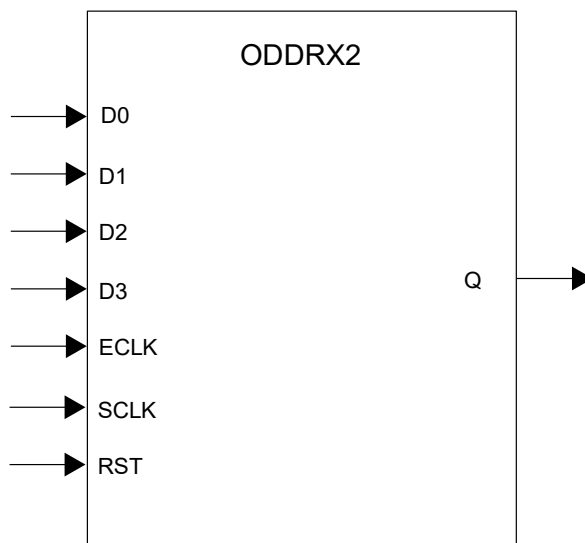


Figure 8.11. ODDRX2

Table 8.15. ODDRX2 Port List

Port	I/O	Description
D0, D1, D2, D3	I	Parallel Data input to the ODDR (D0 is sent out first and D3 last)
ECLK	I	Fast edge clock
SCLK	I	Primary clock input (divide-by-2 of ECLK)
RST	I	Reset to DDR registers
Q	O	DDR data output on both edges of ECLK

8.8.3. ODDRX4

This primitive is used for the Generic x4 ODDR implementation.

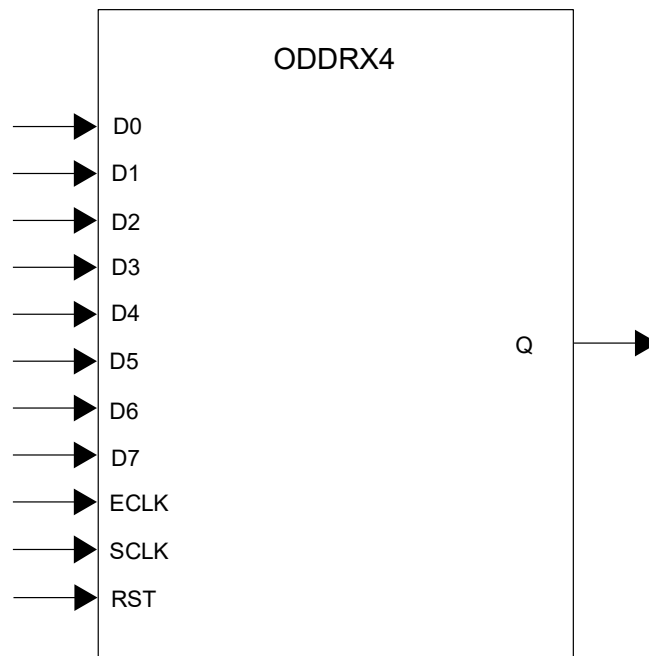


Figure 8.12. ODDRX4 Primitive

Table 8.16. ODDRX4 Port List

Port	I/O	Description
D0, D1, D2, D3, D4, D5, D6, D7	I	Parallel Data input to the ODDR (D0 is sent out first and D7 last)
ECLK	I	Fast edge clock
SCLK	I	Primary clock input (divide-by-4 of ECLK)
RST	I	Reset to DDR registers
Q	O	DDR data output on both edges of ECLK

8.8.4. ODDR5

This primitive is used for the Generic x5 ODDR implementation.

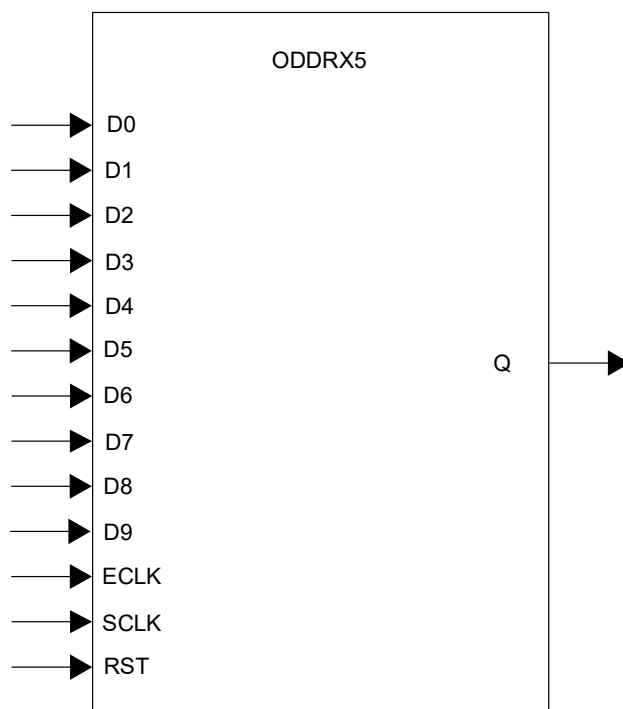


Figure 8.13. ODDR5 Primitive

Table 8.17. ODDR5 Port List

Port	I/O	Description
D0, D1, D2, D3, D4, D5, D6, D7, D8, D9	I	Parallel Data input to the ODDR (D0 is sent out first and D9 last)
ECLK	I	Fast edge clock
SCLK	I	Primary clock input (divide-by-5 of ECLK)
RST	I	Reset to DDR registers
Q	O	DDR data output on both edges of ECLK

8.8.5. ODDR71

This primitive is used for 7:1 LVDS ODDR implementation.

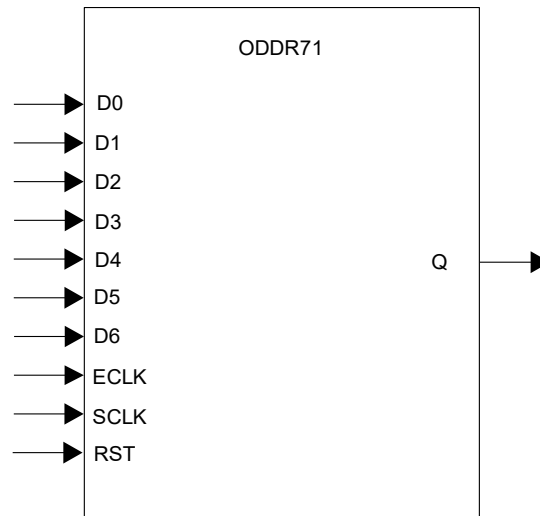


Figure 8.14. ODDR71 Primitive

Table 8.18. ODDR71 Port List

Port	I/O	Description
D0, D1, D2, D3, D4,D5,D6	I	Parallel Data input to the ODDR (D0 is sent out first and D6 last)
ECLK	I	Fast edge clock
SCLK	I	Primary clock input (divide-by-3.5 of ECLK)
RST	I	Reset to DDR registers
Q	O	DDR data output on both edges of ECLK

8.8.6. DQSBUF (DQS Strobe Control Block)

DQSBUF block is used to delay the incoming DQS signal by 90 degrees. DQSBUF receives a delay code from DDRDLL and shifts the signal accordingly. The DQSBUF should be used when the DQS clock tree is used for clocking the IDDR module.

The following describes the functions of the DQSBUF module:

- Receives the delay code from the DDRDLL and generates the 90-degree delayed DQS signal that is used as a Write clock in the IDDR module
- You can choose to move the delay up or down using the dynamic margin control signals (loadn, move, and direction).
- When this margin control circuit is used and LOADN goes high, any further delay code changes from the DDRDLL are not reflected in the delay DQS signal. A soft IP is required to detect the code changes from the DDRDLL and update the MOVE pulse input to the DQSBUF so that the DDRDLL code changes can be tracked.
- If margin control is not used, then LOADN should be low to continuously get code from DDRDLL.
- Pause should be asserted prior to changing readclkssel, DYNDEL<>, or DLL code update.
- Receives READ clock select signals that are used to correctly position the READ signal with respect to the DQS preamble.
- Generates a BURSTDET output that can be used to validate the READ pulse positioning.
- Generates the Read and Write pointers required in the IDDR to correctly transfer data between the DQS and ECLK clock domains.
- Generates DQS write clocks to be used in ODDR modules to generate DQ and DQS.
- Generates the Write Leveling delay required for DDR3 or LPDDR4 interfaces.

8.9. IDDR/ODDR Modules for Memory DDR Implementation

This section describes the primitives used to build DDR, DDR2 and DDR3 memory interfaces. Some of these primitives are also used to generate generic DDR functions that use DQS clocking tree. MachXO5-NX IDDR/ODDR modules support 4:1(×2), 8:1(×4), gearing modes that are used to implement the memory functions. The DDR2 at higher speeds and DDR3 uses the ×2 gearing primitives to implement the interfaces. The DDR3 interface at higher speeds requires the ×4 gearing function. Each of these gearing functions is available on each pin when interfacing to the memory.

8.9.1. Primitive Symbols

Table 8.19 shows a summary of all the DDR memory primitives. See the sections below for detailed descriptions.

Table 8.19. Summary of all DDR Memory Primitives

DDR Memory	DQ Input	DQ Output	DQ Tri-state	DQS Output	DQS Tri-state	Addr/Cmd	Clock
DDR2/DDR3	IDDRX2DQ	ODDRX2DQ	TSHX2DQ	ODDRX2DQS	TSHX2DQS	OSHX2	ODDRX2
(×2 Gearing)	IDDRX4DQ	ODDRX4DQ	TSHX4DQ	ODDRX4DQS	TSHX4DQS	OSHX4	ODDRX4

8.9.2. IDDRX2DQ

This primitive is used to implement the DDR2 memory input interface at higher speeds and DDR3 memory interface.

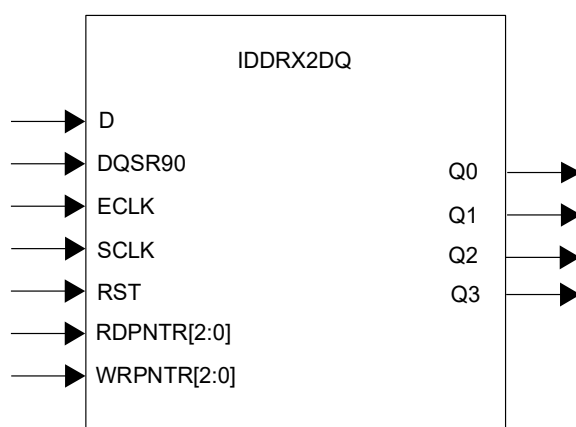


Figure 8.15. IDDRX2DQ Primitive

Table 8.20. IDDRX2DQ Port List

Port	I/O	Description
D	I	DDR data input
DQSR90	I	DQS clock input
ECLK	I	Fast edge clock
SCLK	I	Primary clock input (divide-by-2 of ECLK)
RST	I	Reset to DDR registers
RDPNTR[2:0]	I	Read pointer from the DQSBUF module used to transfer data to ECLK
WRPNTR[2:0]	I	Write pointer from the DQSBUF module used to transfer data to ECLK
Q[3:0]	O	Parallel data output. Q0, Q2 are the data at the positive edges of the input ECLK. Q1 and Q3 are data at negative edge of input ECLK.

8.9.3. IDDRX4DQ

This primitive is used to implement the DDR3 memory input interface at higher speeds.

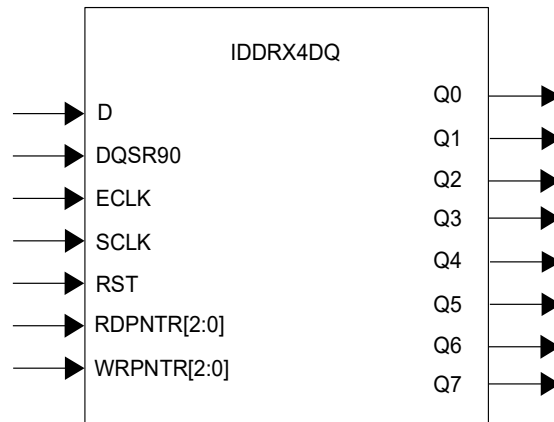


Figure 8.16. IDDRX4DQ Primitive

Table 8.21. IDDRX4DQ Port List

Port	I/O	Description
D	I	DDR data input
DQSR90	I	DQS clock input
ECLK	I	Fast edge clock
SCLK	I	Primary clock input (divide-by-4 of ECLK)
RST	I	Reset to DDR registers
RDPNTR[2:0]	I	Read pointer from the DQSBUF module used to transfer data to ECLK
WRPNTR[2:0]	I	Write pointer from the DQSBUF module used to transfer data to ECLK
Q[7:0]	O	Parallel data output. Q0, Q2, Q4, Q6 are the data at the positive edges of the input ECLK. Q1, Q3, Q5, Q7 are data at negative edge of input ECLK.

8.9.4. ODDRX2DQ

This primitive is used to generate DQ data output for DDR2 with $\times 2$ gearing and for DDR3 memory interface.

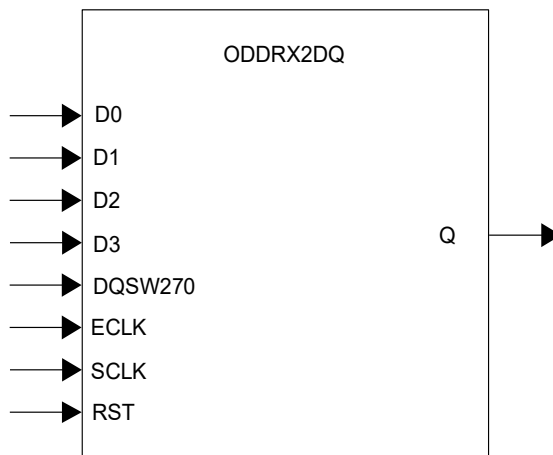


Figure 8.17. ODDRX2DQ

Table 8.22. ODDRX2DQ Port List

Port	I/O	Description
D0, D1, D2, D3	I	Data input to the ODDR (D0 is output first, D3 last)
DQSW270	I	Clock that is 90 degrees ahead of clock used to generate the DQS output
ECLK	I	Fast edge clock
SCLK	I	Primary clock input (divide-by-2 of ECLK)
RST	I	Reset to DDR registers
Q	O	DDR data output on both edges of DQSW270

8.9.5. ODDR4DQ

This primitive is used to generate DQ data output for DDR3 memory interface using ×4 gearing.

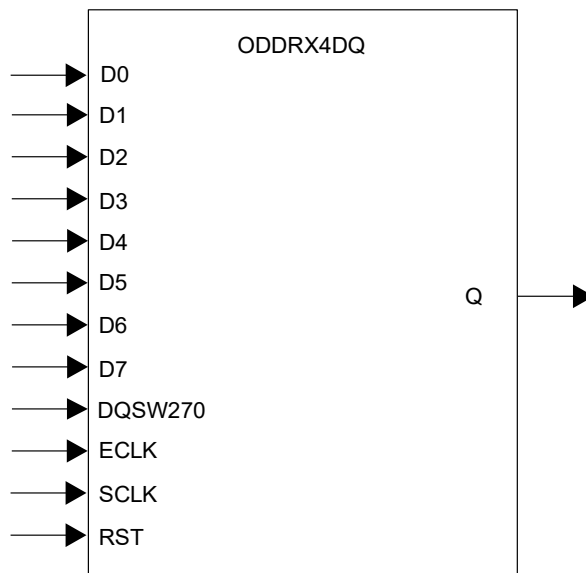


Figure 8.18. ODDR4DQ Primitive

Table 8.23. ODDR4DQ Port List

Port	I/O	Description
D0, D1, D2, D3,	I	Data input to the ODDR (D0 is output first, D7 last)
D4, D5, D6, D7	I	Clock that is 90 degrees ahead of DQSW used to generate DQ. DQSW includes write leveling phase shift from ECLK
DQSW270	I	Fast edge clock
ECLK	I	Primary clock input (divide-by-4 of ECLK)
SCLK	I	Reset to DDR registers
RST	O	DDR data output on both edges of DQSW270

8.10. Memory Output DDR Primitives for DQS Output

The following are the primitives used for DQS output.

8.10.1. ODDR2DQS

This primitive is used to generate DQS clock output for DDR2 and DDR3 memory.

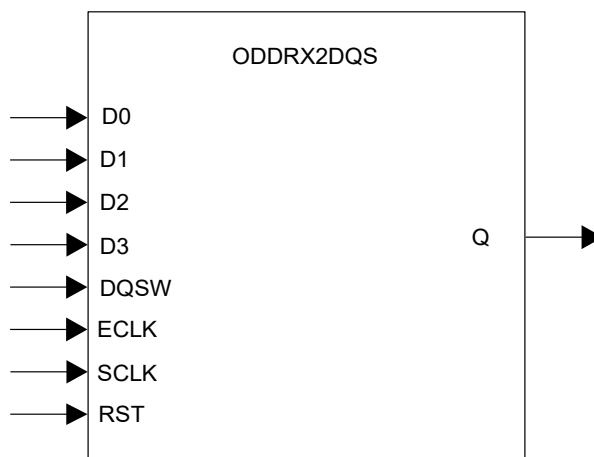


Figure 8.19. ODDR2DQS Primitive

Table 8.24. ODDR2DQS Port List

Port	I/O	Description
D0, D1, D2, D3	I	Data input to the ODDR (D0 is output first, D3 last)
DQSW	I	DQSW includes write leveling phase shift from ECLK
ECLK	I	Fast edge clock
SCLK	I	Primary clock input (divide-by-2 of ECLK)
RST	I	Reset to DDR registers
Q	O	DDR data output on both edges of DQSW

8.10.2. ODDR4DQS

This primitive is used to generate DQS clock output for DDR3 memory using ×4 gearing.

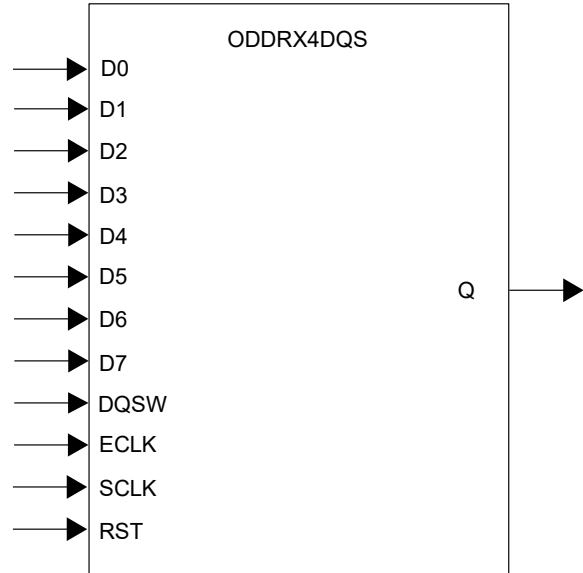


Figure 8.20. ODDR4DQS Primitive

Table 8.25. ODDR4DQS Port List

Port	I/O	Description
D0, D1, D2, D3, D4, D5, D6, D7	I	Data input to the ODDR (D0 is output first, D7 last)
DQSW	I	DQSW includes write leveling phase shift from ECLK
ECLK	I	Fast edge clock
SCLK	I	Primary clock input (divide-by-2 of ECLK)
RST	I	Reset to DDR registers
Q	O	DDR data output on both edges of DQSW

8.11. Memory Output DDR Primitives for Tristate Output Control

The following are the primitives used to implement tri-state control for the outputs to the DDR memory.

8.11.1. TSHX2DQ

This primitive is used to generate the tri-state control for DQ data output for DDR2 memory with $\times 2$ gearing and DDR3 memory.

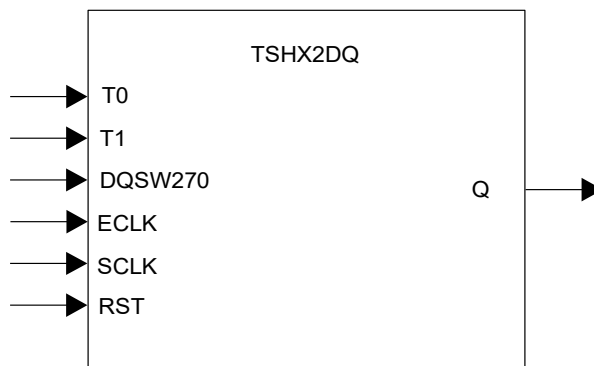


Figure 8.21. TSHX2DQ Primitive

Table 8.26. TSHX2DQ Port List

Port	I/O	Description
T0, T1	I	Tristate input (T0 is output first, followed by T1)
DQSW270	I	Clock that is 90 degrees ahead of the clock used to generate the DQS output
ECLK	I	ECLK input
SCLK	I	Primary clock input (divide-by-2 of ECLK)
RST	I	Reset input
Q	O	Tristate output

8.11.2. TSHX4DQ

This primitive is used to generate the tri-state control for DQ data output for DDR3 memory interface with ×4 gearing.

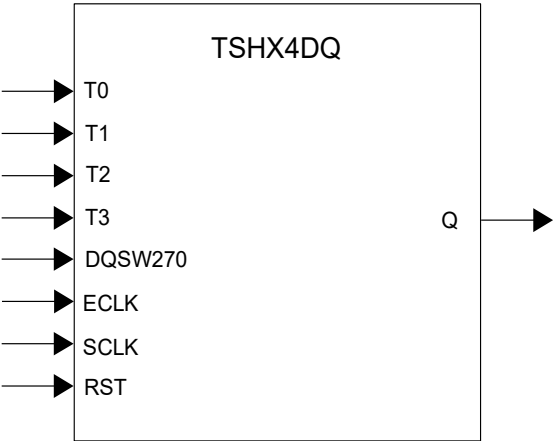


Figure 8.22. TSHX4DQ Primitive

Table 8.27. TSHX4DQ Port List

Port	I/O	Description
T0, T1, T2, T3	I	Tristate input (T0 is output first, followed by T1)
DQSW270	I	Clock that is 90 degrees ahead of the clock used to generate the DQS output
ECLK	I	ECLK input
SCLK	I	Primary clock input (divide-by-4 of ECLK)
RST	I	Reset input
Q	O	Tristate output

8.11.3. TSHX2DQS

This primitive is used to generate the tri-state control for DQS output.

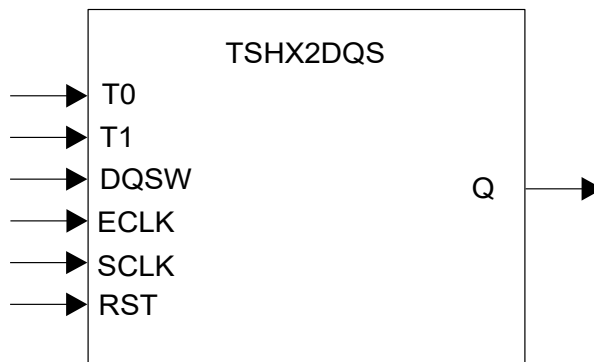


Figure 8.23. TSHX2DQS Primitive

Table 8.28. TSHX2DQS Port List

Port	I/O	Description
T0, T1	I	Tristate input (T0 is output first, followed by T1)
DQSW	I	DQSW includes write leveling phase shift from ECLK
ECLK	I	ECLK input (2× speed of SCLK)
SCLK	I	Primary clock input
RST	I	Reset input
Q	O	Tristate output

8.11.4. TSHX4DQS

This primitive is used to generate the tri-state control for DQS data output for DDR3 memory interface with $\times 4$ gearing.

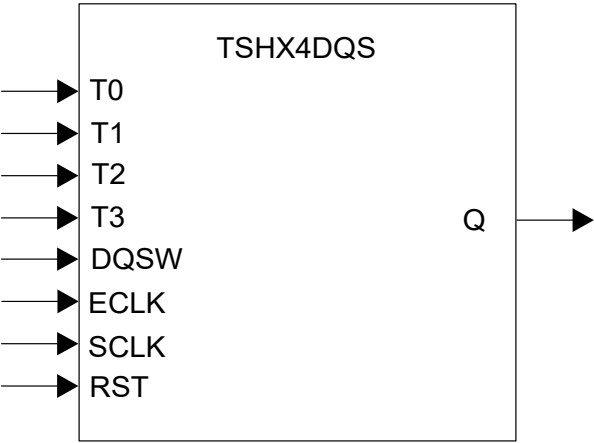


Figure 8.24. TSHX4DQS Primitive

Table 8.29. TSHX4DQS Port List

Port	I/O	Description
T0, T1, T2, T3	I	Tristate input (T0 is output first, followed by T3)
DQSW	I	DQSW includes write leveling phase shift from ECLK
ECLK	I	ECLK input (4 $\times$ speed of SCLK)
SCLK	I	Primary clock input
RST	I	Reset input
Q	O	Tristate output

8.12. Memory Output DDR Primitives for Address and Command

The following are the primitives used to implement the address and command outputs to the DDR memory.

8.12.1. OSHX2

This primitive is used to generate the address and command for DDR3 memory with $\times 2$ gearing and write leveling.

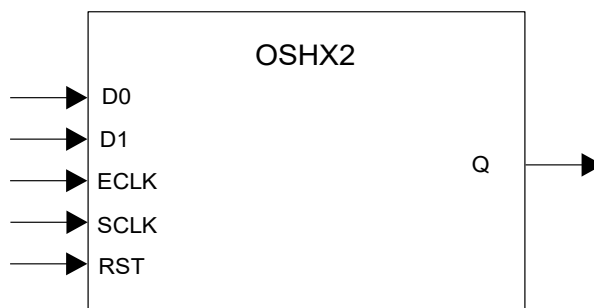


Figure 8.25. OSHX2 Primitive

Table 8.30. OSHX2 Port List

Port	I/O	Description
D0, D1	I	Data input (D0 is output first then D1)
ECLK	I	ECLK input (2 $\times$ speed of SCLK)
SCLK	I	SCLK input
RST	I	Reset input
Q	O	Address and command output

8.12.2. OSHX4

This primitive is used to generate the address and command for DDR3 memory with $\times 4$ gearing and write leveling.

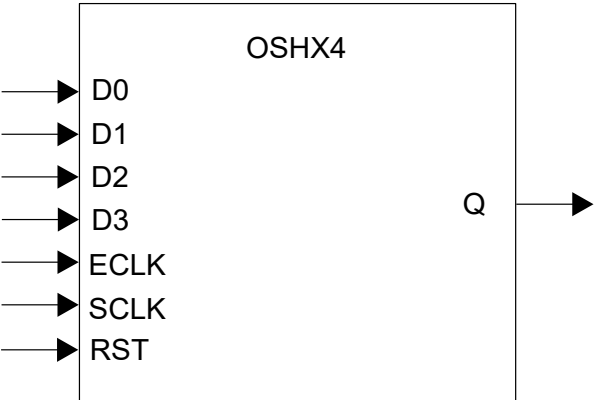


Figure 8.26. OSHX4 Primitive

Table 8.31. OSHX4 Port List

Port	I/O	Description
D0, D1, D2, D3	I	Data input (D0 is output first, D3 last)
ECLK	I	ECLK input (4 $\times$ speed of SCLK)
SCLK	I	Primary clock input
RST	I	Reset input
Q	O	Address and command output

8.13. LPDDR4 Output Delay Primitives

8.13.1. OUTDELAYA

The OUTDELAYA primitive is used to add static and dynamic delay to DOUT and TOUT for write training in LPDDR4.

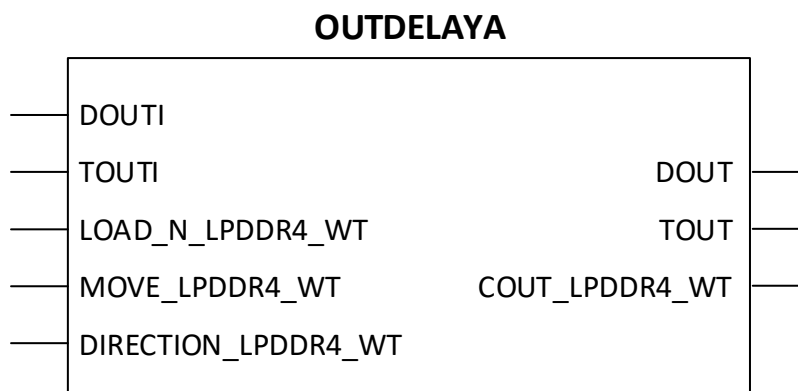


Figure 8.27. OUTDELAYA Primitive

Table 8.32. OUTDELAYA Parameter

Parameter	Possible Values	Default	Description
MARGIN_TEST_ENABLE	ENABLED, DISABLED	DISABLED	For LPDDR4 write training, margin test enable. 0: disable margin test 1: enable margin test
DEL_VALUE	0 to 127	0	For LPDDR4 write training, output fine delay fuse setting: 7b0000_0000: minimum delay 7b1111_1111: maximum delay

Table 8.33. OUTDELAYA Port List

Port	I/O	Description
DOUTI	I	The input for DOUT
TOUTI	I	The input for TOUT
LOAD_N_LPDDR4_WT	I	For LPDDR4 write training, asynchronous reset the output final delay code to factory default value.
MOVE_LPDDR4_WT	I	For LPDDR4 write training, Move pulse rising edge changes the code according to DIRECTION_LPDDR4_WT value.
DIRECTION_LPDDR4_WT	I	For LPDDR4 write training fine delay, 0 to increase the delay code, 1 to decrease the delay code.
DOUT	O	PIC data output, to ASICIO
TOUT	O	PIC tri-state output, to ASICIO
COUT_LPDDR4_WT	O	For LPDDR4 write training, write training margin test output flag to indicate the under-flow or over-flow.

9. Soft IP Modules

The following soft IP Modules are available for use with the Generic DDR interfaces described above. All of the soft IP Modules can be generated using IP Catalog. [Table 9.1](#) summarizes the list of soft IPs available and the ones that are optional versus the ones that are automatically generated with the interface in IP Catalog.

Table 9.1. List of Soft IPs Supported

Soft IP Name	Function	Required
RX_SYNC	Used to break up the DDRDLL to DLLDEL clock loop for Aligned Interfaces.	Yes
GDDR_SYNC	Needed to tolerate large skew between stop and reset input.	Yes
MEM_SYNC	Needed to avoid issues on DDR memory bus and update code in operation without interrupting interface operation.	Yes
7:1 LVDS Bit and Word Alignment (BW_ALIGN)	The soft IP is used to perform bit and word alignment using PLL dynamic phase shift interface and aligned input of IDDR71C.	Optional
MIPI_FILTER	Implements low pass filter on low speed MIPI data	Optional

[Table 9.2](#) summarized the soft IPs used in each interface.

Table 9.2. Soft IP Used in Each Interface

Interface	Soft IP
GDDR1_RX.SCLK.Centered	None
GDDR1_RX.SCLK.Aligned	GDDR71_TX.ECLK
GDDR2_RX.ECLK.Centered	GDDR_SYNC
GDDR2_RX.ECLK.Aligned	RX_SYNC
GDDR2_RX.MIPI	GDDR_SYNC, MIPI_FILTER
GDDR71_RX.ECLK	GDDR_SYNC, BW_ALIGN
GDDR1_TX.SCLK.Centered	None
GDDR1_TX.SCLK.Aligned	None
GDDR2_TX.ECLK.Centered	GDDR_SYNC
GDDR2_TX.ECLK.Aligned	GDDR_SYNC
GDDR71_TX.ECLK	GDDR_S

9.1. Detailed Description of Each Soft IP

9.1.1. GDDR_SYNC

This module is needed for startup all RX Centered and all TX interfaces with 2× gearing.

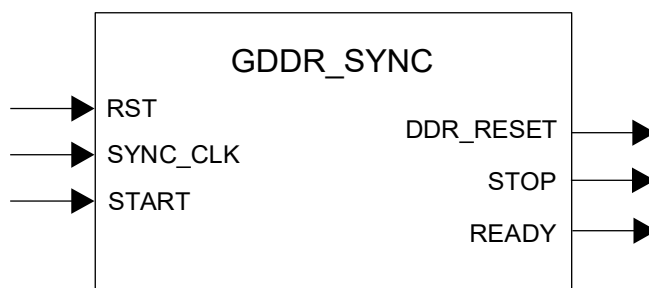


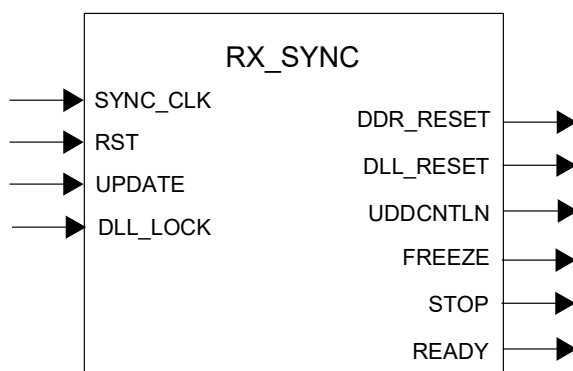
Figure 9.1. GDDR_SYNC Ports

Table 9.3. GDDR_SYNC Ports Description

Port	I/O	Description
SYNC_CLK	I	Startup clock. It can be a low speed continuously running clock, for example, an oscillator clock. It cannot be the RX_CLK or divided version.
RST	I	Active high reset to this sync circuit. When RST=1, STOP=0, DDR_RESET=1, READY=0
START	I	Start sync process. This is used to wait for PLL lock, then start sync process in 7:1 LVDS interface.
STOP	O	Connect to ECLKSYNC.STOP.
DDR_RESET	O	Reset to all IDDRX or ODDRX components and CLKDIV.
READY	O	Indicate that startup is finished and RX circuit is ready to operate.

9.1.2. RX_SYNC

This module is needed for startup RX-aligned interfaces with 2× gearing.


Figure 9.2. RX_SYNC Ports
Table 9.4. GDDR_SYNC Ports Description

Port	I/O	Description
SYNC_CLK	I	Startup clock. It can be a low speed continuously running clock, for example, an oscillator clock. It cannot be the RX_CLK or divided version
RST	I	Active high reset to this sync circuit. When RST=1, STOP=0, FREEZE=0, UDDCNTLN=1, DLL_RESET=1, DDR_RESET=1, READY=0.
DLL_LOCK	I	LOCK output from DDRDLL.
UPDATE	I	UPDATE can be used to re-start sync process. READY goes low and waits for the sync process to be completed before going high again. This can only be performed when no traffic is present.
STOP	O	Connect to ECLKSYNC.STOP.
FREEZE	O	Connect to DDRDLL.FREEZE.
UDDCNTLN	O	Connect to DDRDLL.UDDCNTLN.
DLL_RESET	O	Reset to DDRDLL.
DDR_RESET	O	Reset to all IDDRX components and CLKDIV.
READY	O	Indicate that startup is finished and RX circuit is ready to operate.

9.1.3. MEM_SYNC

This module is needed to startup external memory controller interfaces with 2× gearing.

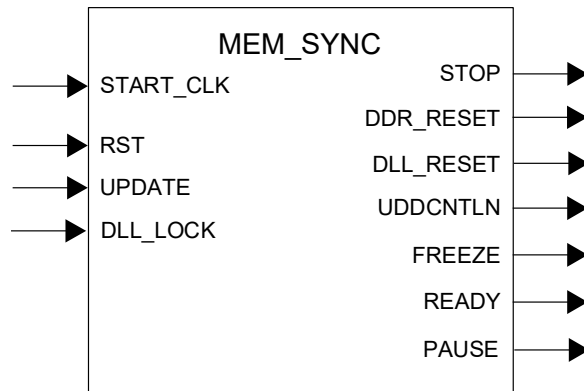


Figure 9.3. MEM_SYNC Ports

Table 9.5. MEM_SYNC Port Description

Port	I/O	Description
SYNC_CLK	I	Startup clock. It can be a low speed continuously running clock, for example, an oscillator clock. It cannot be the RX_CLK or divided version.
RST	I	Active high reset to this sync circuit. When RST=1, STOP=0, FREEZE=0, UDDCNTLN=1, DLL_REEST=1, DDR_RESET=1, READY=0, PAUSE =0.
DLL_LOCK	I	LOCK output from DDRDLL.
UPDATE	I	After ready goes high, you can use UPDATE to update code in DQSBUF, to perform training (change read_clk_sel), or write leveling (change dyndelay<>).
PAUSE	O	Connect to DQSBUF.PAUSE.
STOP	O	Connect to ECLKSYNC.STOP.
FREEZE	O	Connect to DDRDLL.FREEZE.
UDDCNTLN	O	Connect to DDRDLL.UDDCNTLN.
DLL_RESET	O	Reset to DDRDLL.
DDR_RESET	O	Reset to all IDDRX, ODDRX, OSHX components, DQSBUF, and CLKDIV
READY	O	Indicate that startup is finished and RX circuit is ready to operate.

9.1.4. BW_ALIGN

This module is used to perform 7:1 video RX bit and word alignment. This module is optional and can be enabled in IP Catalog.

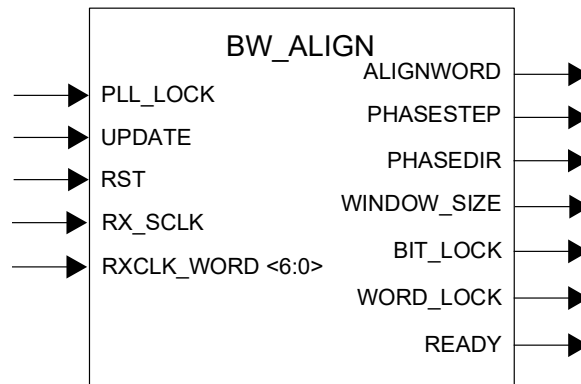


Figure 9.4. BW_ALIGN Ports

Table 9.6. BW_ALIGN Port Description

Port	I/O	Description
RX_SCLK	I	Divided RX clock from the 7:1 RX interface, produced by CLKDIV.
RST	I	Active high reset to this circuit. When RST=1, All outputs=0.
PLL_LOCK	I	Connect to PLL LOCK output. Start the alignment procedures after PLL lock goes high.
UPDATE	I	Start the procedure, or re-start if need to optimize again.
RXCLK_WORD<6:0>	I	Parallel data output from the 2nd IDDRX71 attached to RX CLK Input.
PHASESTEP	O	Rotate phase for PLL.
PHASEDIR	O	Phase rotation direction for PLL, fixed to forward (0) for this design.
ALIGNWORD	O	Connect to IDDRX71.ALIGNWORD, for word rotation.
WINDOW_SIZE	O	Final valid window size.
BIT_LOCK	O	Status output, bit lock is achieved.
WORD_LOCK	O	Status output, word lock is achieved.
READY	O	Indicate that alignment procedure is finished and RX circuit is ready to operate.

With Bit Alignment, the goal is to place Edge Clock (under PLL dynamic phase shift control) to the center of valid window for the clock word and data words. The PLL phase rotation goes through all 16 phases. The PLL high-speed output is used to sample RX input clock. Transitions are detected on the second IDDR71 output, which inputs the RX Clock and phases close to transition are identified. The IP chooses the phase most away from transition as the final phase to use.

The low speed clock has two transitions per 7-bit word. It is not the worst case in terms of inter-symbol interference. On the other hand, we do have 8 possible sample points per bit period. Minimum eye-opening of 3/8 UI is needed to achieve lock. Jitter tolerance is around 0.25 UI, about 300 ps at 756 Mb/sec.

After bit alignment is achieved, word alignment is needed, so video data (in 7-bit words) can be processed in core. The IP uses the ALIGNWD function of the IDDRX71 primitive for word alignment. Each pulse on ALIGNWD rotates the 7-bit bus by 2 bits. In maximum 7 ALIGNWD operations, the word loops through all seven possibilities. The goal is to get 7'b1100011 (7'h63) in the clock word. The clock word is the clock (4 bit 1 and 3'b 0) converted to parallel data, exactly as the video data traffic. For the 7:1 video, the RX input Clock serves as:

- Frequency reference to generate high-speed.
- Phase reference as source synchronized RX, since the clock is edge aligned with the data bits.
- Word alignment reference.

9.1.5. MIPI_FILTER

This module is needed to filter low-speed signals for MIPI RX. It filters out narrow pulses. It allows pulse width above 40 ns to pass.

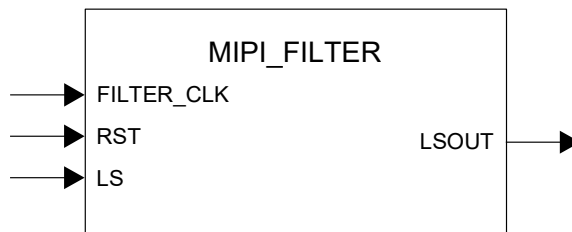


Figure 9.5. MIPI_FILTER Ports

Table 9.7. MIPI_FILTER Port Description

Port	I/O	Description
FILTER_CLK	I	Clock used to drive digital filter. Min frequency = 100 MHz. Recommendation is to use internal oscillator at 133 MHz.
LS	I	Low-speed signal from MIPI PHY.
RST	I	Active high reset. When RST=1, LSOUT=0.
LS_OUT	O	Filtered output signal.
cutoff	Parameter	Parameterize the circuit, default=4, pass signal above 4 cycles. $cutoff = \text{round}(20 \text{ ns/period}(\text{filter_clk}))$. Filter_clk = 100 MHz, cutoff = 4. Filter_clk = 133 MHz, cutoff = 6. Filter_clk = 175 MHz, cutoff = 7. Filter_clk = 200 MHz, cutoff = 8.

References

- [MachXO5-NX Family Data Sheet \(FPGA-DS-02102\)](#)
- [sysCLOCK PLL Design and User Guide for Nexus Platform \(FPGA-TN-02095\)](#)
- [sysI/O User Guide for Nexus Platform \(FPGA TN-02067\)](#)
- [MachXO5-NX web page](#)
- [Lattice Radiant](#) FPGA design software
- [Lattice Radiant Software User Guide](#)
- [Lattice Insights](#) for Lattice Semiconductor training courses and learning plans

Technical Support Assistance

Submit a technical support case through www.latticesemi.com/techsupport.

For frequently asked questions, refer to the Lattice Answer Database at www.latticesemi.com/en/Support/AnswerDatabase.

Revision History

Revision 1.1, October 2025

Section	Change Summary
All	Replaced general reference of <i>MachXO5-NX 15K/25K/35K/55K/65K/100K</i> with specific device identifier.
High-Speed I/O Interface Building Blocks	- Updated the caption of Figure 3.1 to include <i>LFMXO5-20TD</i>, <i>LFMXO5-20TDQ</i>, <i>LFMXO5-30TD</i>, <i>LFMXO5-30TDQ</i>, <i>LFMXO5-35T</i>, and <i>LFMXO5-65T</i> devices. - Updated the caption of Figure 3.2 to include <i>LFMXO5-55TDQ</i> device. - Added a figure note to Figure 3.1 and updated the figure note for Figure 3.2. - Updated I/O Banks section: - Updated section description to include <i>LFMXO5-20TD</i>, <i>LFMXO5-20TDQ</i>, <i>LFMXO5-30TD</i> and <i>LFMXO5-30TDQ</i> devices. - Updated table captions of Table 3.1, Table 3.2, and Table 3.3.

Revision 1.0, July 2025

Section	Change Summary
Abbreviations in This Document	Replaced <i>Acronyms</i> with <i>Abbreviations</i> .
High-Speed I/O Interface Building Blocks	- Added the following note in Figure 3.2. MachXO5-NX 55K/100K Device Clocking Diagram: <i>This clocking diagram applies to MachXO5-NX 55K/100K. Other MachXO5-NX devices share a similar clocking diagram. However, the number of I/O banks and PLLs may vary. For detailed specifications, refer to the MachXO5-NX Family Data Sheet (FPGA-DS-02102).</i> - Added the following note in <i>SGMII Clock Data Recovery (CDR)</i>: <i>The SGMII interface using LVDS I/O has limitations when operating across the full specified temperature range. Lattice recommends using alternative interfaces, such as SERDES or RGMII, for designs requiring a Gigabit Ethernet. Refer to the Knowledge Database article for details. Contact your local Lattice sales representative for more information.</i> - Updated section <i>I/O Banks</i>: - Updated description to include <i>MachXO5-NX 35K</i> and <i>65K</i> devices. - Added Table 3.3. <i>MachXO5-NX 35K and 65K Device I/O Banks</i>.
References	Added this section.

Revision 0.84, March 2024

Section	Change Summary
Disclaimers	Updated disclaimers.
High-Speed I/O Interface Building Blocks	- Updated description in <i>I/O Banks</i> section. - Updated Table 3.1. MachXO5-NX 25K Device I/O Banks title. - Added Table 3.2. MachXO5-NX 55K/100K Device I/O Banks.
High-Speed DDR Interface Details	- Removed reference to <i>Timing Analysis for High-Speed DDR Interfaces</i> section. - Remove interface requirement referencing <i>Timing Analysis for High-Speed DDR Interfaces</i> section in <i>GDDR1_RX.SCLK.Centered</i>, <i>GDDR1_RX.SCLK.Aligned</i>, <i>GDDR2_RX.ECLK.Centered</i>, <i>GDDR2_RX.ECLK.Aligned</i>, <i>GDDR4_RX.ECLK.Centered</i>, <i>GDDR4_RX.ECLK.Aligned</i>, <i>GDDR5_RX.ECLK.Centered</i>, <i>GDDR5_RX.ECLK.Aligned</i>, <i>GDDR2_TX.ECLK.Centered</i>, <i>GDDR2_TX.ECLK.Aligned</i>, <i>GDDR4_TX.ECLK.Centered</i>, <i>GDDR4_TX.ECLK.Aligned</i>, <i>GDDR5_TX.ECLK.Centered</i>, and <i>GDDR5_TX.ECLK.Aligned</i> sections. - Removed <i>Timing Analysis for High-Speed DDR Interfaces</i> section.

Revision 0.83, May 2023

Section	Change Summary
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High-Speed DDR Interface Details	- In the GDDR1_RX.SCLK.Aligned section, updated the first Interface Requirement to The clock input must use an even-numbered PCLK input so that it can be routed directly to the DLLDELD input. - In the GDDR2_RX.ECLK.Aligned section, updated the first Interface Requirement to The clock input must use an even-numbered PCLK input so that it can be routed directly to the DLLDEL module. - In the GDDR4_RX.ECLK.Aligned section, updated the first Interface Requirement to The clock input must use an even-numbered PCLK input so that it can be routed directly to the DLLDEL module. - In the GDDR5_RX.ECLK.Aligned section, updated the first Interface Requirement to The clock input must use an even-numbered PCLK input so that it can be routed directly to the DLLDEL module.
I/O Logic (DDR) User Primitives and Attributes	Updated the description of the first paragraph in the DLL Delay (DLLDEL) section.

Revision 0.82, April 2023

Section	Change Summary
Introduction	Removed support for LPDDR2 and LPDDR3, and added support for LPDDR4.
High-Speed I/O Interface Building Blocks	- Changed figure title from Figure 3.1. MachXO5-NX Device Clocking Diagram to Figure 3.1. LFMXO5-15D/20TD/20TDQ/25/30TD/30TDQ/35T/65T Clocking Diagram. - Added Figure 3.2. LFMXO5-55T/55TD/55TDQ/100T Clocking Diagram.
High-Speed DDR Interface Details	- Revised the maximum speed of interface from 250MHz to 150MHz in the GDDR1_RX.SCLK.Centered section. - Revised the maximum speed of interface from 250MHz to 150MHz in the GDDR1_RX.SCLK.Aligned section. - Removed the maximum speed of interface details from the GDDR2_RX.ECLK.Centered section. - Removed the maximum speed of interface details from the GDDR2_RX.ECLK.Aligned section. - Removed the maximum speed of interface details from the GDDR4_RX.ECLK.Centered section. - Removed the maximum speed of interface details from the GDDR4_RX.ECLK.Aligned section. - Removed the maximum speed of interface details from the GDDR5_RX.ECLK.Centered section. - Removed the maximum speed of interface details from the GDDR5_RX.ECLK.Aligned section. - Revised lower speed interfaces from < 250 to < 150 in the Frequency Constraints section. - Revised lower speed interfaces from < 250 to < 150 in the DDR Input Setup and Hold Time Constraints section.
MachXO5-NX Memory Interfaces	- Removed support for LPDDR2 and LPDDR3, and added support for LPDDR4. - Revised Figure 6.2. Typical LPDDR4 Memory Interface. - Revised Table 6.1. DDR Memory Configurations Support. - Revised Figure 6.12. LPDDR4 Output for CA Generation. - Revised Figure 6.13. LPDDR4 Output for CSN, CKE, and CLOCK Generation.
Using IP Catalog to Build and Plan High-Speed DDR Interfaces	- Removed support for LPDDR2 and LPDDR3, and added support for LPDDR4 in the Configuring DDR Memory Interfaces section. - Revised Table 7.5. DDR_MEM General Tab Parameters. - Revised Table 7.6. DDR_MEM Clock/Address/Command Parameters.
I/O Logic (DDR) User Primitives and Attributes	- Revised Table 8.1. Software Primitives to add the LPDDR4 Output Delay type. - Added the LPDDR4 Output Delay Primitives section.
Technical Support Assistance	Added reference link to the Lattice Answer Database.

Revision 0.81, October 2022

Section	Change Summary
High-Speed DDR Interface Details	Revised the ECLKDIV module's quantity of each Bank on the bottom side of the device from '2' to '4' in the Transmit Interface Guidelines section.

Revision 0.80, March 2022

Section	Change Summary
All	Preliminary release.



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